

2 0 1 4
INTERNATIONAL CONFERENCE ON
SOLID STATE
DEVICES AND MATERIALS

September 8-11, 2014

Tsukuba International Congress Center
(EPOCHAL TSUKUBA)

2014 International Conference on
Solid State Devices and Materials (SSDM 2014)

SECRETARIAT

c/o Inter Group Corp.
Kyodo Tsushin Kaikan 4F,
2-2-5 Toranomom, Minato-ku,
Tokyo 105-0001, Japan
Phone : +81-3-5549-6909
F a x : +81-3-5549-3201
E-mail : ssdm_secretariat@intergroup.co.jp
U R L : <http://www.ssdm.jp>



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CONTENTS

PREFACE	3
SUPPORTING COMPANIES, FOUNDATIONS AND ORGANIZATIONS	4
COOPERATIVE ORGANIZATIONS	5
COMMITTEE MEMBERS	6
GENERAL INFORMATION	9
PLENARY SESSIONS	11
TECHNICAL PROGRAM	
SEPTEMBER 9 (Tue.)	12
SEPTEMBER 10 (Wed.)	18
SEPTEMBER 11 (Thu.)	30
RUMP SESSIONS	38
SHORT COURSES	39
INSTRUCTION FOR SPEAKERS	40
EXHIBITION	41
AUTHOR INDEX	42
FLOOR GUIDE	52
LUNCH MAP	54
ADVERTISEMENT	55
SSDM2015 ANNOUNCEMENT	83
PROGRAM TIME TABLE	84

PREFACE

On behalf of the organizing committee, it is my great pleasure and honor to welcome you to Tsukuba, Japan, for the 2014 International Conference on Solid State Devices and Materials (SSDM2014), September 8-11, 2014. The purpose of SSDM is to contribute to the promotion of science and industry related to solid-state electronics. The conference has been providing a forum for interaction of related fields—ranging from physics and material science to circuits, systems, and process technologies—to discuss on the very latest research. Through SSDM, information has been delivered from Japan and Asia to the rest of the world. In fact, we have witnessed many globally recognized scientific findings and technical achievements that have led to real innovation. We expect that this year will be no exception.

This year, 651 high quality abstracts were submitted to SSDM2014 from 24 countries. Great efforts by the technical program committee in selecting the abstracts have resulted in an excellent technical program consisting of 2 plenary talks, 58 invited papers, 260 contributed oral papers, 183 posters, and 35 late news papers. We hope all of the papers presented at SSDM2014 address in depth nearly all the key issues in the field and provide good stimulation and new perspectives to all participants.

Historically, from SSDM1999, the program committee has been divided into sub-committees, because the fields relating to SSDM had been diversified from the orthodox semiconductor device technologies to material science, process, manufacturing, circuit, and new technologies such as nano, organic, and bio, *etc.* The number of submitted papers and participants has been increased.

To our regret, the number of submitted papers drastically decreased compared to the previous several years; 796 in 2013, 858 in 2012, and 966 in 2011. The reason of this decrease has not been clarified at present time. One of the reasons may be originated from the change of so-called semiconductor business especially in Japan, and this has also caused the change of R&D style. We also fear the reduction of the participants from industries. The technological innovation requires the intimate contact and deep discussion among industry, academia, and government organizations. SSDM has been recognized that one of the missions is to give these opportunities of intimate contact and deep discussion. SSDM will fulfill this mission in the future.

The two plenary speakers are Dr. Kazuo Kyuma, Council for Science and Technology Policy, Cabinet Office, Government of Japan; Professor Peide D. Ye, Purdue University, USA. Dr. Kyuma, who was the organizing committee chair of SSDM 2012, will discuss strategy for science and technology innovations with emphasis of expectations to solid state devices and materials. Prof. Ye will discuss the challenges of new materials and devices beyond Si CMOS including their recent works.

We wish to express our sincere appreciation to all the contributors who submitted technical papers and all the committee members for their great patience to prepare the way for SSDM2014. We also express our sincere gratitude for the financial support provided by MEXT-JSPS and the supporting corporations and foundations.

Your participation at SSDM2014 is greatly appreciated. The utmost consideration has been taken to ensure that throughout the entire conference you will enjoy discussions and create fresh ideas.

September 2014



Kazuya Masu
General Chair, Organizing Committee, SSDM2014
Professor, Tokyo Institute of Technology

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Sponsoring Companies and Foundations:

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as of August 12, 2014

Subsidizing Foundations and Organizations:

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International Exchange Program of National Institute of Information and

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The Murata Science Foundation

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Nippon Sheet Glass Foundation for Materials Science and Engineering

as of August 12, 2014

COOPERATIVE ORGANIZATIONS

Technical Co-Sponsor:

IEEE Electron Devices Society (EDS)

Cooperative Organizations:

Association for Promotion of Electrical, Electronic and Information Engineering

IEEE EDS Japan Chapter

IEEE EDS Kansai Chapter

IEEE EDS Taipei Chapter

IEEE Taipei Section Sensors Council

Japan Institute of Electronics Packaging

Semiconductor Equipment and Materials International

Semiconductor Equipment Association of Japan

The Chemical Society of Japan

The Electrochemical Society Japan Section

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The Institute of Electrical Engineers of Japan

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The Institute of Image Information and Television Engineers

The Japan Society for Analytical Chemistry

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(in alphabetical order)

as of August 13, 2014

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[7] Photonic Devices and Related Technologies

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[9] Physics and Applications of Novel Functional Devices and Materials

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K. Matsuda (Kyoto Univ.)
T. Nakaoka (Sophia Univ.)
T. Ota (NTT Basic Res. Labs.)
K. Terabe (NIMS)

[10] Organic Materials Science, Device Physics, and Applications

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P. Ho (National Univ. of Singapore)

Members:
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H. Kajii (Osaka Univ.)
M. Kitamura (Kobe Univ.)
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H. Murata (JAIST)
H. Okada (Univ. of Toyama)
K. Shinbo (Niigata Univ.)
K. Tajima (RIKEN)
J. Takeya (Univ. of Tokyo)
S. Tokito (Yamagata Univ.)

[11] Sensors and Materials for Biology, Chemistry and Medicine

Chair: J. Ohta (Nara Inst. of Sci. & Tech.)
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C.-H. Liu (National Tsing Hua Univ.)
S. Machida (Hitachi, Ltd.)
M. Sasaki (Toyota Technological Inst.)
T. Tanaka (Tohoku Univ.)
H. Tanaka (Panasonic Corp.)
R. Tero (ToyoHashi Univ. of Tech.)

[12] Spintronics Materials and Devices

Chair: H. Munekata (Tokyo Tech)
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T. Nagahama (Hokkaido Univ.)
J. Nitta (Tohoku Univ.)
J. Okabayashi (Univ. of Tokyo)
Y. Saito (Toshiba Corp.)
H. Shimizu (Tokyo Univ. of Agri & Tech.)

[13] Applications of Nanotubes, Nanowires, and Graphene

Chair: S. Hara (Hokkaido Univ.)
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P. W. Chiu (National Tsing Hua Univ.)

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T. Takenobu (Waseda Univ.)
G. Zhang (NTT Corp.)
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[14] Power Devices and Materials

Chair: M. Kato (Nagoya Inst. of Tech.)
Vice-chairs: H. Umezawa (AIST)
C. -F. Huang (National Tsing Hua Univ.)

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D. Hisamoto (Hitachi, Ltd.)
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T. Makino (AIST)
S. Matsumoto (Kyushu Inst. of Tech.)
K. Nishiwaki (Toyota Motor Corp.)
Y. Tanaka (AIST)
T. Uesugi (Toyota Central R&D Labs. Inc.)

[15] Photovoltaic Materials and Devices

Chair: M. Isomura (Tokai Univ.)
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T. Taima (Kanazawa Univ.)
S. Yata (Panasonic Corp.)
M. Zeman (TU Delft)

GENERAL INFORMATION

DATE

Short Courses: **September 8, 2014 (in English)**

Technical Sessions: **September 9-11, 2014**

CONFERENCE VENUE

Tsukuba International Congress Center (EPOCHAL TSUKUBA)

2-20-3 Takezono, Tsukuba, Ibaraki 305-0032, Japan

Phone: +81-29-861-0001, Fax: +81-29-861-1209

<http://www.epochal.or.jp/>

SSDM2014 will be held at Tsukuba International Congress Center (EPOCHAL TSUKUBA). The access map is available in the conference website.

SHORT COURSES

Short Course lectures are scheduled on September 8, 13:00-17:30. Two Short Course lectures will be held each at Convention Hall 200 and Convention Hall 300.

These two courses are designed for beginners such as young researchers, young engineers, and students.

A) Trends for Future Power Devices

B) Functional Devices in Integrated Systems

*Registrants for Short Course are able to attend both courses freely. One printed copy of the text book for the primary course that you chose is included in the registration fee. A printed copy of the text book for the other course can be purchased, but numbers are limited. Details can be found on page 39.

TECHNICAL SESSIONS

Plenary Sessions:

Plenary Sessions are scheduled on September 9, 10:30 -12:00 at Main Convention Hall.

Non-Technical Plenary Talk:

"Strategy for Science and Technology Innovations- Expectations for Solid State Devices and Materials"
by Kazuo Kyuma (Council for Science and Technology Policy, Cabinet Office, Japan)

Technical Plenary Talk:

"New Channel Materials and Devices Beyond Si CMOS"
by Peide D. Ye (Purdue University, USA)

Details can be found on page 11.

Oral and Poster Presentations:

Oral presentations will be held in the rooms located on 1st, 2nd, 3rd and 4th floors of Tsukuba International Congress Center from September 9 to 11. Poster presentations will be held on September 10, 14:00-16:00 at Multi-Purpose Hall and Conference Room 102.

Rump Sessions:

Rump Sessions are scheduled on September 10, 18:30-20:00 at Room 201(A+B) and 202(A+B). Details can be found on page 38.

OTHER EVENTS

Welcome Reception:

Welcome Reception will be held on September 8, 18:30-20:00 at ESPOIR (1st floor).

Banquet:

Conference Banquet will be held on September 9, 18:30-20:30 at SUBARU Room (1st floor) of OKURA FRONTIER HOTEL TSUKUBA ANNEX. The banquet fee is NOT included in the registration fee. Participants who wish to attend the banquet are requested to order the banquet ticket beforehand.

Award Ceremony:

Award Ceremony for SSDM Award /Paper Award will be held in Opening Session starting 10:00 on September 9 at Main Convention Hall. Young Researcher Award Ceremony will be held in the Banquet starting 18:30 on September 9 at SUBARU Room (1st floor) of OKURA FRONTIER HOTEL TSUKUBA ANNEX.

REGISTRATION

The on-site registration desk will be open September 8 to 11 at the Entrance Hall (1st floor).

Open hours are as follows:

September 8th 16:00 – 19:00

September 9th 09:00 – 17:30

September 10th 08:30 – 17:30

September 11th 08:30 – 14:00

SPECIAL ISSUE of JJAP

The Special Issue of Japanese Journal of Applied Physics will be published in April, 2015.

The online publication will start from February, 2015 in advance of the paper based publication.

INSURANCE

The organizer cannot accept responsibility for accidents that may occur during a delegate's stay. Delegates are therefore encouraged to obtain travel insurances (for medical, personal accident, and luggage) in their home countries prior to departure.

INTERNET ACCESS

Complementary Internet Access is available in public space on each floor and in every conference room.

Some internet services may be restricted due to the internet system restriction of the conference site.

ID and password to connect internet on free Wi-Fi;

Conference rooms: SSID: SSDM2014 / Password (case sensitive): SSDM_TSUKUBA

Public space: SSID: public / Password (case sensitive): will be provided on-site

Non-Technical Plenary Talk

10:30-11:15

"Strategy for Science and Technology Innovations - Expectations for Solid State Devices and Materials"**Kazuo Kyuma**

Council for Science and Technology Policy, Cabinet Office, Japan

Technical Plenary Talk

11:15-12:00

"New Channel Materials and Devices Beyond Si CMOS"**Peide D. Ye**

Purdue University, USA

Opening & Plenary Sessions (Main Convention Hall)

Opening Session

Chair: Y. Miyamoto, Tokyo Tech

10:00

Welcome Address

K. Masu, Tokyo Tech

10:15

SSDM Award / Paper Award Ceremony

Non-Technical Plenary Session

Chair: S. Takagi, Univ. of Tokyo

10:30 PL-1

“Strategy for Science and Technology Innovations - Expectations for Solid State Devices and Materials”

K. Kyuma / Council for Science and Technology Policy, Cabinet Office, Japan

Technical Plenary Session

Chair: S. Takagi, Univ. of Tokyo

11:15 PL-2

“New Channel Materials and Devices Beyond Si CMOS”

P. D. Ye / Purdue Univ., USA

Lunch

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
A-1: ReRAM(I) (13:30-15:00) Chairs: K. Kinoshita (Tottori Univ.) Y. Sasago (Hitachi)	B-1: Group-IV Optical Devices (13:30-15:00) Chairs: Y. Ishikawa (Univ. of Tokyo) N. Iizuka (Toshiba)		D-1: Nano Devices for Chemical & Biosensing (13:30-15:15) Chairs: T. Sakata (Univ. of Tokyo) T. Tanaka (Tohoku Univ.)	E-1: GaN Devices & Characterization (13:30-15:15) Chairs: T. Suzuki (JAIST) T. Hashizume (Hokkaido Univ.)	F-1: Advanced Process and Reliability (13:30-15:20) Chairs: T. Tsunomura (Tokyo Electron) L. Grenouillet (CEA-LETI)	G-1: 3D/TSV (13:30-15:15) Chairs: M. Kodera (Toshiba) K.-N. Chen (NCTU)
13:30 A-1-1 (Invited) Scaling of Resistive Switching Devices <i>D. Ielmini, Politecnico di Milano and IU.NET (Italy)</i>	13:30 B-1-1 (Invited) Germanium Tin Light Emitters on Silicon <i>E. Kasper and M. Oehme, Univ. of Stuttgart (Germany)</i>		13:30 D-1-1 (Invited) Silicon and reduced graphene oxide device concepts for electronically interfacing individual cells in culture <i>S. Ingebrand¹, X.-T. Vu^{1,2}, L. Delle¹, R. L. F. Hempel¹, A. Müller¹, J. K.-Y. Law¹ and V. Pachauri¹,¹Univ. of Applied Science Kaiserslautern, ²RWTH Aachen Univ. (Germany)</i>	13:30 E-1-1 (Invited) Physical effects limiting performance and reliability of GaN High Electron Mobility Transistors <i>E. Zanoni¹, G. Meneghesso¹, M. Meneghini¹, D. Bisi¹, A. Chini¹, C. De Santi¹, F. Rampazzo¹, I. Rossetto¹, A. Stocco¹ and G. Verzellesi²,¹Univ. di Padova, ²Dipartimento di Ingegneria "Enzo Ferrari" and ³Dipartimento di Scienze e Metodi dell'Ingegneria, Università di Modena e Reggio Emilia (Italy)</i>	13:30 F-1-1 (Invited) Heated Ion Implantation Technology for High Performance SOI FinFETs <i>W. Mizubayashi, H. Onoda, Y. Nakashima, Y. Ishikawa, T. Matsukawa, K. Endo, Y.X. Liu, S. O'uchi, J. Tsukada, H. Yamauchi, S. Migita, Y. Morita, H. Ota and M. Masahara, AIST (Japan)</i>	13:30 G-1-1 (Invited) Technology and Application Requirements of 2.5D/3D Field Programmable System-in-Package (SiP) <i>A. Rahman, Altera Corp. (USA)</i>
14:00 A-1-2 Non-negligible Metal Ions Diffusion in Amorphous Oxygen-Deficient Metal-Oxide Based Resistive Switches: A First Principle Study <i>B. Xiao and S. Watanabe, Univ. of Tokyo (Japan)</i>	14:00 B-1-2 Impact of Post-Growth Annealing for Thin-Film Ge Photodiodes on Si <i>S. Nagatomo¹, Y. Kawamata¹, Y. Izawa², S. Hoshino³ and Y. Ishikawa¹,¹Univ. of Tokyo, ²Tokyo Electron Miyagi Ltd. and ³Tokyo Electron Ltd. (Japan)</i>		14:00 D-1-2 High Density Horizontal-aligned Carbon Nanotube Thin Film with Oxygen Plasma Treatment as pH Sensing Membrane of Extended-Gate Field-Effect Transistor <i>K.Y. Wang, W.L. Tsai, C.H. Chou, Y.R. Li, C.Y. Liao and H.C. Cheng, NCTU (Taiwan)</i>	14:00 E-1-2 Combined PEALD Gate-Dielectric and In-Situ SiN Cap-Layer for Reduced V_{th} Shift and R_{ps-on} Dispersion of AlGaIn/GaN HEMTs on 200 mm Si Wafer <i>N. Ronchi¹, B. De Jaeger¹, M. Van Hove¹, R. Roelofs², T.L. Wu^{1,3}, J. Hu^{1,3}, X. Kang¹ and S. Decoutere¹,¹imec, ²ASM and ³KU Leuven (Belgium)</i>	14:00 F-1-2 Operations of CMOS Inverter and Ring Oscillator Composed of Ultra-Thin Body Poly-Ge p- and n-MISFETs for Stacked Channel 3D-IC <i>Y. Kamata¹, M. Koike¹, E. Kurosawa¹, M. Kurosawa², H. Ota¹, O. Nakatsuka³, S. Zaima² and T. Tezuka¹,¹Green Nanoelectronics Center (GNC), AIST and ²Nagoya Univ. (Japan)</i>	14:00 G-1-2 Improvement of Motional Resistance through Concave TSV Design and Modification for Static Capacitance of TSV-Based Resonator <i>J.Y. Shih¹, Y.C. Chen¹, C.H. Chiu², C.L. Lo² and K.N. Chen¹,¹NCTU and ²TXC Corp. (Taiwan)</i>

Lunch

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
<p>H-1: 2D Materials (1) (13:30-15:15) Chairs: T. Machida (Univ. of Tokyo) K. Matsuda (Kyoto Univ.)</p>	<p>J-1: Tunnel FET (13:30-15:20) Chairs: M. Masahara (AIST) M. Goto (Toshiba)</p>	<p>K-1: Flexible Electronics and Thin-film Devices (13:30-15:15) Chairs: T. Someya (Univ. of Tokyo) T. Hayashi (NTT)</p>	<p>M-1: Spin Dynamics (13:30-15:15) Chairs: H. Munekata (Tokyo Tech) H. Shimizu (Tokyo Univ. of Agri. & Tech.)</p>	<p>N-1: Processing and Growth (13:30-14:45) Chairs: M. Kato (Nagoya Inst. of Tech.) S. Harada (Nagoya Univ.)</p>	
<p>13:30 H-1-1 (Invited) Spin-valley physics in 2D crystals <i>Y. Iwasa, Univ. of Tokyo and RIKEN (Japan)</i></p>	<p>13:30 J-1-1 (Invited) Tunnel-FET Transistors for 13nm Gate-Length and Beyond <i>U.E. Avci, D.H. Morris and I.A. Young, Intel Corp. (USA)</i></p>	<p>13:30 K-1-1 (Invited) Polymeric Optical Devices with Printable and Flexible Electrode <i>Y. Ohmori, T. Yamamoto, K. Hiraoka and H. Kajii, Osaka Univ. (Japan)</i></p>	<p>13:30 M-1-1 (Invited) Engineering materials for all-optical helicity-dependent magnetic switching <i>M. Cinchetti¹, S. Alebrand², M. Gottwald², C.-H. Lambert^{2,3}, D. Steil¹, L. Pang¹, M. Hehn³, M.G. Malinowski^{2,3}, Y. Fainman¹, M. Aeschlimann¹, S. Mangin^{2,3} and E.E. Fullerton^{2,4}, ¹Univ. of Kaiserslautern, ²Center for Magnetic Recording Research, Univ. of California San Diego, ³Univ. de Lorraine, ⁴Dept. of Electrical and Computer Engineering, Univ. of California San Diego and ⁵Univ. Paris-Sud (Germany)</i></p>	<p>13:30 N-1-1 Nitrogen doping of 4H-SiC by excimer laser irradiation in liquid nitrogen <i>A. Ikeda, D. Marui, H. Ikenoue and T. Asano, Kyushu Univ. (Japan)</i></p>	
<p>14:00 H-1-2 In situ Tuning of Bandgap in Graphene Oxide Achieved by Solid State Ionics Device <i>T. Tsuchiya, K. Terabe and M. Aono, NIMS (Japan)</i></p>	<p>14:00 J-1-2 Novel Device Architecture Proposal of Source Junctionless Tunneling Field-Effect Transistor (SJL-TFET) <i>Y. Kondo¹, M. Goto¹, Y. Morita², T. Mori², S. Migita², A. Hokazono¹, H. Ota², M. Masahara² and S. Kawanaka¹, ¹Toshiba Corp. and ²AIST (Japan)</i></p>	<p>14:00 K-1-2 Flip-Flop Circuits using Fully Solution Processed Pseudo-CMOS Circuits <i>Y. Takeda^{1,2}, Y. Yoshimura^{1,2}, F.A. Ezarudin Binn Adib³, K. Fukuda^{1,2}, D. Kumaki^{1,2} and S. Tokito^{1,2}, ¹Graduate School of Science and Engineering, Yamagata Univ., ²ROEL, Yamagata Univ. and ³SATO HOLDINGS Corp., Ltd (Japan)</i></p>	<p>14:00 M-1-2 Enhancement of Excitation Efficiency of Photo-Excited Precession of Magnetization in Co/Pd Multilayers with Oblique-Angle Excitation <i>K. Nishibayashi, T. Matsuda, J. Saeki, K. Yamamoto and H. Munekata, Tokyo Tech (Japan)</i></p>	<p>13:45 N-1-2 An experiment on the alleviation of wafer-bending for CVD grown heavily Al-doped 4H-SiC epi-wafer by co-doping of N <i>S.Y. Ji¹, K. Kojima¹, Y. Ishida¹, S. Saito¹, H. Yamaguchi¹, S. Yoshida¹, H. Tsuchida² and H. Okumura¹, ¹AIST and ²CRIEPI (Japan)</i></p>	

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
A-1: ReRAM(I)	B-1: Group-IV Optical Devices		D-1: Nano Devices for Chemical & Biosensing	E-1: GaN Devices & Characterization	F-1: Advanced Process and Reliability	G-1: 3D/TSV
<p>14:20 A-1-3 Interface Engineering in Homogeneous Barrier Modulation RRAM for 3D Vertical Memory Applications W.L. Lai¹, C.T. Chou¹, C.W. Hsu¹, J.C. Liu¹, B. Hudec¹, C.H. Ho², W.Y. Jang², C.H. Lin² and T.H. Hou¹, ¹NCTU and ²Winbond Electronics Corp. (Taiwan)</p> <p>14:40 A-1-4 Novel Non-Precious Metal Electrode Material for ReRAM Device N. Fukuda, Y. Nishioka and K. Suu, ULVAC, Inc. (Japan)</p>	<p>14:15 B-1-3 Electroluminescence from Multiply-Stack of Doped Si Quantum Dots T. Yamada¹, K. Makihara¹, M. Ikeda² and S. Miyazaki¹, ¹Nagoya Univ. and ²Hiroshima Univ. (Japan)</p> <p>14:30 B-1-4 Observation of Stimulated Raman Scattering in Silica-Cladded Silicon Photonic Crystal Waveguides with Modified Holes Y.H. Hsiao, S. Iwamoto and Y. Arakawa, Univ. of Tokyo (Japan)</p> <p>14:45 B-1-5 A 0.94-THz Detector in 180-nm Standard CMOS Process Z. Liu, L. Liu, Z. Zhang, J. Liu and N. Wu, Chinese Academy of Sci. (China)</p>		<p>14:15 D-1-3 pH and pK Sensing Modification by Cosputtered TiSiON/SiO₂/Si Electrolyte-Insulator-Semiconductor Structure C.Y. Hsu¹, T.C. Chen¹, H. Yang², H.C. Wang², W.T. Lin¹, P.C. Juan², C.M. Yang^{1,3,4,5} and C.S. Lai^{1,4,5}, ¹Department of Electronic Eng. Chang Gung Univ., ²Department of Materials Eng and Center for Thin Film Technologies and Applications, Ming Chi Univ., ³Institute of Electro-Optical Eng, Chang Gung Univ., ⁴Healthy Aging Research Center, Chang Gung Univ and ⁵Center for Biomedical Eng, Chang Gung Univ (Taiwan)</p> <p>14:30 D-1-4 Self-Powered Solar Diode Gas Sensors A.E. Gad^{1,5,6}, M.W.G. Hoffmann^{1,6}, J.D. Prades³, F. Ramirez^{3,4}, R. Fiz², H. Shen^{1,6}, S. Mathur² and A. Waag^{1,6}, ¹Braunschweig Univ. of Technology, ²Univ. of Cologne, ³Univ. of Barcelona, ⁴Catalonia Institute for Energy Research, ⁵National Research Center and ⁶Laboratory of Nanometrology (Germany)</p> <p>14:45 D-1-5 Organic Field-Effect Transistor with Organic Acceptors for Ammonia Gas Sensor H.H. Lyu and H.M. Chen, NCTU (Taiwan)</p> <p>15:00 D-1-6 Ultra-High Selective Gas Sensors: novel approaches and future developments M.W.G. Hoffmann^{1,3,5}, J.D. Prades³, L. Mayrhofer¹, F. Ramirez^{3,4}, T.T. Jaervi², M. Moseler², A. Waag^{1,5} and H. Shen^{1,5}, ¹Braunschweig Univ. of Technology, ²Fraunhofer Institute for Mechanics of Materials, ³Univ. of Barcelona, ⁴Catalonia Institute for Energy Research and ⁵Laboratory of Nanometrology (Germany)</p>	<p>14:15 E-1-3 Novel Overlaid Field-Plate for Improvement of Drain I-V Characteristics of AlGaIn/GaN HEMTs S. Mase, T. Egawa and A. Wakejima, Nagoya Inst. of Tech. (Japan)</p> <p>14:30 E-1-4 Temperature Dependence of TiN-Anode GaN Schottky Barrier Diode Characteristics for Microwave Power Rectification R. Fujihara¹, Y. Itai¹, L. Li¹, Q. Liu¹, Y. Ohno² and J.P. Ao¹, ¹Univ. of Tokushima and ²e-Device Inc. (Japan)</p> <p>14:45 E-1-5 Low-frequency Noise of Intrinsic Gated Region in AlN/AlGaIn/GaN Metal-insulator-semiconductor Heterojunction Field-effect Transistors S.P. Le, T.Q. Nguyen, H. Shih, M. Kudo and T. Suzuki, JAIST (Japan)</p> <p>15:00 E-1-6 (Late News) Record-Low Contact Resistance for InAlN/AlN/GaN HEMTs on Si with Non-Gold Metal S. Arulkumaran¹, G.L. Ng^{1,2}, K. Ranjan¹, C.M. Manoj Kumar¹, S.C. Foo¹, K.S. Ang¹ and S. Vicknesh¹, ¹Temasek Laboratories@NTU, Nanyang Technological Univ. and ²School of EEE, Nanyang Technological Univ. (Singapore)</p>	<p>14:20 F-1-3 Atomically Flattening of Si Surface of SOI and Isolation-patterned Wafers T. Goto¹, R. Kuroda², N. Akagawa², T. Suwa¹, A. Teramoto¹, X. Li², S. Sugawa^{1,2}, T. Ohmi¹, Y. Kumagai³, Y. Kamata³ and K. Sibusawa³, ¹NICHE, Tohoku Univ., ²Graduate School of Engineering, Tohoku Univ. and ³LAPIS Semiconductor Miyagi Co., Ltd. (Japan)</p> <p>14:40 F-1-4 Large Size InGaAs-0-I Substrates Fabricated by Direct Wafer Bonding on Si E. Uccelli¹, N. Daix¹, L. Czornomaz¹, D. Caimi¹, C. Rosset¹, M. Sousa¹, H. Siegwart¹, C. Marchiori¹, J.M. Hartmann², K.T. Shiu³, C.W. Weng³, M. Krishnan³, M. Lofaro³, M. Kobayashi¹, D. Sadana¹ and J. Fompeyrine¹, ¹IBM Zurich Research Laboratory, ²CEA, LETI and ³IBM T. J. Watson Research Center (Switzerland)</p> <p>15:00 F-1-5 A New Method to Effectively Separate PBTTI-induced Shallow and Deep Energy Traps in a 28nm High-k Metal-Gate MOSFET E. Hsieh¹, P. Wu¹, S. Chung¹, J. Ke², C. Yang² and C. Tsai², ¹NCTU and ²UMC (Taiwan)</p>	<p>14:20 G-1-3 Ultrawideband Ultralow PDN Impedance of Decoupling Capacitor Embedded Interposers Using Narrow Gap Chip Parts Mounting Technology for 3-D Integrated LSI System K. Kikuchi¹, M. Ujiie², M. Aoyagi¹ and S. Takayama², ¹AIST and ²Arena Co., Ltd. (Japan)</p> <p>14:40 G-1-4 Characterization of Vapor Deposited Polyimides and Process Integration with the Polymeric Liner for Via-Last/Backside-Via Cu-TSV Formation T. Fukushima, M. Mariappan, J.C. Bea, K.W. Lee and M. Koyanagi, Tohoku Univ. (Japan)</p> <p>15:00 G-1-5 (Late News) Improved Leakage Current for TiO₂-Based MIM Capacitors by Embedding Ge Nanocrystals Y.-H. Chen, M.-T. Yu, C.-C. Lin and Y.-H. Wu, Natl. Tsing Hua Univ. (Taiwan)</p>

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
H-1: 2D Materials (1)	J-1: Tunnel FET	K-1: Flexible Electronics and Thin-film Devices	M-1: Spin Dynamics	N-1: Processing and Growth	
<p>14:15 H-1-3 Exfoliated-graphene/MoS₂/metal Vertical Field Effect Transistor with Large Current Modulation and On Current Density <i>R. Moriya¹, T. Yamaguchi¹, Y. Inoue¹, Y. Sata¹, N. Yabuki¹, S. Morikawa¹, S. Masubuchi^{1,2} and T. Machida^{1,2}, ¹IIS, Univ. of Tokyo and ²INQIE, Univ. of Tokyo (Japan)</i></p>	<p>14:20 J-1-3 Self-aligned Bottom Source Tunnel Field-Effect Transistor (Btm-S TFET) with Si:C and Si:P Epitaxial Process <i>T. Miyata, S. Mori, E. Sugizaki, M. Goto, Y. Kondo, A. Hokazono, T. Ohguro and S. Kawanaka, Toshiba Corp. (Japan)</i></p>	<p>14:15 K-1-3 Fabricating Very Short Channels in Organic Field Effect Transistors by Electrophoresis Technique <i>R. Negishi¹, T. Murata¹, J. Takeya² and Y. Kobayashi¹, ¹Osaka Univ. and ²Univ. of Tokyo (Japan)</i></p>	<p>14:15 M-1-3 Laser Induced Sub-Terahertz Coherent Spin Dynamics in Ferrimagnetic D_{0.21}Mn₃Ga Films <i>S. Mizukami, A. Sugihara and K.Z. Suzuki, Tohoku Univ. (Japan)</i></p>	<p>14:00 N-1-3 Structure of basal plane defects formed by the conversion of threading screw dislocation during solution growth of SiC <i>S. Harada, S.Y. Xiao, M. Tagawa, Y. Yamamoto, S. Arai, N. Tanaka and T. Ujihara, Nagoya Univ. (Japan)</i></p>	
<p>14:30 H-1-4 Fabrication and Characterization of MoS₂ FET structure with Nano-Sheets Ca₂Nb₂O₁₀ Gate Insulator <i>T. Kobayashi¹, S. Hirose¹, H. Uchida¹, T. Kawae¹ and A. Morimoto¹, ¹Kanazawa Univ. and ²Sophia Univ. (Japan)</i></p>	<p>14:40 J-1-4 Fabrication Process and Thermal Stability of Isoelectronic Traps for High ON-current Si-based Tunnel Field-Effect Transistors <i>T. Mori, Y. Morita, N. Miyata, S. Migita, K. Fukuda, T. Yasuda, M. Masahara and H. Ota, AIST (Japan)</i></p>	<p>14:30 K-1-4 Annealing Effect on Field-Effect Mobilities in Bottom-Contact Alkylated Dinaphthothienothiophene Transistors <i>M. Kitamura^{1,2}, Y. Kuzumoto³ and Y. Arakawa², ¹Kobe Univ., ²Univ. of Tokyo and ³Sharp Corp. (Japan)</i></p>	<p>14:30 M-1-4 Excitation of Electric-Field-induced Spin Wave in the Strained Garnet Ferrite Thin Films Using Sub-Picosecond Pulsed Wave <i>M. Adachi, H. Yamahara, M. Seki, H. Matsui and H. Tabata, Univ. of Tokyo (Japan)</i></p>	<p>14:15 N-1-4 Heteroepitaxial growth of diamond films on 3C-SiC(001)/Si substrates by antenna-edge microwave plasma CVD <i>J. Yaita^{1,2}, T. Iwasaki^{1,2,3}, M. Natal⁴, S.E. Sadow⁴ and M. Hatano^{1,2,3}, ¹Tokyo Tech, ²JST-CREST, ³JST-ALCA and ⁴Univ. of South Florida (Japan)</i></p>	
<p>14:45 H-1-5 (Invited) Band nesting in semiconducting transition metal dichalcogenide <i>G. Eda, Dept. of Physics/Chemistry, NUS and Graphene Research Centre, NUS (Singapore)</i></p>	<p>15:00 J-1-5 Design Guidelines of Steep Subthreshold TFET to Minimize Energy of Logic Circuits <i>H. Fuketa¹, K. Yoshioka¹, K. Fukuda², T. Mori², H. Ota², M. Takamiya¹ and T. Sakurai¹, ¹Univ. of Tokyo and ²AIST (Japan)</i></p>	<p>14:45 K-1-5 High-Mobility n-Channel Organic Transistor of Solution Processed Perylene-diimide Derivative Single Crystals on PS/SiO₂ Dielectric <i>S. Mondal, W.H. Lin, Y.C. Chen, B.H. Chen, T.F. Yang and M.Y. Kuo, National Chi Nan Univ. (Taiwan)</i></p> <p>15:00 K-1-6 Heat Protection Circuit with Polymer PTC for Flexible Electronics <i>T. Yokota^{1,2}, Y. Terakawa¹, J. Reeder^{1,3}, M. Kaltenbrunner^{1,2}, T. Ware², W. Voit², T. Sekitani^{2,4} and T. Someya^{1,2}, ¹Univ. of Tokyo, ²JST ERATO, ³Univ. of Texas and ⁴Univ. of Osaka (Japan)</i></p>	<p>14:45 M-1-5 Snell's law of the magnetostatic surface wave in ferromagnetic films <i>K. Tanabe¹, R. Matsumoto², J. Ohe³, S. Murakami², T. Moriyama⁴, D. Chiba⁵, K. Kobayashi¹ and T. Ono⁴, ¹Osaka Univ., ²Tokyo Tech, ³Toho Univ., ⁴Kyoto Univ. and ⁵Univ. of Tokyo (Japan)</i></p> <p>15:00 M-1-6 Spin Wave-Assisted Magnetization Switching in Nanometer-Scaled Bilayer Elements <i>T. Seki, W. Zhou and K. Takanashi, IMR, Tohoku Univ. (Japan)</i></p>	<p>14:30 N-1-5 (Late News) α-Ga₂O₃ Schottky barrier diodes fabricated by mist epitaxy technique <i>M. Oda^{1,2}, A. Takatsuka¹, T. Hitora¹, J. Kikawa³, K. Kaneko² and S. Fujita², ¹FLOSFLA, INC., ²Kyoto Univ. and ³Ritsumeikan Univ. (Japan)</i></p>	

Tuesday, September 9

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
<p>A-2: ReRAM(II) (15:40-17:15) Chairs: T. Sakamoto (LEAP) M. -H. Lee (Macronix)</p>	<p>B-2: Si Photonics (15:40-17:10) Chairs: T. Shimizu (PETRA) H. Fukuda (NTT)</p>		<p>D-2: Microfluidics (15:40-17:10) Chairs: C. -H. Liu (National Tsing Hua Univ.) T. Sakata (Univ. of Tokyo)</p>	<p>E-2: High-Frequency Devices & Circuits (15:40-17:10) Chairs: E. Lind (Lund Univ.) K. Maezawa (Univ. of Toyama)</p>	<p>F-2: Gate Stack Characterization (15:40-17:25) Chairs: K. Kita (Univ. of Tokyo) P. D. Ye (Purdue Univ.)</p>	<p>G-2: Reliability (15:40-17:20) Chairs: T. Fukushima (Tohoku Univ.) N. Sugiyama (Toray Res. Center)</p>
<p>15:40 A-2-1 Growth and Shrinkage of Conductive Filament in Cu/MoO_x ReRAMs Observed by Means of In-Situ TEM M. Arita, Y. Ohno, M. Kudo and Y. Takahashi, Hokkaido Univ. (Japan)</p>	<p>15:40 B-2-1 (Invited) Hybrid III-V on Silicon Lasers B. Ben Bakir¹, C. Sciannalepore², A. Descos¹, H. Duprez², T. Ferrotti^{1,2}, C. Jany¹, J. Harduin¹, D. Bordel¹, K. Hassan¹, A. Chantre² and S. Menezo¹, ¹CEA, Leti, Minattec Campus and ²STMicroelectronics (France)</p>		<p>15:40 D-2-1 (Invited) Device Technologies for Cell and Tissue Analysis T. Fujii, IIS, Univ. of Tokyo (Japan)</p>	<p>15:40 E-2-1 (Invited) Room-Temperature Resonant-Tunneling- Diode Terahertz Oscillator S. Suzuki and M. Asada, Tokyo Tech (Japan)</p>	<p>15:40 F-2-1 (Invited) Band Offsets at High-k Oxide/Semiconductor Interfaces: From Silicon to High-Mobility Channel Materials V.V. Afanas'ev, H.-Y. Chou, M. Houssa and A. Stesmans, Univ. of Leuven (Belgium)</p>	<p>15:40 G-2-1 Stress Distribution Pattern in Cross- Sectional 3D-LSI Examined by u-XRD M. Mariappan, J.C. Bea, T. Fukushima, K.W. Lee and M. Koyanagi, Tohoku Univ. (Japan)</p>
<p>16:00 A-2-2 Dual-Mode Bipolar Resistance Switching in the HfO₂ RRAM Device H.Z. Zhang¹, K.S. Yew¹, D.S. Ang², C.J. Gu¹ and X.P. Wang², ¹Nanyang Tech. Univ. and ²Inst. of Microelectronics, A*STAR (Singapore)</p>	<p>16:10 B-2-2 High Efficiency Apodized Grating Couplers with Metal Mirrors between a-Si:H Multilayer Waveguides toward 3D Optical Interconnection Y. Kuno, J. Kang, Y. Hayashi, J. Suzuki, T. Amemiya, N. Nishiyama and S. Arai, Tokyo Tech (Japan)</p>		<p>16:10 D-2-2 (Invited) Microfluidic biochip technology for biological cell research M.-H. Wu, Chang Gung Univ. (Taiwan)</p>	<p>16:10 E-2-2 F-band Bidirectional Transceiver using 75-nm InP HEMTs S. Shiba¹, M. Sato¹, H. Matsumura¹, Y. Kawano¹, T. Suzuki¹, Y. Nakasha¹, T. Takahashi¹, K. Makiyama¹, T. Iwai¹ and N. Hara¹, ¹Fujitsu Ltd. and ²Fujitsu Laboratories Ltd. (Japan)</p>	<p>16:10 F-2-2 Quantitative Evaluation of Slow Traps near Ge MOS Interfaces by Using Time Response of MOS Capacitance K. Tanaka^{1,2}, R. Zhang^{1,2}, M. Tanaka^{1,2} and S. Takagi^{1,2}, ¹Univ. of Tokyo and ²JST-CREST (Japan)</p>	<p>16:00 G-2-2 Investigation of the Plasma Damage by Etching Process for TSV Formation in Via-last Backside-via 3D IC Y. Sugawara¹, H. Hashiguchi¹, S. Tanikawa¹, H. Kino², K. Lee³, T. Fukusima⁴, M. Koyanagi³ and T. Tanaka^{1,2}, ¹Dept. of Bioengineering and Robotics, Tohoku Univ., ²Dept. of Biomedical Engineering, Tohoku Univ. and ³NICHE, Tohoku Univ. (Japan)</p>
<p>16:20 A-2-3 Electro-thermal driven nano-scale IMT characteristics of SmNiO₃ for selector application of cross-point memory array S.H. Misha, N. Tamanna, A. Prakash, J. Song, D. Lee, E. Cha and H. Hwang, Pohang Univ. of Sci. and Tech. (Korea)</p>	<p>16:25 B-2-3 A High Extinction Ratio Silicon Nitride Polarizing Beam Splitter J. Feng and R. Akimoto, AIST (Japan)</p>		<p>16:40 D-2-3 In Vitro Reconstruction of Tumor Microenvironment for Studying Angiogenesis K.W. Chang¹, Y.Y. Hsu¹, T.H. Punde¹, Y.F. Chan², L.W. Kuo², K.Y. Lee² and C.H. Liu¹, ¹National Tsing Hua Univ. and ²Shuang Ho Hospital (Taiwan)</p>	<p>16:25 E-2-3 Experimental Demonstration of Resonant Tunneling Super Regenerative Detectors Detecting High Order Harmonic Signals J. Pan, Y. Kakutani, T. Nakayama, M. Mori and K. Maezawa, Univ. of Toyama (Japan)</p>	<p>16:30 F-2-3 Validity of Direct-gap Photoluminescence Analysis for Non- destructive Characterization of Oxide/Germanium Interface S. Kabuyanagi^{1,2}, T. Nishimura^{1,2}, T. Yajima^{1,2}, K. Nagashio^{1,2} and A. Toriumi^{1,2}, ¹Univ. of Tokyo and ²JST-CREST (Japan)</p>	<p>16:20 G-2-3 Dominant Factors of Stress-Induced Migration in Electroplated Copper Thin Films Used for Through Silicon Via (TSV) Interconnections K. Suzuki, R. Furuya and H. Miura, Tohoku Univ. (Japan)</p>
<p>16:40 A-2-4 Self-Rectifying Ta/TaO_x/ TiO₂/Ti Cell for High- Density Flexible RRAM C.T. Chou, C.W. Hsu, C.C. Chang and T.H. Hou, NCTU (Taiwan)</p>	<p>16:40 B-2-4 Humidity Tolerance for Athermal Si-Slot Wavelength Filters using Amorphous Fluoride Polymer and SiO₂ Protection Layer Y. Atsumi, J. Kang, J. Suzuki, Y. Hayashi, N. Nishiyama and S. Arai, Tokyo Tech (Japan)</p>		<p>16:55 D-2-4 High-Efficiency Cellular Separation Method Utilizing Optically-Induced Dielectrophoretic (ODEP) Force-based Microfluidic Platform S.B. Huang¹, S.L. Liu¹, T.K. Chiu¹, C.H. Hsieh² and M.H. Wu¹, ¹Chang Gung Univ. and ²Hosp. of Chang Gung Memorial (Taiwan)</p>	<p>16:40 E-2-4 Non-destructive Mapping of Doping and Structural Composition of High Current Density Resonant Tunnelling Diodes Grown by Metal-Organic Vapour Phase Epitaxy Through Photoluminescence Spectroscopy K.J.P. Jacobs¹, B.J. Stevens², T. Mukai³, D. Ohmishi³ and R.A. Hogg¹, ¹Univ. of Sheffield, ²EPSRC National Centre for III-V Technologies and ³Rohm Co. Ltd. (UK)</p>	<p>16:50 F-2-4 Spatial Variation of the Work Function in Nano- crystalline TiN Films Measured by Dual-Mode Scanning Tunneling Microscopy L. Bolotov, K. Fukuda, T. Tada, T. Matsukawa and M. Masahara, AIST (Japan)</p>	<p>16:40 G-2-4 Suppression of Cu Ion Drift by Metal-Cap on Cu lines, Improving Interconnect Dielectric Reliability M. Ueki, N. Furutake, N. Inoue and Y. Hayashi, Renesas Electronics Corp. (Japan)</p>
<p>17:00 A-2-5 (Late News) Modeling of Read Disturbance Mechanism due to Carrier Trapping in Sub-20nm NAND Flash Memory D. Kang¹, K. Lee¹, S. Kwon², S. Kim², Y. Hwang² and H. Shin¹, ¹Seoul National Univ. and ²Samsung Electronics Corp., Ltd. (Korea)</p>	<p>16:55 B-2-5 (Late News) High-quality thin-film- like multifold Ge/Si/ Ge composite quantum- dot hetero-structures for visible to near-infrared photodetection M.-H. Kuo¹, W.-T. Lai¹, H.- T. Chang², S.-W. Lee² and P.- W. Li¹, ¹Dept. of Electrical Engineering and Center for Nano Science and Technology, National Central Univ. and ²Institute of Materials Science and Engineering, National Central Univ. (Taiwan)</p>		<p>16:55 E-2-5 (Late News) Impact of In_xGa_{1-x}As Capping Layer on Characteristic of III-V Trigate MOSFET Devices C.-H. Huang^{1,2} and Y. Li^{1,2,3}, ¹Parallel and Scientific Computing Lab., NCTU, ²Institute of Communications Engineering, NCTU and ³Dept. of Electrical and Computer Engineering, NCTU (Taiwan)</p>	<p>16:55 E-2-5 (Late News) Sub-300°C Fabrication of Poly-GeSn Junctionless Tri-Gate p-FETs Enabling Sequential 3D Integration of CMOS Circuits M. Kurosawa^{1,2}, Y. Kamata¹, H. Ikenoue⁴, N. Taoka¹, O. Nakatsuka¹, T. Tezuka³ and S. Zaima¹, ¹Nagoya Univ., ²JSPS, ³AIST/GNC and ⁴Kyushu Univ. (Japan)</p>	<p>17:10 F-2-5 (Late News) Analysis of the Breakdown Voltage of an Area Surrounded by the Multi-trench Gaps in a 4kV Monolithic Isolator for a Communication Network Interface Y. Takeuchi, R. Kuroda and S. Sugawa, Graduate School of Engineering, Tohoku Univ. (Japan)</p>	

Tuesday, September 9

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
<p>H-2: 2D Materials (2) (15:40-17:25) Chairs: T. Suemasu (Univ. of Tsukuba) T. Nagata (NIMS)</p>	<p>J-2: Characterization (15:40-17:25) Chairs: T. Hiramoto (Univ. of Tokyo) K. Sukegawa (Fujitsu Semicon.)</p>	<p>K-2: Organic Photovoltaics I (15:40-16:55) Chairs: M. Ikegami (Toin Univ. of Yokohama) K. Tajima (RIKEN)</p>	<p>M-2: Spin Transport (15:40-17:25) Chairs: H. Shimizu (Tokyo Univ. of Agri. & Tech.) K. Hamaya (Osaka Univ.)</p>	<p>N-2: Power Devices and Modules (15:40-17:25) Chairs: S. Matsumoto (Kyushu Inst. of Tech.) H. Tadano (Univ. of Tsukuba)</p>	
<p>15:40 H-2-1 (Invited) Growth, characterization, and functionalization of graphene and hexagonal boron nitride <i>H. Hibino, S. Wang, C.M. Orofeo and S. Suzuki, NTT Corp. (Japan)</i></p>	<p>15:40 J-2-1 (Invited) Comprehensive Investigation of Self-Heating Effect (SHE) in Nanoscale Planar and Fin FETs: Impacts of Device Parameters on SHE and Analog Performance Optimization <i>T. Takahashi^{1,2}, T. Matsuki³, T. Shinada⁴, Y. Inoue⁵ and K. Uchida^{1,2}, ¹Keio Univ., ²JST-CREST and ³AIST (Japan)</i></p>	<p>15:40 K-2-1 (Invited) Design and Characterizations of Perovskite Solar Cells <i>H.-Y. Hsu and E.W.-G. Diau, NCTU (Taiwan)</i></p>	<p>15:40 M-2-1 (Invited) Magneto-reprogrammable semiconductor logic at room temperature <i>J. Hong¹, S. Joo², J.D. Song³, J. Chang⁴ and M. Johnson⁵, ¹Korea Univ., ²KRISS, ³Center for Opto-Electronic Convergence Systems, KIST, ⁴Spin Convergence Research Center, KIST and ⁵Naval Research Lab (Korea)</i></p>	<p>15:40 N-2-1 (Invited) Challenges to the silicon IGBT limit with PNM structure <i>M. Sumitomo, H. Sakane, K. Arakawa, Y. Higuchi and M. Matsui, DENSO Corp. (Japan)</i></p>	
<p>16:10 H-2-2 Chemical Vapor Deposition of Hexagonal Boron Nitride Films on c-plane Sapphire Substrates <i>N. Umehara, I. Kuwahara, T. Kouno, H. Kominami, Y. Nakanishi and K. Hara, Shizuoka Univ. (Japan)</i></p>	<p>16:10 J-2-2 Improvement of S-factor Method for Evaluation of MOS Interface State Density <i>W.-L. Cai^{1,2}, M. Takenaka^{1,2} and S. Takagi^{1,2}, ¹Univ. of Tokyo and ²JST-CREST (Japan)</i></p>	<p>16:10 K-2-2 Dye-sensitized Solar Cells Using Scattering Layer with Micron-sized Pores for Indoor Light Energy Harvesting <i>M. Suzuka, H. Yabe, N. Hayashi, T. Kitagaki and T. Sekiguchi, Panasonic Corp. (Japan)</i></p>	<p>16:10 M-2-2 Anisotropic spin dynamics of drifting electrons with coexistence of Rashba and Dresselhaus spin-orbit interactions <i>Y. Kunihashi¹, H. Sanada¹, H. Goioh¹, K. Onomitsu¹, M. Kohda¹, J. Nitta² and T. Sogawa¹, ¹NTT BRL and ²Tohoku Univ. (Japan)</i></p>	<p>16:10 N-2-2 Current filamentation caused by dynamic avalanche during turn-off transient under short-circuit operation of IGBTs <i>T. Kobayashi¹, T. Suwa¹, T. Matsuda² and T. Ogura², ¹Toshiba I.S. Corp. and ²Toshiba Corp. (Japan)</i></p>	
<p>16:25 H-2-3 Quantum Interference in a Ballistic Graphene n-p-n Junction: Fabry-Perot Interference and a Novel Magnetoresistance Oscillation <i>S. Morikawa¹, S. Masubuchi¹, R. Moriya¹, K. Watanabe², T. Taniguchi² and T. Machida¹, ¹Univ. of Tokyo and ²NIMS (Japan)</i></p>	<p>16:30 J-2-3 Effective Work Function Shift Induced by TiN Sacrificial Metal Gates as a Function of Their Thickness and Composition in 14 nm NMOS devices <i>C. Suarez-Segovia^{1,2}, P. Caubet¹, V. Joseph¹, O. Gourhant¹, G. Romano¹, F. Domengie¹ and G. Ghibaudo³, ¹STMicroelectronics and ²IMEP-LAHC (France)</i></p>	<p>16:25 K-2-3 Development of Integrated Tandem Dye Sensitized Solar Cells <i>S. Kosar¹, Y. Struk¹, Y. Pihosh², K. Matsubara³, M. Kondo³ and I. Turkevych¹, ¹Chernitsy National Univ., ²Univ. of Tokyo and ³AIST (Ukraine)</i></p>	<p>16:25 M-2-3 Large Spin Accumulation Signals in Epitaxial Mn5Ge3 Contacts on Ge without Oxide Tunnel Barrier <i>A. Spiesser, H. Saito, R. Jansen, S. Yuasa and K. Ando, Spintronics Res. Center, AIST (Japan)</i></p>	<p>16:25 N-2-3 Design for EMI suppression during reverse recovery by 600V lateral SOI PiN diode with traps <i>M. Tsukuda¹, H. Imaki² and I. Omura², ¹The International Centre for the Study of East Asian Development and ²Kyusyu Inst. of Tech. (Japan)</i></p>	
<p>16:40 H-2-4 Fabrication of Two-Dimensional 10 nm Graphene Dot Array and Optical Characterization <i>T. Okada¹, K. Igarashi¹, P. Han², T. Hitosugi², C.H. Huang³, C.Y. Su⁴ and S. Samukawa², ¹IFS, Tohoku Univ., ²WPI-AIMR, Tohoku Univ., ³Ming Chi Univ. of Tech. and ⁴National Central Univ. (Japan)</i></p>	<p>16:50 J-2-4 Radiation Hardness Evaluations of 65 nm FD-SOI and Bulk Processes by Measuring SET Pulse Widths and SEU Rates <i>E. Sonezaki, J. Furuta and K. Kobayashi, Kyoto Inst. of Tech. (Japan)</i></p>	<p>16:40 K-2-4 Improvement of Electrical Conductivity by Low-temperature Solvent Annealing Method for High Performance Organic Solar Cells <i>S.J. Park, K.Y. Lee, D.H. Kim and Y.J. Kim, Yonsei Univ. (Korea)</i></p>	<p>16:40 M-2-4 Effect of Insertion Layers on Schottky Barrier Height of Fe/n-type Ge Junctions <i>H. Saito, Y. Sato, T. Takada, R. Jansen and S. Yuasa, AIST (Japan)</i></p>	<p>16:40 N-2-4 An 800V-class lateral NMOS structure with a reduced parasitic capacitance for a level-shift circuit integrated in a high voltage gate driver IC <i>M. Yamaji¹, A. Jonishi¹, H. Sumida² and Y. Hashimoto², ¹Fuji Electric Corp. Ltd. and ²Shinshu Univ. (Japan)</i></p>	
<p>16:55 H-2-5 Influence of Rhenium on the Structural and Optical Properties of Molybdenum Disulfide <i>M. Sigiyo¹, Y.S. Huang¹, C.H. Ho², Y.C. Lin³, K. Suenaga³ and K.K. Tiong⁴, ¹Department of Electronic and Computer Eng. National Taiwan Univ. of Sci. and Tech., ²Graduate Inst. of Applied Sci. and Tech. National Taiwan Univ. of Sci. and Tech., ³AIST and ⁴National Taiwan Ocean Univ. (Taiwan)</i></p>	<p>17:10 J-2-5 (Late News) Charge Pumping Current from Single Si/SiO₂ Interface Traps: Direct Observation of P_b Centers and Fundamental Trap-Counting by the Charge Pumping Method <i>T. Tsuchiya¹ and Y. Ono², ¹Shimane Univ. and ²Univ. of Toyama (Japan)</i></p>		<p>16:55 M-2-5 Layer Thickness Dependence of Spin Orbit Torques and Fields in Pt/Co/AIO Trilayer Structures. <i>T. Yang¹, M. Kohda¹, T. Seki², K. Takanashi² and J. Nitta¹, ¹Department of Materials Science, Tohoku Univ. and ²Institute for Materials Research, Tohoku Univ. (Japan)</i></p>	<p>16:55 N-2-5 250°C Switching Behavior of All SiC Power Module with Sandwich Structure <i>F. Kato^{1,2}, R. Simanjorang², F. Lang², H. Nakagawa^{1,2}, H. Yamaguchi^{1,2} and H. Sato^{1,2}, ¹AIST and ²R&D Partnership for Future Power Electronics Tech. (Japan)</i></p>	
<p>17:10 H-2-6 Withdrawn</p>			<p>17:10 M-2-6 Magnetic Sensors Based on MgO-Magnetic Tunnel Junctions with Perpendicularly Magnetized CoFeB Sensing Layers <i>T. Nakano¹, M. Oogane¹, H. Naganuma¹, T. Yano², K. Ao² and Y. Ando¹, ¹Tohoku Univ. and ²DENSO Corp. (Japan)</i></p>	<p>17:10 N-2-6 High speed real-time temperature monitoring system inside power devices package using infrared radiation <i>N. Hirata, A. Watanabe and I. Omura, Kyushu Inst. of Tech. (Japan)</i></p>	

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
<p>A-3: CBRAM/DRAM (9:30-11:00) Chairs: K. Hamada (Micron Memory Japan) T. Sakamoto (LEAP)</p>	<p>B-3: Light Sources and Functional Devices (9:30-11:15) Chairs: H. Oohashi (NTT Electronics) K. Kojima (Tohoku Univ.)</p>	<p>C-3: Growth and Process of Nitrides (9:30-10:45) Chairs: T. Iwai (Fujitsu Lab.) T. Suemasu (Univ. of Tsukuba)</p>	<p>D-3: Biosensors (9:30-10:45) Chairs: H. -M. Chen (NCTU) R. Tero (Toyohashi Univ. of Tech.)</p>	<p>E-3: GaN Power Devices (9:30-11:15) Chairs: T. Tanaka (Panasonic) T. Uesugi (Toyota Central R&D Labs.)</p>	<p>F-3: Interface and Material Science (9:30-11:00) Chairs: K. Kakushima (Tokyo Tech) T. Yamaguchi (Renesas Electronics)</p>	
<p>9:30 A-3-1 (Invited) Current Status of Cation-Based Resistive Memory <i>M.N. Kozicki and H.J. Barnaby, Arizona State Univ. (USA)</i></p>	<p>9:30 B-3-1 Demonstration of GaAs based Nanowire Plasmonic Laser <i>J.F. Ho¹, J. Tatebayashi¹, S. Sergeant¹, C.F. Fong¹, S. Iwamoto^{1,2} and Y. Arakawa^{1,2}, ¹Inst. Nano Quantum Info. Electron., Univ. of Tokyo and ²Inst. Industrial Sci., Univ. of Tokyo (Japan)</i></p>	<p>9:30 C-3-1 (Invited) Direct Growth of Uniform In-rich InGaN on Si: A New Basic Technology <i>P. Aseev¹, P.S. Rodriguez¹, V.J. Gómez¹, P. Kumar¹, N.H. Alvi¹, J.M. Manuel², F.M. Morales², J.J. Jiménez², R. García², E. Calleja¹ and R. Nötzel¹, ¹Univ. Politécnica de Madrid and ²Univ. de Cádiz (Spain)</i></p>	<p>9:30 D-3-1 Sensitivity Enhancement for Reaction between Drosophila LUSH odorant-binding Protein and Ethanol using Dual-Gate EGFETs <i>I.K. Lee¹, T.E. Bae¹, H.C. Lau¹, J.O. Lim², J.Y. Kwon², T.J. Ha¹ and W.J. Cho¹, ¹Kwangwoon Univ., ²Kyungpook National Univ. and ³Sungkyunkwan Univ. (Korea)</i></p>	<p>9:30 E-3-1 (Invited) Commercialization of 600V GaN HEMTs <i>P. Parikh¹, Y. Wu¹, U. Mishra¹, L. Shen¹, R. Birkhahn¹, B. Swenson¹, J. Gritters¹, R. Barr¹, L. McCarthy¹, J. Honea¹, S. Yea¹, K. Smith¹, P. Smith¹, D. Dunn¹, J. McKay¹, H. Clement¹, T. Kikkawa², T. Hosoda², Y. Asai², K. Imanashi² and K. Shono², ¹Transphorm Inc. and ²Transphorm Japan Inc. (USA)</i></p>	<p>9:30 F-3-1 (Invited) Negative Capacitance in Ferroelectric Materials and Implications for Steep Transistors <i>S. Salahuddin, Univ of California, Berkeley (USA)</i></p>	
<p>10:00 A-3-2 Mechanism of OFF-State Lifetime Improvement in Complementary Atom Switch <i>N. Banno, M. Tada, T. Sakamoto, M. Miyamura, K. Okamoto, N. Iguchi, T. Nohisa and H. Hada, LEAP (Japan)</i></p>	<p>9:45 B-3-2 Optical Coherence Tomography Imaging by Using a Superluminescent Diode Based on InAs/GaAs Quantum Dots <i>H. Shibata¹, T. Yasuda¹, S. Ohkouchi², N. Ikeda³, H. Ohsato³, E. Watanabe³, Y. Sugimoto³, K. Furuki⁴, K. Miyajiri⁵, R.A. Hogg⁵ and N. Ozaki¹, ¹Wakayama Univ., ²NEC Corp., ³NIMS, ⁴Think-Lands Co. Ltd. and ⁵Univ. Sheffield (Japan)</i></p>	<p>10:00 C-3-2 Selective Area Growth of N-face GaN (000-1) Films by Group-III-Source Flow-Rate Modulation Epitaxy <i>T. Akasaka, C.H. Lin and H. Yamamoto, NTT BRL (Japan)</i></p>	<p>9:45 D-3-2 Elucidation of semiconductor / bio-interface structure by molecular dynamics simulation <i>Y. Maekawa, Y. Shibuta and T. Sakata, Univ. of Tokyo (Japan)</i></p>	<p>10:00 E-3-2 A Novel High-Current Density GaN-based Normally-Off Transistor with Tensile Strained Quaternary InAlGaIn Barrier <i>R. Kajitani, K. Tanaka, M. Ogawa, H. Ishida, M. Ishida and T. Ueda, Panasonic Corp. (Japan)</i></p>	<p>10:00 F-3-2 Development of Ferroelectric Phase in TiN/Hf-Zr-O/TiN Capacitors Prepared by Sputter Deposition and Capped Anneal <i>R. Migita, H. Ota, Y. Morita and M. Masahara, AIST (Japan)</i></p>	
<p>10:20 A-3-3 DRAM with Storage Capacitance of 3.9 fF using CAAC-OS Transistor with L of 60 nm and having More Than 1-h Retention Characteristics <i>T. Onuki, K. Kato, M. Nomura, Y. Yakubo, S. Nagatsuka, T. Matsuzaki, S. Hondo, Y. Hata, Y. Okazaki, M. Nagai, T. Atsumi, M. Sakakura, T. Okuda, Y. Yamamoto and S. Yamazaki, Semiconductor Energy Lab. Corp., Ltd. (Japan)</i></p>	<p>10:00 B-3-3 Effect of Cavity-Layer Thicknesses on Two-Color Lasing in a Coupled Multilayer Cavity with InAs Quantum Dots <i>C. Harayama¹, S. Kato¹, Y. Nakagawa^{1,2}, X. Lu¹, N. Kumagai¹, T. Kitada¹ and T. Isu¹, ¹Univ. of Tokushima and ²NICHIA Corp. (Japan)</i></p>	<p>10:15 C-3-3 Synthesis of Gallium Nitride Nanostructure by Ammoniating the Electrochemically Deposited Gallium Oxide on Silicon Substrate <i>N. M. Ghazali¹, M.R. Mahmood², K. Yasui³ and A.M. Hashim¹, ¹Univ. Teknologi Malaysia, ²Univ. Teknologi MARA and ³Nagaoka Univ. of Tech. (Malaysia)</i></p>	<p>10:00 D-3-3 A Miniaturized Implantable Glucose Sensor Based on CMOS Line Sensor Using Glucose-Responsive Fluorescent Hydrogel <i>T. Kawamura¹, M. Takahashi², K. Masuda¹, T. Noda¹, K. Sasagawa¹, T. Tokuda¹, T. Okitsu², S. Takeuchi³ and J. Ohta¹, ¹Nara Inst. of Sci. and Tech., ²BEANS Laboratory and ³Univ. of Tokyo (Japan)</i></p>	<p>10:15 E-3-3 5V High Threshold Voltage Normally-off MIS-HEMTs with Combined Partially Recessed and Multiple Fluorinated-Dielectric Layers Gate Structures <i>H. Huang¹, Y.H. Wang¹, Y.C. Liang², G.S. Samudra¹, C.F. Huang² and W.H. Kuo³, ¹National Univ. of Singapore, ²National Tsing Hua Univ. and ³Indus. Tech. Res. Inst. (Singapore)</i></p>	<p>10:20 F-3-3 SiO₂-interface Layer Reduction in HfO₂ Gate Stacks through Si-substrate Oxidation <i>X. Li, T. Yajima, T. Nishimura, K. Nagashio and A. Toritami, Univ. of Tokyo (Japan)</i></p>	
<p>10:40 A-3-4 2T1C Gain Cell Memory with Improved Retention Characteristic By Dual Coupling Method for SOC application Using 45nm-logic compatible CMOS Process <i>C.J. Lee, Y.K. Lee, M.K. Park, S.W. Kim and D.H. Lee, Samsung Electronics Corp. (Korea)</i></p>	<p>10:15 B-3-4 Intersubband All-Optical Logic Gate in InGaAs/AlAsSb Quantum Wells <i>J. Feng, R. Akimoto and S. Gozu, AIST (Japan)</i></p>	<p>10:30 C-3-4 Droplet Epitaxial Growth of 1.55-μm Wavelength InAs Quantum Dots on Metamorphic InAlAs/GaAs(III)A <i>N. Ha^{1,2}, T. Mano¹, X. Liu¹, T. Kuroda^{1,2}, K. Mitsuishi¹, A. Ohtake¹, A. Castellano^{1,3}, S. Sanguinetti³, T. Noda¹, Y. Sakuma¹ and K. Sakoda¹, ¹NIMS, ²Kyushu Univ. and ³Univ. Milano Bicocca (Japan)</i></p>	<p>10:15 D-3-4 Signal Amplification of Immune-Field-Effect Transistors Using Enzyme Catalyzed Ag Reduction to Overcome Debye Screening Length <i>H.J. Jang¹, J.H. Ahn², S.W. Moon¹, T.E. Bae¹, M.G. Kim³, Y.B. Shin⁴ and W.J. Cho¹, ¹Department of Electronic Materials Eng, Kwangwoon Univ., ²Department of Nano Manufac Tech, Nano Convergence Mech Systems Res Division, Korea Inst of Machinery and Materials, ³Department of Chemistry, Gwangju Inst of Sci & Tech and ⁴Res Center of Integrative Cellulomics, Korea Res Institute of Bioscience and Biotech (Korea)</i></p>	<p>10:30 E-3-4 Normally-off Operation GaN HEMT Devices with Nano-pattern Structure <i>Y.K. Fu, W.H. Kuo, S.F. Lin and Y.L. Chou, Indus. Tech. Res. Inst. (Taiwan)</i></p>	<p>10:40 F-3-4 Defect Distribution and MIGS at Metal/Ge Interfaces; First-Principles Study <i>S. Sasaki, T. Hiramatsu, K. Kobinata and T. Nakayama, Chiba Univ. (Japan)</i></p>	

Wednesday, September 10

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
<p>H-3: Topological Insulators and Imaging (9:30-11:15) Chairs: A. Kimura (Hiroshima Univ.) K. Terabe (NIMS)</p>	<p>J-3: CMOS Platform & SRAM (9:30-11:15) Chairs: H. Tokita (Renesas Electronics) N. Planes (STMicroelectronics)</p>	<p>K-3: Organic Photovoltaics II (9:30-11:00) Chairs: P. Ho (National Univ. of Singapore) S. Yata (Panasonic)</p>	<p>M-3: RF and Analog Techniques (9:30-11:15) Chairs: I. Akita (Toyoashi Univ. of Tech.) T. Matsuda (Toyama Pref. Univ.)</p>		<p>P-3: Nanowire Electronics (9:30-11:15) Chairs: K. Kawaguchi (Univ. of Tokyo) G. Zhang (NTT)</p>
<p>9:30 H-3-1 (Invited) Quantum anomalous Hall effect in magnetically doped topological insulator <i>K. He, Y. Wang and Q.-K. Xue, Tsinghua Univ. (China)</i></p>	<p>9:30 J-3-1 (Invited) A 16 nm FinFET CMOS Technology for Mobile SoC and Computing Applications <i>S.-Y. Wu, C.Y. Lin, M.C. Chiang, J.J. Liaw, J.Y. Cheng, S.H. Yang, C.H. Yao, T.L. Lee, W. Chang, C.C. Chen, M.H. Tsai, S.M. Jang, K.S. Chen and Y. Ku, Taiwan Semiconductor Manufacturing Company (Taiwan)</i></p>	<p>9:30 K-3-1 (Invited) FUTURE PROSPECTS OF ORGANIC AND HYBRID SOLAR CELLS FOR NEXT GENERATION PHOTOVOLTAICS <i>H. Segawa, Univ. of Tokyo (Japan)</i></p>	<p>9:30 M-3-1 (Invited) Time Difference Amplifier and Its Application for TDC <i>T. Nakura, Univ. of Tokyo (Japan)</i></p>		<p>9:30 P-3-1 (Invited) Signatures of Majorana Fermions in Topological Superconductor Nanowires <i>H. Xu, Lund Univ. and Peking Univ. (Sweden)</i></p>
<p>10:00 H-3-2 Band-Alignment Induced Current Modulation in Bi₂Se₃ Topological Insulator <i>G. Gupta, M.B.A. Jalil and G. Liang, NUS (Singapore)</i></p>	<p>10:00 J-3-2 Detailed Analysis of Minimum Operation Voltage (V_{min}) of Extraordinarily Unstable Cells in Fully Depleted Silicon-on-Thin-BOX (SOTB) 6T-SRAM <i>T. Mizutani¹, Y. Yamamoto², H. Makiyama², T. Yamashita², H. Oda², S. Kamohara², N. Sugii² and T. Hiramoto¹, ¹Univ. of Tokyo and ²LEAP (Japan)</i></p>	<p>10:00 K-3-2 Push Coating Technique Applied for a Bulk-heterojunction Solar Cell <i>S. Kobayashi¹, D. Kaneto¹, S. Fujii², H. Kataura² and Y. Nishioka¹, ¹Ninon Univ. and ²AIST (Japan)</i></p>	<p>10:00 M-3-2 A 0.8 ps-LSB, 10-bit, 0.018 mm² Time-to-Digital Converter <i>Z. Xu, M. Sugawara, M. Miyahara and A. Matsuzawa, Tokyo Tech (Japan)</i></p>		<p>10:00 P-3-2 Encapsulated Gate-All-Around InAs/InP Core-Shell Nanowire FETs <i>S. Sasaki, K. Tateno, G. Zhang, H. Pigot, Y. Harada, S. Saito, A. Fujiwara, T. Sogawa and K. Muraki, NTT Basic Research Labs. (Japan)</i></p>
<p>10:15 H-3-3 (Late News) Electric transport properties of the thallium-based topological insulators <i>G. Eguchi¹, K. Kuroda², K. Shirai², A. Kimura² and M. Shiraiishi¹, ¹Dept. of Electronic Science and Engineering, Graduate School of Engineering, Kyoto Univ. and ²Graduate School of Science, Hiroshima Univ. (Japan)</i></p>	<p>10:20 J-3-3 Comparison and Statistical Analysis of Four Write Stability Metrics in Bulk CMOS SRAM Cells <i>H. Qiu, T. Mizutani, T. Saraya and T. Hiramoto, Univ. of Tokyo (Japan)</i></p>	<p>10:15 K-3-3 Control of Donor/Acceptor Interface in Bilayer Organic Solar Cells <i>K. Tajima^{1,2}, Y.F. Zhong^{1,3}, A. Tada³, Y.F. Geng^{3,4}, Q.S. Wei³, S. Izawa^{1,3} and K. Hashimoto³, ¹RIKEN CEMS, ²JST, ³Univ. of Tokyo and ⁴NCNST (Japan)</i></p>	<p>10:20 M-3-3 Evaluation of Uniqueness of Output from Current Mismatch ID Generation Circuit for Sensor Network Services <i>K. Matsunaga, S. Oshima, T. Minotani, T. Kondo and H. Morimura, NTT Microsystem Integration Laboratories (Japan)</i></p>		<p>10:15 P-3-3 Integration of Vertical InAs Nanowires on Ge(111) by Selective-Area MOVPE <i>K. Tomioka^{1,2}, F. Ishizaka¹, E. Nakai¹ and T. Fukui¹, ¹Hokkaido Univ. and ²JST-PRESTO (Japan)</i></p>
<p>10:30 H-3-4 Withdrawn</p>	<p>10:40 J-3-4 High Reliability SRAM Development for 40 nm Embedded Spilt Gate-MONOS <i>S. Okamoto¹, K. Maekawa², Y. Kawashima¹, K. Shiba², H. Sugiyama¹, M. Inoue¹ and A. Nishida¹, ¹Renesas Electronics Corp. and ²Renesas Semiconductor Manufacturing Co., Ltd. (Japan)</i></p>	<p>10:30 K-3-4 The Effect of Bathocuproine (BCP) buffer layer in boron subphthalocyanine chloride (SubPc)/fullerene (C₆₀) Organic Solar Cells with inverted structure <i>X. Hao, S. Wang, T. Sakurai and K. Akimoto, Univ. of Tsukuba (Japan)</i></p>	<p>10:40 M-3-4 A Nano-Watt Power Rail-to-Rail CMOS Amplifier with Adaptive Biasing for Ultra-Low Power Analog LSIs <i>T. Ozaki, T. Hirose, K. Tsubaki, N. Kuroki and M. Numa, Kobe Univ. (Japan)</i></p>		<p>10:30 P-3-4 Impact of High-κ Spacers on Parasitic Effects Considering DC/AC Performance Optimization in Si-Nanowire FETs for sub 10 nm Technology Node <i>J.H. Hong¹, S.H. Lee¹, Y.R. Kim¹, E.Y. Jeong¹, J.S. Yoon¹, J.S. Lee¹, R.H. Baek² and Y.H. Jeong¹, ¹Pohang Univ. of Tech. and Sci. and ²SEMATECH (Korea)</i></p>

Wednesday, September 10

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
A-3: CBRAM/DRAM	<p>B-3: Light Sources and Functional Devices</p> <p>10:30 B-3-5 Room Temperature Lasing Characteristics in Metal-Coated GaN Spiral and Grating Structures <i>S.W. Liao¹, W.C. Liao¹, K.J. Chen¹, M.H. Shih^{1,2} and H.C. Kuo¹, ¹NCTU and ²Academia Sinica (Taiwan)</i></p> <p>10:45 B-3-6 Highly Efficient White Organic Light Emitting Devices with a Binary Random Phase Array <i>T. Hirasawa¹, Y. Inada¹, S. Nishiwaki¹, J. Matsuzaki², Y. Nakamura¹, A. Hashiya¹, S. Wakabayashi¹ and M. Suzuki¹, ¹Panasonic Corp. and ²Panasonic Corp. Eco Solutions Company (Japan)</i></p> <p>11:00 B-3-7 Synthetic Multi-Spectral Material Filter Based on Terahertz Metamaterial Combined with Thin-Film Etalon Structure <i>H. Kang, H. Jung and H. Lee, Soongsil Univ. (Korea)</i></p>	C-3: Growth and Process of Nitrides	<p>D-3: Biosensors</p> <p>10:30 D-3-5 (Late News) Anions Sensing and Interfering Behaviors of Electrolyte-Insulator-Semiconductor Sensors with Nitrogen Plasma Treated Samarium Oxide <i>Y.-T. Chan, Y.-R. Ye, J.-C. Wang and C.-S. Lai, Dept. of Electronic Engineering, Chang Gung Univ. (Taiwan)</i></p>	<p>E-3: GaN Power Devices</p> <p>10:45 E-3-5 Enhancement-mode AlGaIn/GaN HEMTs by selective area growth of AlGaIn layer with Al₂O₃ deposition <i>T. Narita, K. Inoue, A. Wakejima and T. Egawa, Nagoya Inst. of Tech. (Japan)</i></p> <p>11:00 E-3-6 Study of Constant Voltage Off-state Stress on Au-free AlGaIn/GaN Schottky Barrier Diodes <i>J. Hu^{1,2}, S. Stoffels¹, S. Lenci¹, T. Wu^{1,2}, N. Ronchi¹, S. You¹, B. Bakeroot^{1,3}, G. Groeseneken^{1,2} and S. Decoutere¹, ¹imec, ²KU Leuven and ³Ghent Univ. (Belgium)</i></p>	F-3: Interface and Material Science	

Wednesday, September 10

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
H-3: Topological Insulators and Imaging 10:45 H-3-5 Real-space Mapping of Spin-resolved Quantum Hall Chiral Edge States by Near-field Scanning Optical Microscopy <i>S. Nomura¹, S. Mamyouda¹, H. Ito¹, Y. Shibata¹, T. Ohira¹, L. Yoshikawa¹, Y. Ootuka¹, S. Kashiwaya², M. Yamaguchi³, H. Tamura³ and T. Akazaki³, ¹Univ. of Tsukuba, ²AIST and ³NTT BRL (Japan)</i> 11:00 H-3-6 KPFM Observation of Quantum Dots Induced by Clustered Donors in Selectively-Doped SOI-FETs <i>K. Tyszcza^{1,2}, D. Moraru¹, T. Mizuno³, R. Jablonski² and M. Tabe¹, ¹Shizuoka Univ. and ²Warsaw Univ. of Tech. (Japan)</i>	J-3: CMOS Platform & SRAM 11:00 J-3-5 (Late News) The Guideline of Si/SiGe Hetero-Junction Design in Parallel Plate Style TFETs (PP-TFETs) for Si CMOS Platform Implementation <i>M. Goto¹, Y. Kondo¹, Y. Morita², S. Migita², A. Hokazono¹, H. Ota², M. Masahara² and S. Kawanaka¹, ¹Toshiba Corp. and ²GNC, AIST (Japan)</i>	K-3: Organic Photovoltaics II 10:45 K-3-5 Property Enhancement of Hole Transport Layer and Transparent Electrode by the Addition of Polar Solvents for Organic Solar Cells <i>D.H. Kim, K.Y. Lee, S.J. Park and Y.J. Kim, Yonsei Univ. (Korea)</i>	M-3: RF and Analog Techniques 11:00 M-3-5 (Late News) On-chip Microparticle Manipulation with Efficient Wireless Power Transfer <i>Y. Dei, Y. Kishiwada, R. Yamane, T. Inoue and T. Matsuoka, Osaka Univ. (Japan)</i>		P-3: Nanowire Electronics 10:45 P-3-5 Comparative Study of Silicon Nanowire Transistors with Triangular-Shaped Cross Sections <i>Y.B. Zhang, L. Sun, H. Xu, Y.Q. Xia, J.W. Han, Y. Wang and S.D. Zhang, Peking Univ. (China)</i> 11:00 P-3-6 Thermal Transport Properties of Si Nanowire Covered with SiO₂ Layer: A Molecular Dynamics Study <i>T. Zushi^{1,3}, K. Ohmori², K. Yamada² and T. Watanabe¹, ¹Waseda Univ., ²Univ. of Tsukuba and ³JSPS Research Fellow (Japan)</i>

Wednesday, September 10

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
A-4: FeRAM/PCRAM (16:30-17:30) Chairs: H. Saito (Fujitsu Semicon.) Y. Sasago (Hitachi)	B-4: Magneto-Optic Devices (16:30-17:45) Chairs: H. MuneKata (Tokyo Tech) H. Oohashi (NTT Electronics)	C-4: Metal Induced Crystallization (16:30-17:30) Chairs: T. Suemasu (Univ. of Tsukuba) T. Iwai (Fujitsu Lab.)	D-4: Neural Interface (16:30-17:45) Chairs: Y. Mita (Univ. of Tokyo) J. Ohta (Nara Inst. of Sci. & Tech.)	E-4: Silicon Carbide Devices (16:30-17:45) Chairs: Y. Tanaka (AIST) R. Hattori (Mitsubishi Electric)	F-4: Metal Contacts and Junction Technologies (16:30-17:40) Chairs: T. Nakayama (Chiba Univ.) S. Migita (AIST)	G-4: III-V and Quantum Photovoltaics (16:30-17:45) Chairs: N. Kojima (Toyota Tech. Inst.) L. -S. Hong (National Taiwan Univ. of Science and Technology)
16:30 A-4-1 10⁸ Endurance Nonvolatile Memory Transistor with 100 nm Metal Gate <i>L.V. Hai, M. Takahashi, W. Zhang and S. Sakai, AIST (Japan)</i>	16:30 B-4-1 (Invited) On-Chip Nonreciprocal Photonic Devices Using Magneto-Optical Oxide Thin Films <i>L. Bi¹, J. Hu², H.S. Kim³, G.F. Dionne³, C.A. Ross³, X. Liang¹, J. Xie¹ and L. Deng¹, ¹Univ. of Electron. Sci. and Tech. of China, ²Univ. of Delaware and ³Mass. Inst. Tech. (China)</i>	16:30 C-4-1 (Invited) Metal-Induced Crystallization - Fundamentals and Applications <i>Z. Wang¹ and E.J. Mittemeijer^{1,2}, ¹Max Planck Inst. for Intelligent Systems and ²Univ. of Stuttgart (Germany)</i>	16:30 D-4-1 (Invited) MEMS Neural Probes by CMOS Technology and Micromachining <i>O. Paul, Univ. of Freiburg (Germany)</i>	16:30 E-4-1 (Invited) The Continuing Evolution of Silicon Carbide Power MOSFETs <i>J.A. Cooper, Purdue Univ. (USA)</i>	16:30 F-4-1 (Invited) Nickel Compound and Alloy Contacts to Nanoscale Si, Ge, and InGaAs Channels <i>R. Chen¹, B.-M. Nguyen^{1,2}, W. Tang^{2,3} and S.A. Dayeh^{1,2}, ¹Univ. of California San Diego, ²Los Alamos National Laboratory and ³Univ. of California Los Angeles (USA)</i>	16:30 G-4-1 (Invited) High Efficiency, Flexible, Thin Film III-V Solar Cell Technology <i>G.S. Higashi, Alta Devices, Inc. (USA)</i>
16:50 A-4-2 Effect of Oxygen Partial Pressure Under Heat Treatment on Ferroelectricity of (Hf_{0.5}Zr_{0.5})O₂ Thin Films <i>H. Funakubo^{1,2}, T. Shimizu¹, T. Yokouchi¹, T. Oikawa¹, T. Shirashi¹, T. Kiguchi¹, A. Akama¹, T.J. Konno³, H. Uchida⁴, D. Kim⁵ and A. Gruverman⁵, ¹Department of Innovative and Engineered Material, Tokyo Tech, ²Materials Reserch Center for Element Strategy, Tokyo Tech, ³Institute for Materials Research, Tohoku Univ., ⁴Department of Materials and Life Sciences, Sophia Univ. and ⁵Department of Physics and Astronomy, Univ. of Nebraska, Lincoln (Japan)</i>	17:00 B-4-2 (Invited) Optical Isolators and Circulators on Si Waveguide Platforms <i>T. Mizumoto and Y. Shoji, Tokyo Tech (Japan)</i>	17:00 C-4-2 Orientation-Controlled Large-Grain SiGe on Flexible Substrate by Nucleation-Controlled Gold-Induced Crystallization <i>J.H. Park^{1,2}, M. Miyao¹ and T. Sadoh¹, ¹Kyushu Univ. and ²JSPS Research Fellow (Japan)</i>	17:00 D-4-2 (Invited) Multi-channel Recording System with UWB Wireless Data Transmitter for Brain-Machine Interface <i>T. Suzuki¹, H. Ando¹, T. Yoshida², M. Hirata^{1,3}, K. Takizawa¹, ¹NICT and Osaka Univ., ²Hiroshima Univ. and ³Osaka Univ. Medical School (Japan)</i>	17:00 E-4-2 3.3-kV Double Channel-Doped SiC Vertical JFET in Cascade Configuration <i>H. Shimizu, S. Akiyama, N. Yokoyama, A. Shima and Y. Shimamoto, Hitachi, Ltd. (Japan)</i>	17:00 F-4-2 NiPt Silicide Agglomeration Caused by Stress Relaxation along <1010> Direction in NiSi Grain <i>M. Mizuo¹, T. Yamaguchi², X. Pages³, K. Vanormelingen⁴, M. Smits⁵, E. Granneman⁵, M. Fujisawa² and N. Hattori¹, ¹Renesas Semiconductor Manufacturing Co., Ltd., ²Renesas Electronics Corp. and ³Levitech BV (Japan)</i>	17:00 G-4-2 Hole Trap Associated with High Background Doping in P-type GaAsN Grown by Chemical Beam Epitaxy <i>O. Elleuch, L. Wang, K. Demizu, K. Ikeda, N. Kojima, Y. Ohshita and M. Yamaguchi, Toyota Tech (Japan)</i>
17:10 A-4-3 A 4F²-cross-point Phase Change Memory Using Nano-crystalline Doped GeSbTe Material <i>T. Morikawa, K. Akita, M. Kinoshita, M. Tai, T. Ohyanagi and N. Takaura, LEAP (Japan)</i>	17:30 B-4-3 Double-Dielectric-Loaded Plasmonic Optical Isolator for Integration into Photonic Integrated Circuits <i>T. Kaihara¹, T. Ando¹, H. Shimizu¹, V. Zayets², H. Saito³, K. Ando² and S. Yuasa², ¹Tokyo Univ. of Agri. Tech. and ²AIST (Japan)</i>	17:15 C-4-3 Metal-Induced Crystallization of Amorphous Ge on Insulators: Comparative Study of Catalytic Effects between Al and Sn <i>N. Oya, K. Toko and T. Suemasu, Univ. of Tsukuba (Japan)</i>	17:30 D-4-3 A Flexible Antenna Using a Parylene Film for Wirelessly-Powered Neural Recording Devices <i>K. Okabe¹, I. Akita¹, S. Asai¹ and M. Ishida^{1,2}, ¹Toyohashi Univ. of Tech. and ²Electronics-Inspired Interdisciplinary Res. Inst. (EIRIS) (Japan)</i>	17:15 E-4-3 Temperature Dependence of Current Gain in 4H-SiC Bipolar Junction Transistors <i>S. Asada, T. Okuda, T. Kimoto and J. Suda, Kyoto Univ. (Japan)</i>	17:20 F-4-3 Reduction of Parasitic Resistance in Ge nMOSFETs with NiGe/n⁺Ge Junctions by Two-step Phosphorus Ion Implantation <i>M. Koike, Y. Kamimuta and T. Tezuka, AIST (Japan)</i>	17:15 G-4-3 Electrical Evaluation of Energy Distribution of State Density for Embedded Quantum Dot Single Layer <i>T. Hoshii and Y. Okada, RCAST, Univ. of Tokyo (Japan)</i>
				17:30 E-4-4 (Late News) 3.3 kV/1500 A Power Modules for the World's First All-SiC Traction Inverter <i>K. Hamada¹, S. Hino^{1,2}, N. Miura¹, H. Watanabe^{1,2}, S. Nakata^{1,2}, E. Suekawa³, Y. Ebiike³, M. Imaizumi³, I. Umezaki³ and S. Yamakawa^{1,2}, ¹Advanced Technology R&D Center, Mitsubishi Electric Corp., ²R&D Partnership for Future Power Electronics Technology (FUPET) and ³Power Device Works, Mitsubishi Electric Corp. (Japan)</i>		17:30 G-4-4 Enhanced Light Absorption in Ge/Si Quantum Dot Solar Cells by Surface Photonic Nanostructures <i>T. Tayagaki¹, Y. Kishimoto¹, Y. Hoshi² and N. Usami², ¹Kyoto Univ. and ²Nagoya Univ. (Japan)</i>

Wednesday, September 10

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
<p>H-4: Novel Devices (16:30-17:30) Chairs: H. Inokawa (Shizuoka Univ.) T. Tanamoto (Toshiba)</p>	<p>J-4: Device Physics (16:30-17:30) Chairs: M. Hane (Renesas Electronics) O. Weber (CEA-LETI)</p>	<p>K-4: Organic Biosensors (16:30-17:45) Chairs: S. Tokito (Yamagata Univ.) K. Shinbo (Niigata Univ.)</p>			<p>P-4: Novel Interconnects (16:30-17:45) Chairs: M. Ueki (Renesas Electronics) D. Kondo (Fujitsu)</p>
<p>16:30 H-4-1 Purcell Effect of THz Emission using Multilayer Photonic Micro-Structures <i>N. Tsurumachi¹, H. Izawa¹, T. Kai¹, T. Kawanaka¹, F. Toyoshima¹, H. Shira², F. Shimokawa¹, H. Miyagawa¹, S. Koshida¹ and S. Nakanishi¹, ¹Kagawa Univ. and ²Inst. of Molecular Science (Japan)</i></p>	<p>16:30 J-4-1 n⁺/p⁺-Single Doping Effects on Impurity Band Structure Modulation in Two Dimensional Si Layers <i>T. Mizuno¹, Y. Nakahara¹, Y. Nagamine¹, Y. Suzuki¹, Y. Nagata¹, T. Aoki¹ and T. Sameshima², ¹Kanagawa Univ. and ²Tokyo Univ. of Agric. and Tech. (Japan)</i></p>	<p>16:30 K-4-1 (Invited) Organic Bioelectronics - regulating cell signalling <i>in vivo</i> and <i>in vivo</i>, towards new therapy methods <i>M. Berggren, D. Simon, K. Tybrandt, E. Gabrielsson, A. Jonsson and D. Nilsson, Linköping Univ. (Sweden)</i></p>			<p>16:30 P-4-1 (Invited) A Possibility of Cross-Bar Wiring in Three-Dimensional Crystallographic Space <i>H.M. Yamamoto, CIMoS, IMS and RIKEN (Japan)</i></p>
<p>16:45 H-4-2 Control of Metal-to-Insulator Phase Transition in VO₂ Thin Films via Interface Engineering <i>T. Yajima, T. Nishimura and A. Toriumi, Univ. of Tokyo (Japan)</i></p>	<p>16:50 J-4-2 Mobility Model for Advanced SOI-MOSFETs Including Back-Gate Contribution <i>H. Zenitani, H. Miyamoto, H. Kikuchi, U. Feldmann, H.J. Mattausch and M. Miura-Mattausch, Hiroshima Univ. (Japan)</i></p>	<p>17:00 K-4-2 An Extended-gate Organic Field-Effect Transistor toward Food Freshness Sensing <i>T. Minamiki^{1,2}, T. Minami^{1,2}, K. Fukuda^{1,2}, D. Kumaki^{1,2} and S. Tokito^{1,2}, ¹Yamagata Univ. and ²Research Center for Organic Electronics (Japan)</i></p>			<p>17:00 P-4-2 (Invited) METAL-CNT CONTACTS <i>P. Wilhite, A.A. Vyas and C.Y. Yang, Santa Clara Univ. (USA)</i></p>
<p>17:00 H-4-3 Impact of Dopant Induced States on Interband Tunneling in Nanoscale pn Junctions <i>H.N. Tan¹, S. Purviyanti^{1,2}, D. Moraru¹, L.T. Anh¹, M. Manoharan³, T. Mizuno¹, H. Mizuta^{3,4}, D. Hartanto² and M. Tabé¹, ¹Shizuoka Univ., ²Univ of Indonesia, ³JAIST and ⁴Univ of Southampton (Japan)</i></p>	<p>17:10 J-4-3 On the Importance of Electron-electron Scattering for Hot-carrier Degradation <i>S. Tyaginov^{1,2}, M. Bina¹, J. Franco³, B. Kaczer² and T. Grasser², ¹Inst. for Microelectronics, TU Wien, ²Ioffe Physical-Technical Inst. and ³imec (Austria)</i></p>	<p>17:15 K-4-3 Detection of Cysteine in Water using an Extended-gate Organic Field Effect Transistor <i>T. Minami, T. Minamiki, K. Fukuda, D. Kumaki and S. Tokito, Yamagata Univ. (Japan)</i></p>			<p>17:30 P-4-3 Resistivity of Graphene Nanowires: Requirements of Quality and Doping for Inter-Connect Applications <i>H. Miyazaki¹, M. Katagiri¹, M. Takahashi¹, Y. Yamazaki¹, D. Nishide¹, T. Matsumoto¹, M. Wada¹, N. Sakuma¹, K. Ueno², R. Matsumoto³, A. Kajita¹ and T. Sakai¹, ¹LEAP, ²Shibaura Inst. of Tech. and ³Tokyo Polytechnic Univ. (Japan)</i></p>
<p>17:15 H-4-4 Resistance Switching Behavior of ZnO Resistive RAM (RRAM) with a Reduced Graphene Oxide capping layer <i>C.L. Lin, W.Y. Chang, Y.L. Huang, T.W. Wang and K.Y. Hung, Feng Chia Univ. (Taiwan)</i></p>		<p>17:30 K-4-4 OTFT Circuit Design for Actuator Driving Control in an Organic Fluid Pump <i>L. Chen, T.K. Maiti, H. Miyamoto, M. Miura-Mattausch and H.J. Mattausch, Hiroshima Univ. (Japan)</i></p>			

POSTER SESSION

(14:00-16:00, Multi-Purpose Hall and 102)

Area 1: Advanced LSI Processing & Materials Science

(15 papers)

PS-1-1

High Mobility Ultrathin GeSn (111) pMOSFETs by Solid Phase Epitaxy
T. Maeda¹, W. Jevasuwan¹, H. Hattori¹, N. Uchida¹, S. Miura², M. Tanaka², J.P. Locquet³ and R. Lieten^{3,4,5}, ¹AIST, ²Yokohama National Univ., ³KU Leuven, ⁴IMEC and ⁵Entegris (Japan)

PS-1-2

Electrically Active Defects in GeSnSi/Ge Junctions Formed at Low Temperature
N. Taoka^{1,2}, T. Asano², T. Yamaha², T. Terashima², S. Asaba², O. Nakatsuka², P. Zaumseil¹, G. Capellini¹, T. Schroeder¹ and S. Zaima², ¹IHP and ²Nagoya Univ. (Germany)

PS-1-3

Effect of Kr/O₂ Mixed ECR Plasma Oxidation on Electrical Properties of Al₂O₃/Ge Gate Stacks Fabricated by ALD
Y. Nagatomi, Y. Nagaoka, K. Yamamoto, D. Wang and H. Nakashima, Kyushu Univ. (Japan)

PS-1-4

High-k/Ge Interface Passivation Using Cycling Ozone Oxidation
X. Yang^{1,2}, S.K. Wang¹, L. Han^{1,2}, X. Zhang², B. Sun¹, H.D. Chang¹, W. Zhao¹, Z.H. Zeng^{1,2}, H.G. Liu¹ and Y.P. Cu², ¹Inst. of Microelectronics of Chinese Academy of Science and ²Univ. of Southeast (China)

PS-1-5

Flexible Silicon-Germanium Devices With High-k/Metal Gate Stacks For Next Generation High Hole Mobility Channel Devices
J.M. Nassar, A.M. Hussain, J.P. Rojas and M.M. Hussain, King Abdullah Univ. of Science and Technology (KAUST) (Saudi Arabia)

PS-1-6

Transformation of Holes Emission Paths under Negative Bias Temperature Stress in Deeply Scaled pMOSFETs
Y. Liao¹, X. Ji¹, Q. Guo² and F. Yan¹, ¹Nanjing Univ. and ²Wuhan Xinxin Semiconductor Manufac. Company (China)

PS-1-7

Thickness Dependences of Stress, Poisson's Ratio and Longitudinal Optical Phonon Lifetime in Ultrathin Strained-Silicon-on-Insulator
V. Poborchii, M. Hara and T. Tada, AIST (Japan)

PS-1-8

Assessment of Self Heating Effect (SHE) on Negative Bias Temperature Instability in SOI FinFETs under Circuit Operation
H. Jiang, Z.Y. Lun, B. Chen, G. Du, X.Y. Liu and X. Zhang, Peking Univ. (China)

PS-1-9

The Impact of Positive Bias Temperature Instabilities on Stacked High-k/Metal Gate Transistor with TiN Barrier Layer
D.C. Huang¹, J. Gong², C.F. Huang¹ and S.S. Chung³, ¹National Tsing Hua Univ., ²Tunghai Univ. and ³NCTU (Taiwan)

PS-1-10

Recovery of Interface States Generated by Hot-Carrier Stress
Y. Yamamoto, Hitachi, Ltd. (Japan)

PS-1-11

Reliability of Polycrystalline HfO₂ Thin Films Directly Bonded to Si Substrates
R. Hasunuma, Y. Tomura and K. Yamabe, Univ. of Tsukuba (Japan)

PS-1-12 (Late News)

Fabrication of High Performance Single-Crystalline Silicon Thin Film Transistors on a Polyethylene Terephthalate Substrate
K. Sakaike¹, M. Akazawa¹, A. Nakagawa¹ and S. Higashi^{1,2}, ¹Dept. of Semiconductor Electronics and Integration Science, Graduate School of Advanced Sciences of Matter, Hiroshima Univ. and ²Research Inst. for Nanodevice and Bio Systems, Hiroshima Univ. (Japan)

PS-1-13 (Late News)

Toward 1-nm-EOT Hf_{0.5}Zr_{0.5}O₂ Ferroelectric Films
T. Nishimura, T. Yajima, K. Nagashio and A. Toriumi, Univ. of Tokyo (Japan)

PS-1-14 (Late News)

Si-substrate-based High Mobility Ge-pMOSFETs Using Ozone Passivated Al₂O₃/GeO₂ Gate Dielectric
S.K. Wang¹, X. Yang^{1,2}, Z. Gong¹, R. Liang³, B. Sun¹, W. Zhao¹, H. Chang¹, J. Wang³ and H.G. Liu¹, ¹Inst. of Microelectronics of Chinese Academy of Sci., ²Southeast Univ. and ³Tsinghua Univ. (China)

PS-1-15 (Late News)

Properties of Ultrathin Body Condensation GOI Films Thinned by Additional Thermal Oxidation
W.K. Kim^{1,2}, M. Takenaka^{1,2} and S. Takagi^{1,2}, ¹Univ. of Tokyo and ²JST-CREST (Japan)

Area 2: Advanced Interconnect and 3D Integration/ Materials and Characterization

(4 papers)

PS-2-1

Joule Heating Induced Bonding Interface Improvement and Ti Breakthrough by Electron Bombardment for 40- μ m Pitch of Cu TSV and Cu/Sn μ -Bump Pair
Y.J. Chang¹, Y.S. Hsieh¹, C.T. Ko^{1,2}, W.C. Lo², F.Y. Ouyang², C.S. Wu⁴, Y.M. Cheng⁴, W.J. Chen⁴ and K.N. Chen¹, ¹NCTU, ²Electronics and Optoelectronics Res. Lab., ITRI, ³Department of Engineering and System Science, National Hsing Hua Univ. and ⁴Metal Industries R&D Centre (Taiwan)

PS-2-2

Influence of Lateral Stress on Interdiffusion in Thin Cr/Au Film
J. He, X. Huang, L. Zhang, D. Zhao, W. Hu and D. Zhang, Peking Univ. (China)

PS-2-3

Measurement on Interfacial Adhesion Property of Low-k Thin Film by the Surface Acoustic Waves Using the Cohesion Zone Model
X. Xiaoa¹, Y. Tao¹ and T. Kikkawa², ¹Univ. of Tianjin and ²Hiroshima Univ. (China)

PS-2-4 (Late News)

Vacuum Ultraviolet (VUV) / Vapor-Assisted Bonding for Organic / Inorganic Hybrid Integration
A. Shigetou¹, M. Ajayan^{1,2}, J. Mizuno² and S. Shuichi², ¹National Inst. for Mater. Sci. and ²Waseda Univ. (Japan)

Area 3: CMOS Devices / Device Physics

(12 papers)

PS-3-1

Extraction of Source/Drain Series Resistance Components Optimized for Double-gate FinFETs.
J.-S. Yoon, E.-Y. Jeong, S.-H. Lee, Y.-R. Kim, J.-H. Hong, J.-S. Lee and Y.-H. Jeong, Pohang Univ. of Sci. and Tech. (Korea)

PS-3-2

Impact of Surface Oxide Layer on Band Structure Modulation in Si Quantum Well Structures
T. Mizuno¹, Y. Suzuki¹, M. Yamanaka¹, Y. Nagamine¹, Y. Nakahara¹, Y. Nagata¹, T. Aoki¹ and T. Maeda¹, ¹Kanagawa Univ. and ²AIST (Japan)

PS-3-3

Strain Effects on Monolayer MoS₂ Field Effect Transistors
L. Zeng¹, Z. Xin², P.Y. Chang² and X.Y. Liu¹, ¹Inst. of Microelectronics, Peking Univ. and ²School of Electronic and Computer Engineering, Peking Univ. (China)

PS-3-4

Impact of Trap Behavior in High-k/Metal Gate p-MOSFET with Incorporated Fluorine on Low-Frequency Noise Characteristics
T.-H. Kao¹, S.-L. Wu², C.-Y. Wu², Y.-K. Fang¹, P.-C. Huang¹, C.-M. Lai³, C.-W. Hsu³, Y.-W. Chen³, O. Cheng³ and S.-J. Chang¹, ¹National Cheng Kung Univ., ²Cheng Shiu Univ. and ³United Microelectronics Corp. (Taiwan)

PS-3-5

Initial and Long-Term Frequency Degradation on Ring Oscillators from Plasma Induced Damage in 65 nm Bulk and Silicon On Thin BOX Processes
R. Kishida, A. Oshima, M. Yabuuchi and K. Kobayashi, Kyoto Inst. of Tech. (Japan)

PS-3-6

Gate Voltage Dependent 1/f Noise Variance Model in n-Channel MOSFETs
Y. Arai, H. Aoki, F. Abe, S. Todoroki, R. Khatami, M. Kazumi, T. Totsuka, T. Wang and H. Kobayashi, Gunma Univ. (Japan)

PS-3-7

Electrical Characteristics of Novel Junctionless FinFET Utilizing Trench Structure for Extreme Scaling
M.-S. Yeh, Y.-C. Wu, M.-H. Wu, Y.-R. Jhan and M.-H. Chung, National Tsing Hua Univ. (Taiwan)

PS-3-8

Dopant Drive-in Path Analysis in Poly-Silicon Filled in Trench Type 3D-MOSFET using Atom Probe Tomography
K. Inoue¹, H. Takamizawa¹, Y. Shimizu¹, B. Han¹, Y. Nagai¹, F. Yano², Y. Kunimune³, M. Inoue⁴ and A. Nishida⁴, ¹Tohoku Univ., ²Tokyo City Univ., ³Renesas Semiconductor Manufacturing Co., Ltd. and ⁴Renesas Electronics Corp. (Japan)

PS-3-9

High Performance Germanium n⁺/p Shallow Junction for the Scaled nMOSFET
C. Wang, C. Li, W. Huang, S.Y. Chen and H.K. Lai, Xiamen Univ. (China)

PS-3-10

Investigation of Low-Frequency Noise in High-k First/Metal Gate Last HfO₂ and ZrO₂ nMOSFETs
S.L. Wu¹, B.C. Wang², Y.Y. Lu¹, S.C. Tsai², J.F. Chen², S.J. Chang^{2,3}, S.P. Chang^{2,3}, C.H. Hsu⁴, C.W. Yang⁴, C.G. Chen¹, O. Cheng⁴ and P.C. Huang^{2,3}, ¹Cheng Shiu Univ., ²Inst. of Microelectronics and Department of Electrical Engineering, National Cheng Kung Univ., ³Advanced Optoelectronic Tech. Center, National Cheng Kung Univ. and ⁴United Microelectronics Corp. (Taiwan)

PS-3-11

New Concept of Planar Germanium MOSFET with Stacked Germanide Layers at Source/Drain
H. Xu, L. Sun, Y.-B. Zhang, Y.-Q. Xia, J.-W. Han, Y. Wang and S.-D. Zhang, Peking Univ. (China)

PS-3-12

Physical DC and Thermal Noise Models of 18 nm DG Junctionless pMOSFETs
E.-Y. Jeong¹, M.J. Deen², C.-H. Chen², R.-H. Beak³, J.-S. Lee¹ and Y.-H. Jeong¹, ¹Pohang Univ. of Sci. and Tech., ²McMaster Univ. and ³SEMATECH (Korea)

Area 4: Advanced Memory Technology

(13 papers)

PS-4-1

The Impact of Inserted Ta Ultra-thin Layer on the Resistive Switching Voltage in Ir/Ti/Ta/HfO₂/TiN/Ti/SiO₂/Si Devices
S. Asanuma, H. Shima, M. Yamazaki, N. Hata and H. Akinaga, AIST (Japan)

PS-4-2

A Possible Bipolar HfO₂ Resistive Memory Device with Self-Rectification - Observations from STM Study
Y. Zhou, K.S. Yew and D.S. Ang, Nanyang Tech. Univ. (Singapore)

PS-4-3

Rectifying Characteristics of Sol-gel derived TiO₂ thin films for 1D-1R Resistance Switching Memory Applications
J.H. Kim, K.H. Nam, T.J. Ha, W.J. Cho and H.B. Chung, Kwangwoon Univ. (Korea)

PS-4-4

Scanning Tunneling Microscopy Study of the Bipolar Resistance Switching Characteristics of Nanoscopic Conductive Filament for HfO₂-based MIM stack
K.S. Yew, Y. Zhou and D.S. Ang, Nanyang Tech. Univ. (Singapore)

PS-4-5

La/Al-doped ZrO₂ Thin-Film Resistive Random Access Memory Devices by Sol-gel Method for Transparent Solid-State Circuit Systems
Y.R. Wang¹, B. Chen¹, B. Gao¹, L.F. Liu¹ and J.F. Kang¹, Peking Univ. (China)

PS-4-6

Improvement of Unipolar Resistive Switching by N₂ Annealing in Ni/ZrO₂/TaN Memory Device
T.L. Tsai, T.H. Ho and T.Y. Tseng, NCTU (Taiwan)

PS-4-7

Switching Properties in ZrO₂-Based Resistive Switching Device
U. Chand, C.-Y. Huang, J.S. Meena and T.-Y. Tseng, NCTU (Taiwan)

PS-4-8

A Measurement of Ratio-less 12-transistor SRAM cell Operation at Ultra-low Supply-voltage
T. Kondo, H. Yamamoto, H. Imi, H. Okamura and K. Nakamura, Kyushu Inst. of Tech. (Japan)

PS-4-9

Enhanced Erasing Performance of Ω -Gate P-Channel Junctionless Fin-FET SONOS Nonvolatile Memory
M.S. Yeh, Y.C. Wu, M.H. Chung, Y.R. Jhan and M.H. Wu, National Tsing Hua Univ. (Taiwan)

PS-4-10

Stochastic Model for SPICE simulation about Resistance Distribution of Magnetic Tunnel Junction
G.H. Kil¹, J.T. Choi¹, C.M. Choi¹, H. Sukegawa², S. Mitani² and Y.H. Song¹, ¹Hanyang Univ. and ²NIMS (Korea)

PS-4-11

Reliability Modeling of Magnetic Tunnel Junction using MgO Barrier
J.M. Lee¹, C.M. Choi¹, Y.T. Oh¹, H. Sukegawa², S. Mitani² and Y.H. Song¹, ¹Hanyang Univ. and ²NIMS (Korea)

PS-4-12 (Late News)

Find Filament in ReRAM using Thermal Analysis
M. Uenuma, I. Yamashita and Y. Uraoka, NAIST (Japan)

PS-4-13 (Late News)

Multilevel Storage and its Cycling in Ge₁Sb₁Te₂ Phase-Change Memory
Y. Yin¹, S. Iwashita² and S. Hosaka¹, ¹Divi. of Electronics and Informatics, Gunma Univ. and ²Dept. Production of Science and Technology, Gunma Univ. (Japan)

Area 5: Advanced Circuits and Systems

(13 papers)

PS-5-1

A Characterization Method of On-Chip Tee-Junction for Millimeter-Wave CMOS Circuit Design
K.K. Tokgoz, N. Fajri, Y. Seo, S. Kawai, K. Okada and A. Matsuzawa, Tokyo Tech (Japan)

PS-5-2

Diode Modeling with Lossy Nonlinear Capacitance Model
R. Nahara, K. Katayama, K. Takano, S. Amakawa, T. Yoshida and M. Fujishima, Univ. of Hiroshima (Japan)

PS-5-3

A Comprehensive Modeling of Skin and Proximity Effects for mm-wave Inductors Simulation and Design in Nanoscale CMOS Technology
J.C. Guo and R.J. Chan, NCTU (Taiwan)

PS-5-4

A Novel Electromechanical Model of a MEMS Energy Harvesting Device for a Multi-physics Simulation Platform on a Circuit Simulator
T. Konishi¹, T. Matsushima¹, D. Yamane², K. Masu², H. Toshiyoshi³ and K. Machida^{1,2}, ¹NTT Advanced Tech. Corp., ²Tokyo Tech and ³Univ. of Tokyo (Japan)

PS-5-5

SoC Realization of LVQ Neural Network with On-chip Learning and Recognition
F. An, T. Akazawa, S. Yamazaki, L. Chen and H.J. Mattausch, Hiroshima Univ. (Japan)

PS-5-6

Digital Word-Parallel Low-Power Recognition SoC for Mobile Equipment Based on Nearest Euclidean Distance Search and KNN Classification
S. Yamasaki, T. Akazawa, F. An and H.J. Mattausch, Univ. of Hiroshima (Japan)

PS-5-7

Design Guidelines of All Storage Class Memory (SCM) SSD and Hybrid SCM/NAND Flash SSD to Balance Performance, Power, Endurance and Cost
T. Onagi¹, C. Sun^{1,2} and K. Takeuchi¹, ¹Chuo Univ. and ²Univ. of Tokyo (Japan)

PS-5-8

A High-frequency Level-up Shifter Based on 0.18 μ m Vertical MOSFETs with More than 70% Reduction of Overshoot-voltage Above VDD
S. Tanoi^{1,2} and T. Endoh^{1,2}, ¹Tohoku Univ. and ²ACCEL, JST (Japan)

PS-5-9

Dynamically Reconfigurable Non-Volatile Multi-Context FPGA with CAAC-OS-based Programmable Routing Switches
N. Bjorklund^{1,2}, Y. Okamoto¹, T. Aoki¹, M. Kozuma¹, Y. Kurokawa¹, T. Ikeda¹, N. Yamada¹, Y. Okazaki¹, H. Miyairi¹, M. Fujita³ and S. Yamazaki¹, ¹Semiconductor Energy Lab. Co., Ltd., ²Linkoping Univ. and ³Univ. of Tokyo (Japan)

PS-5-10

A Dual-Mode Active Pixel Sensor for Low-Light-Level Detection Using a Hybrid Photodetector
S. Lee, S.H. Jo, M. Bae, B.S. Choi and J.K. Shin, Kyungpook National Univ. (Korea)

PS-5-11

Multichannel Capacitance to Voltage Converter for Pressure Sensor Front-end
R. Kuguminato¹, T. Matsuda¹, K. Izumi¹, H. Iwata¹, M. Mizushima² and T. Obata³, ¹Toyama Pref. Univ., ²Oga Inc. and ³Toyama Industrial Technology Center (Japan)

PS-5-12

Pulse-Output Readout Circuit with Temperature Compensation for a Temperature-Dependent Input Voltage
R.L. Wang¹, C. Yu¹, W.D. Wu¹, Y.F. Hao¹, J.L. Shi¹, H.H. Liao², H.H. Tsai² and Y.Z. Juang², ¹National Kaohsiung Normal Univ. and ²National Chip Implementation Center, National Applied Research Lab. (Taiwan)

PS-5-13 (Late News)

Studies on Response Speed and Sensitivity of Two-Dimensional Integrated Magnetic Sensor
T. Kimura, K. Uno and T. Masuzawa, Ibaraki Univ. (Japan)

Area 6: Compound Semiconductor Electron Devices & Related Technologies

(18 papers)

PS-6-1

Comparison of Power Gain Performance between Conventional and Independently Biased HBT Cascode Chips
D.M. Luong, K. Honjo, Y. Takayama and R. Ishikawa, Univ. of Electro-Communications (Japan)

PS-6-2

Fluorinated Al₂O₃ Gate Dielectric Engineering on GaSb MOS Devices
Z.H. Zeng^{1,2}, B. Sun¹, H.D. Chang¹, W. Zhao¹, X. Yang^{1,2}, S.K. Wang¹, X. Zhang², Y.P. Cui² and H.G. Liu¹, ¹Inst. of Microelectronics of Chinese Academy of Sciences and ²Southeast Univ. (China)

PS-6-3

InGaSb Buried-Channel pMOSFET Fabricated by Using Digital Etch Technique
B. Sun¹, Z.H. Zeng^{1,3}, H.D. Chang¹, S.K. Wang¹, W.X. Wang² and H.G. Liu¹, ¹Inst. of Microelectronics of Chinese Academy of Sciences, ²Inst. of Physics, Chinese Academy of Sciences and ³Southeast Univ. (China)

PS-6-4

Characterization of GaAs Surface State by Hard X-ray Photoemission Spectroscopy
Y. Saito, J. Ihara, T. Yonemura, K. Yamaguchi and D. Tsurumi, Sumitomo Electric Industries, Ltd. (Japan)

PS-6-5

High-frequency Performance In_{0.49}Ga_{0.51}P/In_{0.4}Ga_{0.6}As MOSFET
J.H. Zhou^{1,2}, H.D. Chang², G.M. Liu², H.O. Li¹ and H.G. Liu², ¹Guangxi Experiment Center of Info. Sci., Guilin Univ. of Electronic Tech. and ²Microwave Device and IC Department, Inst. of Microelectronics of Chinese Academy of Sciences (China)

PS-6-6

Reduction of Initial Threshold Voltage Shift in ALD-Al₂O₃/AlGaIn/GaN MIS-HEMTs on Si Substrates by Post-deposition Annealing
T. Kubo, J. Freedman, Y. Yoshida and T. Egawa, Nagoya Inst. of Tech. (Japan)

PS-6-7

Observation of Drain Current Instability on p-GaN Gate AlGaIn/GaN HEMTs
T.F. Chang¹, T.C. Hsiao¹, C.F. Huang¹, C.W. Chiu², T.Y. Yang², T.Y. Huang², Y.C. Liang² and G. Samudra³, ¹Nat'l Tsing Hua Univ., ²Richtek Tech. Corp. and ³Nat'l Univ. of Singapore (Taiwan)

PS-6-8

Study of HfO₂/AlGaIn/GaN MOS-HEMT for High Power Application
W.C. Lan¹, P.C. Chin¹, Y.C. Lin², J.S. Maa³ and E.Y. Chang^{2,4}, ¹Inst. of Photonic System, NCTU, ²Inst. of Materials Sci. and Eng., NCTU, ³Inst. of Lighting and Energy Photonics NCTU and ⁴Inst. of Electronics Engineering, NCTU (Taiwan)

PS-6-9

Electrical Characteristic Simulation of Novel AlGaIn/GaN Vertical HEMT with Multi-Aperture and SiO₂ Current Blocking Layer
N.M. Shrestha, Y.Y. Wang, Y. Li and E.Y. Chang, NCTU (Taiwan)

PS-6-10

Reduction in Mobility Difference between C-Axis-Aligned Crystalline IGZO-FET and Si-FET by Miniaturization
S. Matsuda, Y. Yamane, Y. Okazaki, T. Ishizu, Y. Kobayashi, H. Suzawa, A. Isobe and S. Yamazaki, Semiconductor Energy Laboratory Co., Ltd. (Japan)

PS-6-11

Fabrication and Characteristics of Fully-Transparent Al-Sn-Zn-O TFTs Fabricated on Glass at Low Temperature
Y.Y. Cong¹, D.D. Han¹, J. Wu^{1,2}, N.N. Zhao^{1,2}, Z.F. Chen^{1,2}, F.L. Zhao^{1,2}, J.C. Dong^{1,2}, S.D. Zhang², X. Zhang¹ and Y. Wang¹, ¹Inst. of Microelectronics, Peking Univ. and ²Shenzhen Graduate School, Peking Univ. (China)

PS-6-12

Characteristics of Submicron Indium-Tin-Oxide Thin-Film Transistors Fabricated by Film Profile Engineering
Y.A. Huang¹, H.C. Lin^{1,2} and T.Y. Huang¹, NCTU and ²National Nano Device Labs. (Taiwan)

PS-6-13

Fabrication of High Performance Ultra-thin body SnO₂ Thin-Film-Transistors (TFTs) using Microwave Annealing
S.W. Moon, H.J. Jang and W.J. Cho, Department of Electronic Materials Eng, Kwangwoon Univ. (Korea)

PS-6-14

Fully Transparent Dual-active-layer ITO/TZO TFT Fabricated on Glass Substrate at low-temperature
Z.F. Chen^{1,2}, D.D. Han², N.N. Zhao^{1,2}, J. Wu^{1,2}, Y.Y. Cong², J.C. Dong^{1,2}, F.L. Zhao^{1,2}, S.D. Zhang^{1,2}, X. Zhang^{1,2}, Y. Wang² and L.F. Liu², ¹Shenzhen Graduate School, Peking Univ. and ²Inst. of Microelectronics, Peking Univ. (China)

PS-6-15

A Comparison of Photo-Induced Hysteresis between Hydrogenated Amorphous Silicon and Amorphous IGZO Thin-Film Transistors
T.J. Ha, J.H. Kim, W.J. Cho and H.B. Chung, Kwangwoon Univ. (Korea)

PS-6-16 (Late News)

Ideal transport characteristics of Schottky contacts on AlGaIn/GaN structure grown on free-standing Si-GaN substrate
T. Nanjo, K. Kurahashi, M. Tanaka, A. Kiyoi, A. Imai, M. Suita, Y. Suzuki, T. Tanaka and E. Yagyu, Mitsubishi Electric Corp. (Japan)

PS-6-17 (Late News)

Physical Mechanism of Source and Drain Resistance Reduction in Oxide TFT ~Towards High-Performance Short-Channel InGaZnO TFT~
K. Ota, K. Sakuma, T. Irisawa, C. Tanaka, D. Matsushita and M. Saitoh, Toshiba Corp. (Japan)

PS-6-18 (Late News)

The reading operation of quantum dot memory devices using photocurrent detection in strain relaxation InAs quantum dots
J.-F. Wang, C.-L. Lin, S.-S. Pan, C.-P. Huang, C.-S. Hsieh and J.-F. Chen, National Chiao Tung Univ. (Taiwan)

Area 7: Photonic Devices and Related Technologies

(14 papers)

PS-7-1

Structure Dependence of over 10 GHz Lateral Si-PIN Photodiode Fabricated by CMOS Compatible Process
G. Li, K. Maekita, T. Maruyama and K. Iiyama, Kanazawa Univ. (Japan)

PS-7-2

A Silicon Schottky Photodetector Made Directly on a Silicon Fiber
Y.P. Huang, S.H. Chen and L.A. Wang, National Taiwan Univ. (Taiwan)

PS-7-3

A Novel Method of Fabricating Silicon Microsphere Resonators for High Quality-Factor Whispering-Gallery-Mode Generation
C.A. Lin, J.H. Chen and L.A. Wang, National Taiwan Univ. (Taiwan)

PS-7-4

All-Optical-Gate-Type Mode-Locked Few-Picosecond Pulsed Laser with Externally Injected, Weakly Modulated Optical Seed
K. Nagahiro, T. Nakane, H. Itagaki, T. Shibuya, K. Hirai and Y. Ueno, Univ. of Electro-Communications (Japan)

PS-7-5

Modes Selection in a Semiconductor Circular Ring Laser Diode by Perturbation at the Active Soliton Cavity
M.C. Shih, C.L. Yen, J.Z. Luo and W.H. Lan, National Univ. of Kaohsiung (Taiwan)

PS-7-6

Ge/Si/Ge Potential Barrier Structure for Bolometer in Uncooled Infrared Image Sensor
J. Takarada, T. Oda and A. Furukawa, Tokyo Univ. of Sci. (Japan)

PS-7-7

GaAs/AlAs Triple-Coupled Cavity with InAs Quantum Dots for an Ultrafast Wavelength Conversion Device via the Four-Wave-Mixing
M. Ogarane¹, Y. Yasunaga¹, Y. Nakagawa^{1,2}, K. Morita^{1,3}, T. Kitada¹ and T. Isu¹, ¹Univ. of Tokushima, ²NICHIA Corp. and ³Chiba Univ. (Japan)

PS-7-8

The Improvement of Surface Current of 2.6 μm InGaAs Photodetectors by Using ICPCVD Technology
X. Ji¹, B. Liu¹, H. Tang², X. Li², M. Shi², Y. Zhou¹, Y. Xu¹, H. Gong² and F. Yan¹, ¹Nanjing Univ. and ²Chinese Academy of Sci. (China)

PS-7-9

GaN Metal-Insulator-Semiconductor Ultraviolet Photodetectors with a Magnesium Fluoride Insulator
C.H. Chen, W.C. Lin and J.F. He, Cheng Shiu Univ. (Taiwan)

PS-7-10

Optical Property of Triangle-Shaped GaN Microdisk Array with Triangular Lattice
S. Suzuki¹, T. Kouno¹, M. Sakai², K. Kishino³ and K. Harai¹, ¹Shizuoka Univ., ²Univ. of Yamanashi and ³Sophia Univ. (Japan)

PS-7-11

Hydrothermal Growth of Quasi-Crystalline ZnO Thin Films and Theirs Application in Ultraviolet Photodetectors
Y.C. Tu¹, S.J. Wang¹, R.W. Wu¹, T.C. Tsai¹, T.H. Lin¹, C.H. Hung¹, K.M. Uang² and T.M. Cheng², ¹National Cheng Kung Univ. and ²WuFeng Univ. (Taiwan)

PS-7-12

High Pockel's Coefficient for Poled Polymer in Multilayered Electro-Optical Device
Y. Jouane¹, Y.C. Chang¹, D. Zhang¹, A.K.Y. Jen² and Y. Enami¹, ¹Kochi Univ. of Tech. and ²Univ. of Washington (Japan)

PS-7-13

Electro-Optic Polymer/TiO₂ Slot Waveguide Modulators Driven with Low Half-Wave Voltage
Y. Enami¹, Y. Jouane¹, D. Zhang¹, Y.C. Chang¹, J. Luo² and A.K.Y. Jen², ¹Kochi Univ. of Tech. and ²Univ. of Washington (Japan)

PS-7-14

Scaling Study of Antenna-Coupled Microbolometer
A. Tiwari¹, H. Satoh¹, M. Aoki², M. Takeda², N. Hiramoto² and H. Inokawa¹, ¹Research Institute of Electronics, Shizuoka Univ. and ²Graduate School of Engineering, Shizuoka Univ. (Japan)

Area 8: Advanced Material Synthesis and Crystal Growth Technology (18 papers)

PS-8-1

Morphological and Structural Observation of Ni and Fe Clusters on SrTiO₃ (001) and (110) surfaces
M. Tanaka, NIMS (Japan)

PS-8-2

Growth and Optical Properties of GaSb/GaAs type-II Quantum Dots with and without Wetting Layer
T. Kawazu¹, T. Noda¹, M. Mano¹, Y. Sakuma¹ and H. Sakaki^{1,2}, ¹NIMS and ²Toyota Tech. Inst. (Japan)

PS-8-3

Low-temperature Formation of nc-Si in SiO₂ by Soft X-ray Irradiation
F. Kusakabe¹, S. Hirano¹, A. Heya¹, N. Matsuo¹, K. Kanda², T. Mchizuki², K. Kohama³ and K. Ito³, ¹Univ. of Hyogo, ²LASTI, Univ. of Hyogo and ³Osaka Univ. (Japan)

PS-8-4

Soft X-ray Crystallization of Si_{1-x}Ge_x Multilayer Films
A. Heya¹, F. Kusakabe¹, N. Matsuo¹, K. Kanda², T. Motizuki², M. Takahashi³ and K. Ito³, ¹Univ. of Hyogo, ²LASTI, Univ. of Hyogo and ³Osaka Univ. (Japan)

PS-8-5 (Late News)

A self-aligned Ge/SiO₂/Si_{0.4}Ge_{0.6} gate-stacking heterostructure generated in a single fabrication step
W.-T. Lai¹, K.-C. Yang¹, T.-C. Hsu¹, P.-H. Liao¹, T. George² and P.-W. Li¹, ¹National Central Univ. and ²Private Consultant (Taiwan)

PS-8-6

Synthesis, Characterization and Carrier Transport Properties of Crystalline Ge Nanowires Growth with Ag-Based Catalysts
R. C. Gouveia^{1,2}, H. Kamimura¹, A. G. Rodrigues¹ and A. J. Chiquito¹, ¹Federal Univ. of São Carlos and ²Instituto Federal de Educação Ciência e Tecnologia de São Paulo (Brazil)

PS-8-7

Evolution of TiO₂ Nanostructures from Nucleation to Nanorods by Hydrothermal Growth Method
Y.C. Huang¹, R.M. Ko², S.J. Wang¹ and Y.R. Lin³, ¹Department of Electrical Engineering, National Cheng Kung Univ., ²Advanced Optoelectronic Tech. Center, National Cheng Kung Univ. and ³Ming Chi Univ. of Tech. (Taiwan)

PS-8-8

High Electron Mobility, Low Carrier Concentration of Hydrothermally Grown ZnO Thin Films on Seeded a-Plane Sapphire at Low Temperature
N.A. Jayah¹, H. Yahaya¹, M.R. Mahmood², T. Terasako³, K. Yasui⁴ and A.M. Hashim¹, ¹Univ. Teknologi Malaysia, ²Univ. Teknologi MARA, ³Ehime Univ. and ⁴Nagaoka Univ. of Tech. (Malaysia)

PS-8-9
Growth of V-doped ZnO Thin Films with Two-layer Structure on α -Al₂O₃ by RF Magnetron Sputtering
H. Chiba, T. Kawashima and K. Washio, Tohoku Univ. (Japan)

PS-8-10
Effects of Annealing on In-Ga-Zn-Oxide Films
K. Okazaki¹, H. Kanemura¹, Y. Hosaka¹, T. Obonai¹, M. Oota², M. Takahashi², S. Nishino² and S. Yamazaki², ¹Advanced Film Device Inc. and ²Semiconductor Energy Lab. Co., Ltd. (Japan)

PS-8-11
Synthesis, Microstructure, Optical and Magnetic Properties of Ge-doped CuFeO₂ Delafossite Oxide
T. Kamwanna, L. Naka-in, P. Srepusharawoot, S. Pinitsoontorn and V. Amornkitbamrung, Khon Kaen Univ. (Thailand)

PS-8-12
(001) Orientation Single Crystalline PZT Pyroelectric Nanorod Array Synthesized by Hydrothermal Reaction
C.G. Wu, Q.X. Peng, J. Meng, X.Y. Sun, Y. Shuai, J.Q. Cao, W.B. Luo and W.L. Zhang, Univ. of Electronic Sci. and Tech. of China (China)

PS-8-13
Enhancement of Pyroelectric PZT Thick Film Sintered at Low Temperature on Pt-Si Substrate by Adding Pb₂Ge₃O₁₁
C.G. Wu, Q.X. Peng, J. Meng, X.Y. Sun, Y. Shuai, J.Q. Cao, W.B. Luo and W.L. Zhang, Univ. of Electronic Sci. and Tech. of China (China)

PS-8-14
Effects of Pr Doping on the Scintillation Properties of CeBr₃ Crystals Grown by the Modified Micro-Pulling-Down Method
T. Ito¹, Y. Yokota², S. Kurosawa^{1,2}, K. Kamada^{2,3}, J. Pejchal^{2,4}, Y. Ohashi¹ and A. Yoshikawa^{1,2,3}, ¹IMR, Tohoku Univ., ²NICHE, Tohoku Univ., ³C&A Corp. and ⁴Inst. of Phys. AS CR (Japan)

PS-8-15
LiF/CaF₂/LiBaF₃ Ternary Fluoride Eutectic Scintillator
K. Hishinuma¹, K. Kamada^{2,3}, S. Kurosawa^{1,2}, A. Yamaji¹, J. Pejchal^{2,4}, Y. Yokota², Y. Ohashi¹ and A. Yoshikawa^{1,2,3}, ¹IMR, Tohoku Univ., ²NICHE, Tohoku Univ., ³C&A Corp. and ⁴Inst. of Phys. AS CR, Cukrovarnicka (Japan)

PS-8-16
Improvement of Scintillation Properties on Ce doped Y₃Al₅O₁₂ scintillator by divalent cations co-doping
K. Kamada^{1,2}, A. Nagura³, M. Nikl⁴, S. Kurosawa³, J. Pejchal^{1,4}, Y. Ohashi³, Y. Yokota¹ and A. Yoshikawa^{1,2,3}, ¹NICHE, Tohoku Univ., ²C&A Corp., ³IMR, Tohoku Univ. and ⁴Inst. of Phys. AS CR (Japan)

PS-8-17
Electrical Transport Properties in Ternary NbMoS₂ Layer crystals
H.P. Hsu¹, R.S. Chen², Y.H. Huang², C.C. Pung² and Y.S. Huang², ¹Ming Chi Univ. of Tech. and ²National Taiwan Univ. of Sci. and Tech. (Taiwan)

PS-8-18
Behavior of Focused Ga⁺ Beam Spot Milling and its Superimposition Propertey
H.M. Chen¹, P.J. Wu², K.Y. Shen¹ and C.H. Kuan^{1,2}, ¹Graduate Inst. of Electronics Engineering, National Taiwan Univ. and ²Graduate Inst. of Biomedical Electronics and Bioinformatics, National Taiwan Univ. (Taiwan)

Area 9: Physics and Applications of Novel Functional Devices and Materials (12 papers)

PS-9-1
Analysis of Single- and Double-barrier Tunneling Diode Structures using Ultra-thin-CaF₂/CdF₂/Si Multilayered Heterostructures Grown on Si
K. Suda, Y. Kuwata and M. Watanabe, Tokyo Tech (Japan)

PS-9-2
Diode like Behavior of IZO Junction with Superconducting Electrode at Low Temperatures
K. Makise¹ and B. Shinozaki², ¹NICT and ²Univ. of Kyushu (Japan)

PS-9-3
Investigation and Mitigation of Work-Function Variation for III-V Heterojunction Tunnel FET
C.W. Hsu, M.L. Fan and P. Su, NCTU (Taiwan)

PS-9-4
High-performance Fully-transparent Ni-doped ZnO Thin-film Transistors Fabricated on Flexible Plastic Substrate at Low Temperature
L.L. Huang¹, D.D. Han¹, Z.F. Chen^{1,2}, Y.Y. Cong¹, J. Wu^{1,2}, N.N. Zhao^{1,2}, J.C. Dong^{1,2}, F.L. Zhao^{1,2}, L.F. Liu¹, S.D. Zhang³, X. Zhang³ and Y. Wang¹, ¹Inst. of Microelectronics, Peking Univ. and ²Shenzhen Graduate School, Peking Univ. (China)

PS-9-5
Position Control of PbS Quantum Dot by Nanohole on Silicon Substrate
A. Hirota¹, S. Nakashima^{1,2} and K. Mukai¹, ¹Yokohama National Univ. and ²RIKEN Advanced Research Institute (Japan)

PS-9-6
Performance Enhancement of Colloidal Synthesis-Coated Au-Nanoparticle Nonvolatile Memory with Low Damage NH₃ Plasma Treatment on SiO₂ Tunneling Layer
C. Liao¹, Y. Liu¹, J. Wang¹, L. Chang² and C. Lai¹, ¹Chang Gung Univ. and ²Ming Chi Univ. of Tech. (Taiwan)

PS-9-7
Single InGaN nanocolumn spectroscopy
K. Sekine, Y. Onoue, T. Yoshiike, K. Asami, S. Ishizawa, T. Nakaoka and K. Kishino, Sophia Univ. (Japan)

PS-9-8
Fabrication of 10-nm-Scale Nanoconstrictions in graphene using AFM-Based Local Anodic Oxidation Lithography
M. Arai¹, S. Masubuchi^{1,2}, K. Nose¹, Y. Mitsuda¹ and T. Machida^{1,2}, ¹IIS, Univ. of Tokyo and ²INQIE, Univ. of Tokyo (Japan)

PS-9-9
Theoretical study of current fluctuation in multi-contact molecular bridge systems
S. Tsukuda and T. Nakayama, Chiba Univ. (Japan)

PS-9-10
Parameter Extraction by Microwave Characteristics of two-section Distributed feedback lasers
Y.C. Hwang, S.C. Hsu, Y.H. Lo, C.Y. Chien, H.C. Kuo and C.C. Lin, NCTU (Taiwan)

PS-9-11
High Detectivity Infrared Detectors Using Porous PZT Pyroelectric Thick Films
C.G. Wu, Q.X. Peng, X.Y. Sun, J. Meng, Y. Shuai, J.Q. Cao, W.B. Luo and W.L. Zhang, Univ. of Electronic Sci. and Tech. of China (China)

PS-9-12
Electric states in laterally and vertically arrayed Type-II Quantum Dots
T. Kawazu, NIMS (Japan)

Area 10: Organic Materials Science, Device Physics, and Applications (15 papers)

PS-10-1
Measurement and Analysis of Annealing Effect on Parylene Dielectric Transistor
R. Shidachi¹, N. Take¹, L. Philida¹, T. Tokuhara¹, T. Yokota^{1,2}, T. Sekitani^{1,2,3} and T. Someya^{1,2}, ¹Univ. of Tokyo, ²JST and ³Osaka Univ. (Japan)

PS-10-2
Improvement in Electronic Stability under Bending Stress in Flexible Organic TFT using Polymer Semiconductor
T. Sekine, K. Fukuda, D. Kumaki and S. Tokito, Research Center for Organic Electronics, Yamagata Univ. (Japan)

PS-10-3
Impact of Gate Coupling and Misalignment on Performance of Double-gate Organic Thin Film Transistors
J.W. Han, L. Sun, Y.Q. Xia, H. Xu, Y.B. Zhang, S.D. Zhang and Y. Wang, Peking Univ. (China)

PS-10-4
Charge-Transfer Behavior of Conducting Polymers as Contact Electrode for Semiconductor Devices
J. Kawakita, Y. Fujikawa, T. Nagata and T. Chikyow, NIMS (Japan)

PS-10-5
Dramatic Improvement of Bulk Heterojunction PTB7: PC₆₁BM Organic Solar Cells by Adding Small Amounts of P3HT
Y. Otori¹, T. Hoashi¹, S. Fujii², H. Kataura² and Y. Nishioka¹, ¹Nihon Univ. and ²AIST (Japan)

PS-10-6
Electrochemical Deposition of ZnO Nanorods for Hybrid Solar Cells
J. Damasco Ty and H. Yanagi, NAIST (Japan)

PS-10-7
1,3,5-tri(phenyl-2-benzimidazole)-benzene Cathode Buffer Layer Effects on Solution-Processable Organic Solar Cell Based on 1,4,8,11,15,18,22,25-Octaethylphthalocyanine
G.D.R. Banoukepa¹, A. Fujii¹, Y. Shimizu² and M. Ozaki¹, ¹Osaka Univ. and ²AIST (Japan)

PS-10-8
Cathode Buffer Layer Composed of Hyper-Branched Polymer Having Imidazole Moieties for Organic Devices
K. Fujita, Y. Kimoto and T. Okada, Kyushu Univ. (Japan)

PS-10-9
Fabrication of Large-area Nano Metal Meshes by Strip-off Method
X. Fang¹, C.H. Lin², Y.T. Sun¹, H.W. Zan³, H.F. Meng¹ and L.A. Wang¹, ¹Graduate Inst. of Photonics and Optoelectronics, National Taiwan Univ., ²Inst. of Electronics Eng., National Tsing-Hua Univ., ³Department of Photonics and Institute of Electro-Optics, NCTU and ⁴Institute of Physics, NCTU (Taiwan)

PS-10-10
Variety of Emission Color Control for Coating and Self-Aligned Ink-jet Printed Small Molecules Organic Light-Emitting Diodes
T. Kanamori¹, S. Naka¹ and H. Okada^{1,2}, ¹Univ. of Toyama and ²Center for Res. and Development in Natural Sciences (Japan)

PS-10-11
Low-Frequency Noise Characteristics of Metal-Organic-Metal Ultraviolet Sensors
P.Y. Su¹, R.W. Chuang¹, C.H. Chen² and T.H. Kao¹, ¹National Cheng Kung Univ. and ²Cheng Shiu Univ. (Taiwan)

PS-10-12
Investigation of Localized SPR and Grating-coupled SPR Enhanced Photocurrent of TiO₂ Films
S. Nootchanat^{1,2}, H. Ninsont^{1,3}, C. Thammacharoen², S. Ekgasir², K. Shinbo⁴, K. Kato⁴, F. Kaneko⁴ and A. Baba¹, ¹Niigata Univ., ²Chulalongkorn Univ. and ³Chiang Mai Univ. (Japan)

PS-10-13
Investigation of Initial Deposition Stage of Small Molecule Alq₃ on \bar{n} -NPD Layer by Modified Electro-spray Deposition (ESD) Technique (nano-mist deposition: NMD)
Y. Takatsuka¹, T. Irie¹, D. Nishi¹ and A. Kikuchi^{1,2}, ¹Univ. of Sophia and ²Sophia Nanotechnology Research Center (Japan)

PS-10-14
Electric and Pyroelectric Properties of spin-coated Polyurea Films
M. Morimoto, Y. Koshiba, M. Misaki and K. Ishida, Kobe Univ. (Japan)

PS-10-15
Fabrication and Optical Anisotropy of Non-Peripheral Octahexylphthalocyanine Films with Large Mono-Domain
T. Higashi, M. Ohmori, M.F. Ramanarivo, H. Yoshida, A. Fujii and M. Ozaki, Osaka Univ. (Japan)

Area 11: Sensors and Materials for Biology, Chemistry and Medicine
(17 papers)

PS-11-1
Detection of PCR Products by Micro- and Nanoscale Field-Effect Transistors
M. Schwartz^{1,2}, T.C. Nguyen¹, X.T. Vu^{1,2}, P. Wagner³ and S. Ingebrandt¹, ¹Univ. of Applied Sciences Kaiserslautern, ²RWTH Aachen Univ. and ³Hasselt Univ. (Germany)

PS-11-2
Surface Modified Poly-crystalline Silicon Nanowires Field Effect Transistor for Ammonia Gas Sensor
W.T. Kuo¹, Y.R. Lo², Y.S. Yang² and H.M.P. Chen^{1,3}, ¹Department of Photonics, NCTU, ²Department of Biological Science and Technology, NCTU and ³Institute of Biomedical Engineering, NCTU (Taiwan)

PS-11-3
CMOS Pulse-Width-Modulation Readout Circuit for ISFET-Based Sensors
R.L. Wang¹, W.D. Wu¹, C. Yu¹, P.H. Chiul¹, J.L. Shi¹, Y.F. Hao¹, H.H. Liao², H.H. Tsai² and Y.Z. Juang², ¹National Kaohsiung Normal Univ. and ²National Chip Implementation Center, National Applied Research Lab. (Taiwan)

PS-11-4
PSpice Simulation Model for Biomolecule Detection with Silicon Nanowire Bio-sensors in both Potentiometric and Impedimetric Readout Mode
T.C. Nguyen¹, M. Schwartz¹, X.T. Vu^{1,2} and S. Ingebrandt¹, ¹Univ. of Applied Sciences Kaiserslautern and ²RWTH Aachen Univ. (Germany)

PS-11-5
Characterization of ion sensitive extended-gate field effect transistor coated by functional self-assembled monolayer
T. Kajisa and T. Sakata, Univ. of Tokyo (Japan)

PS-11-6
Schottky Barrier Carbon Nanotube FET (CNTFET) Gas Sensors
C.V.S. Reddy¹, S. Maheshwaram¹, S. Dasgupta¹, A.K. Saxena¹, N. Jain² and S.K. Manhas¹, ¹Indian Inst. of Tech. Roorkee and ²Solid State Physics Lab. (India)

PS-11-7
Conductive Diamond-like Carbon Film Deposition by Low Temperature Neutral Beam Enhanced Chemical Vapor Deposition for Bio-LSIs
X.J. Chang¹, Y. Kikuchi^{1,2}, T. Kubota¹, K.Y. Inoue³, T. Matsue^{3,4} and S. Samukawa^{1,4}, ¹Inst. of Fluid Sci., Tohoku Univ., ²Tokyo Electron Ltd., ³Grad. Sch. of Environ., Tohoku Univ. and ⁴WPI-Adv. Inst. Mat. Res., Tohoku Univ. (Japan)

PS-11-8
Induction of Neural Stem Cells on Indium Tin Oxide Surface
I.C. Lee, Y.C. Liu, Y.C. Wu and K.F. Lei, Chang Gung Univ. (Taiwan)

PS-11-9
Fluidity Evaluation of Cell Membrane Model Formed on Graphene Oxide with Single Particle Tracking Using Qdot
Y. Okamoto, T. Molegi, S. Iwasa, A. Sandhu and R. Tero, Toyohashi Univ. of Tech. (Japan)

PS-11-10
Formation and Fluidity Measurement of Artificial Lipid Membranes on Polyvinyl Chloride Substrate
T. Kobayashi¹, A. Kono¹, T. Hattori¹, K. Sawada¹ and R. Tero^{1,2}, ¹Toyohashi Univ. of Tech and ²Electronics-Inspired Interdisciplinary Research Institute (Japan)

PS-11-11
Fiber-optic Biosensor based on Multimode Interference using Small-core Single-mode Fiber
M. Doi¹, S. Taw¹, Y. Yanase² and H. Fukano¹, ¹Okayama Univ. and ²Hiroshima Univ. (Japan)

PS-11-12
Sensitivity Enhancement in Refractive Index Measurement based on Optical Fiber Multimode Interference with Gold Nanoparticles
S. Taw, H. Daitoh and H. Fukano, Okayama Univ. (Japan)

PS-11-13
SPR Imaging Sensor for Visualization of Individual Cell Activation and Clinical Diagnosis of Allergy
Y. Yanase, T. Kawaguchi, K. Ishii and M. Hide, Hiroshima Univ. (Japan)

PS-11-14
Electrochemical Impedance Spectroscopy of Colloidal Gold Nanoparticles in Chromatography Paper for Immunochematographic Assay
F. Hori and S. Uno, Ritsumeikan Univ. (Japan)

PS-11-15
Catalytic Behaviour of Ultrafine Pt on the Gas Sensor of ZnO Nanoparticles
A. Ahmadi Daryakenari¹, A. Apostoluk² and J.J. Delaunay¹, ¹Univ. of Tokyo, Mechanical Eng. and ²Institut des Nanotechnologies de Lyon (Japan)

PS-11-16
Bioassay of Target Proteins Using A NiCr Strain Gauge-Cantilever Liposome Biosensor with Droplet-Sealed Structure
Z. Zhang¹, T. Aka¹, M. Sohgo², K. Takada¹, K. Yamashita¹ and M. Noda¹, ¹Kyoto Inst. Tech. and ²Niigata Univ. (Japan)

PS-11-17
Capacitive Breathing Sensor and Evaluation of Body Movement Noise
M. Sasaki, S.K. Kundu, J. Jeong and S. Kumagai, Toyota Tech. Inst. (Japan)

Area 12: Spintronics Materials and Devices
(13 papers)

PS-12-1
Preparation of GaAs-based Spin-photonic Devices for Emission and Detection of Circularly Polarized Light
H. Muneoka, N. Nishizawa, H. Ikeda and K. Nishibayashi, Tokyo Tech (Japan)

PS-12-2
Monolithic integration of Magneto-Optical Plasmonic Waveguides with GaAs/Al-GaAs Waveguides on GaAs Substrate and with Si Nanowire Waveguides on Si sub-strate for Integrated Non-reciprocal Optical Devices
V. Zayets, H. Saito, K. Ando and S. Yuasa, AIST (Japan)

PS-12-3
Fabrication of Ge-based light-emitting diodes with a ferromagnetic electrode
S. Iba¹, H. Saito¹, S. Yuasa¹, Y. Yasutake² and S. Fukatsu¹, ¹AIST and ²Univ. of Tokyo (Japan)

PS-12-4
Effects of Band Mixing on Hole-Spin Superposition in GaAs/AlGaAs Quantum Wells
T. Ito^{1,2}, H. Gotoh³, M. Ichida⁴ and H. Ando¹, ¹Res. Inst. of Electronics, Shizuoka Univ., ²Graduate School of Eng., Shizuoka Univ., ³NTT Basic Res. Labs., NTT Corp. and ⁴Department of Physics, Faculty of Sci. and Eng., Konan Univ. (Japan)

PS-12-5
Effects of interface electric field on the magnetoresistance for nonlocal setup
T. Tanamoto, M. Ishikawa, T. Inokuchi, H. Sugiyama and Y. Saito, Toshiba Corp. (Japan)

PS-12-6
In-plane Anisotropy of a CoFeB-MgO Magnetic Tunnel Junction with Perpendicular Magnetic Easy Axis
E. Hirayama¹, S. Kana¹, K. Sato², M. Yamanouchi^{1,3}, H. Sato^{3,4}, S. Ikeda^{1,3,4}, F. Matsukura^{2,3} and H. Ohno^{1,2,3,4}, ¹Lab. for Nanoelectronics and Spintronics, Res. Inst. of Electrical Communication, Tohoku Univ., ²WPI-AIMR, Tohoku Univ., ³Center for Spintronics Integrated Systems, Tohoku Univ. and ⁴Center for Innovative Integrated Electronic Systems, Tohoku Univ. (Japan)

PS-12-7
Dependence of magnetic properties of MgO/CoFeB/Ta stacks on CoFeB and Ta thicknesses
K. Watanabe¹, S. Ishikawa¹, H. Sato^{2,3}, S. Ikeda^{1,2,3}, M. Yamanouchi^{1,2}, S. Fukami^{2,3}, F. Matsukura^{1,2} and H. Ohno^{1,2,3,4}, ¹Lab. for Nanoelectronics and Spintronics, Res. Inst. of Electrical Communication, Tohoku Univ., ²Center for Spintronics Integrated Systems, Tohoku Univ., ³Center for Innovative Electronic Systems, Tohoku Univ. and ⁴WPI-Advanced Inst. for Materials Res., Tohoku Univ. (Japan)

PS-12-8
The Fabrication of the Magnetic Tunnel Junctions Including Spinel Ferrite Layers
N. Takahashi¹, T. Kawai¹, T. Nagahama² and T. Shimada¹, ¹Graduate School of Chemical Sciences and Engineering, Hokkaido Univ. and ²Graduate School of Engineering, Hokkaido Univ. (Japan)

PS-12-9
Synthesis And Characterization of Electron Doped La_{0.85}Te_{0.15}MnO₃ Thin Film Grown on LaAlO₃ Substrate By Pulsed Laser Deposition Technique.
I. Bhat¹, Shahid. Husain¹ and S.I. Patil², ¹Department of Physics, Aligarh Muslim Univ. and ²Department of Physics, Univ. of Pune (India)

PS-12-10
Growth of Very Thin Films of Mn₂Ge with a Perpendicular Magnetic Anisotropy
A. Sugihara, S. Mizukami and T. Miyazaki, WPI-AIMR, Tohoku Univ. (Japan)

PS-12-11
LLG Micromagnetic Simulation on STT Efficiency of sub 30nm Perpendicular MTJs with etching damage
K. Ito, S. Ohuchida and T. Endoh, Tohoku Univ. (Japan)

PS-12-12
Fabrication of Magnetic Tunnel Junctions with Synthetic Coupled Free Layer for Highly Sensitive Magnetic Field Sensor Devices
D. Kato¹, M. Oogane¹, K. Fujiwara¹, T. Nishikawa², H. Naganuma¹ and Y. Ando¹, ¹Tohoku Univ. and ²KONICA MINOLTA (Japan)

PS-12-13
Development of Scanning de-SQUID system for local magnetic imaging
Y. Shibata¹, Y. Osima¹, H. Kashiwaya², R. Ishiguro³, S. Kashiwaya², H. Takayanagi⁴ and S. Nomura¹, ¹Univ. of Tsukuba, ²AIST, ³RIKEN and ⁴NIMS (Japan)

Area 13: Applications of Nanotubes, Nanowires, and Graphene
(14 papers)

PS-13-1
Electrical Properties of MoS₂/Graphene Heterostructure and pn Junction Diode
W.J. Su¹, H.C. Chang², H.Y. Chang², Y.S. Huang^{1,2} and K.Y. Lee^{1,2}, ¹Graduate Institute of Electro-Optical Engineering, National Taiwan Univ. of Sci. and Tech. and ²Department of Electronic Engineering, National Taiwan Univ. of Sci. and Tech. (Taiwan)

PS-13-2
Improved Dispersibility and Thermopower of Single-Walled Carbon Nanotubes in Ionic Polymers
M. Nakano, Y. Nonoguchi, T. Nakashima and T. Kawai, NAIST (Japan)

PS-13-3
Graphene as a Template Layer for the Growth of Ga-Based Compound Materials
F.R. Wong¹, N.S.A. Aziz¹, K. Yasui² and A.M. Hashim¹, ¹Malaysia-Japan International Inst. of Tech. and ²Nagaoka Univ. of Tech. (Malaysia)

PS-13-4
Defect Generation in Mono-layer Graphene in O₂-PDA and FGA
W.J. Liu, K. Nagashio, T. Nishimura and A. Toriumi, Univ. of Tokyo (Japan)

PS-13-5
Damping of Unexpected Motion of Carbon-Nanotube Nanorelay-Arm by Introducing Pinhole Defects
A. Nagataki^{1,2}, K. Takei¹, T. Arie¹ and S. Akita¹, ¹Osaka Pref. Univ. and ²KRI Inc. (Japan)

PS-13-6
Ab Initio Calculations for Li⁺ Solvation in Ethylene Carbonate near the Graphite Edges with Hydrogen/Oxygen Terminations
T. Kawai^{1,2} and S. Okada², ¹NEC Corp. and ²Univ. of Tsukuba (Japan)

PS-13-7
A First Principles Study on CVD Graphene Growth on Copper Surface: C-C Bonding Reactions at Graphene Edges
N. Tajima¹, T. Kaneko¹, J. Nara¹ and T. Ohno^{1,2}, ¹NIMS and ²Univ. of Tokyo (Japan)

PS-13-8
Detection of Molecular Charge Dynamics through Current Noise in A GaAs-based Nanowire FET
S. Inoue^{1,2}, R. Kuroda^{1,2}, M. Sato^{1,2} and S. Kasai^{1,2}, ¹Graduate School of Info.Sci.Tech., Hokkaido Univ. and ²RCIQE, Hokkaido Univ. (Japan)

PS-13-9
Highly-Sensitive BiFeO-Coated ZnO Nanowire Arrays for Flexible Piezoelectric Sensing Applications
C.P. Cheng, C.H. Hsu, C.P. Chou, Z.Y. Liou, Y.S. Li, Y.Y. Syu and C.H. Cheng, National Taiwan Normal Univ. (Taiwan)

PS-13-10
Characterization of Electron Transport Properties of <110> InAs Nanowires by Hall Effect Measurements
Z. Cui¹, R. Perumal¹, T. Ishikura¹, K. Konishi¹, K. Yoh¹ and J. Motohisa², ¹RCIQE, Hokkaido Univ. and ²IST, Hokkaido Univ. (Japan)

PS-13-11
Characterization of Selective Doping and Stress in Ge/Si Core-Shell Nanowires
M. Yu, J. Wipakorn and N. Fukata, NIMS (Japan)

PS-13-12
Design and Growth of Nanowire Nanocavity
T. Wada¹, S. Hara^{1,2} and J. Motohisa¹, ¹Graduate School of Information Science and Technology, Hokkaido Univ. and ²Research Center for Integrated Quantum Electronics, Hokkaido Univ. (Japan)

PS-13-13
Enhancement of Thermoelectric Properties via Radial Dopant Inhomogeneity in B-doped Si Nanowires
T. Yanagida¹, F. Zhuge¹, K. Nagashima¹, N. Fukata² and K. Uchida³, ¹Osaka Univ., ²NIMS and ³Keio Univ. (Japan)

PS-13-14 (Late News)
Electrical Characterization of Nanometer Structures with Graphene Directly Grown on SiO₂ by Alcohol Chemical Vapor Deposition
H. Sato¹, K. Yamada¹, A. Nakamura¹, H. Sato¹, J. Temmyo¹ and H. Inokawa², ¹Grad. Sch. Of Engineering, Shizuoka Univ. and ²Res. Inst. Of Elec. Shizuoka Univ. (Japan)

Area 14: Power Devices and Materials
(14 papers)

PS-14-1
Hot carrier effect and PBTI of a thin-film SOI power MOSFET at high temperature
W. Yoshida, T. Takasugi and S. Matsumoto, Kyushu Inst. of Tech. (Japan)

PS-14-2
Well proximity effect impact on fully isolated low R_{on}*Q_g MOSFET performance
M. Shima¹, M. Katayama¹, H. Sato¹, M. Onoda¹, T. Yoshimura¹, T. Ishihara¹, Y. Suzuki¹, N. Suzuki¹, M. Hosoda², T. Imada² and T. Hirose², ¹Fujitsu Semiconductor Ltd. and ²Fujitsu Laboratories Ltd. (Japan)

PS-14-3
Impact of the silicon on diamond structure for high temperature switching applications
H. Kanoya, K. Nakagawa and S. Matsumoto, Kyushu Inst. of Tech. (Japan)

PS-14-4
Analysis of forward voltage and reverse recovery charge control of silicon PiN diodes
Y. Yamashita and S. Machida, Toyota Central R&D Labs., Inc. (Japan)

PS-14-5
Growth and investigation of stacking fault of 4H-SiC C-face homoepitaxial layers with 1° off-angle
K. Masumoto^{1,2}, H. Asamizu^{1,3}, K. Tamura^{1,3}, C. Kudou^{1,4}, J. Nishio^{1,5}, K. Kazutoshi^{1,2}, T. Ohno^{1,6} and H. Okumura^{1,2}, ¹FUPET, ²AIST, ³ROHM Co., Ltd., ⁴Panasonic Corp., ⁵Toshiba Corp. and ⁶Hitachi, Ltd. (Japan)

PS-14-6
Tilt-implanted trench termination for SiC power devices
G.Y. Song, D.H. Cho, G.H. Song and G.S. Kim, Sogang Univ. (Korea)

PS-14-7
Short-circuit capability of SiC power MOSFETs
T. Shoji^{1,2}, A. Soeno¹, H. Toguchi¹, S. Aoi¹, Y. Watanabe¹ and H. Tadano³, ¹Toyota Central R&D Labs., Inc., ²Toyota Motor Corp. and ³Univ. of Tsukuba (Japan)

PS-14-8
Switching characteristics of a 4H-SiC IGBT with interface defects up to the nonquasi-static regime
I. Pesic^{1,2}, D. Navarro¹, M. Fujinaga², Y. Furu² and M. Miura-Mattausch¹, ¹Hiroshima Univ. and ²Silvaco Japan (Japan)

PS-14-9
Energy-band offset of AlN/Diamond(111) heterojunction determined by X-ray photoelectron spectroscopy
M. Imura, A. Tanaka, H. Iwai, J. Liu, M. Liao and Y. Koide, NIMS (Japan)

PS-14-10
Schottky-barrier inhomogeneities in WC/p-diamond at high temperature
A. Fiori, T. Teraji and Y. Koide, NIMS (Japan)

PS-14-11
Static and transient performance comparisons between diamond p+/p- diode and m-i-pt (Metal-Intrinsic-p+) diode
A. Nawawi¹, K.J. Tseng¹, R. Rusli¹, G.A.J. Amaratunga^{1,2}, H. Umezawa³ and S. Shikata³, ¹Nanyang Tech. Univ., ²Univ. of Cambridge and ³AIST (Singapore)

PS-14-12 (Late News)
Generation and suppression of oxidation byproducts at 4H-SiC C-face / SiO₂ interface characterized by infrared spectroscopy
H. Hirai¹ and K. Kita^{1,2}, ¹The Univ. of Tokyo and ²JST-PRESTO (Japan)

PS-14-13 (Late News)
Effect of gate oxide process at SiC-MOS interface on threshold voltage shift analyzed by DLTS
J. Hasegawa¹, M. Noguchi¹, M. Furuhashi¹, S. Nakata¹, T. Iwasaki¹, T. Koderu¹, T. Nishimura¹ and M. Hatano¹, ¹Tokyo Inst. Of Tech. and ²Mitsubishi Electric Corp. (Japan)

PS-14-14 (Late News)
Quantitative characterization of border traps with widely-spread time constants in SiC MOS capacitors by transient capacitance measurements
Y. Fujino¹, R.H. Kikuchi¹, H. Hirai¹ and K. Kita^{1,2}, ¹The Univ. of Tokyo and ²JST-PRESTO (Japan)

Area 15: Photovoltaic Materials and Devices
(9 papers)

PS-15-1
Simulation Analysis of The Potential Causes for The Low Jsc in GaAsN Solar Cells
L. Wang, O. Elleuch, N. Kojima, Y. Ohshita and M. Yamaguchi, Toyota Tech. Inst. (Japan)

PS-15-2
Characterization of Directly Bonded Ge/GaAs by Surface Activated Bonding for Multi-junction Solar Cells
G. Kono, M. Fujino, D. Yamashita, K. Watanabe, M. Sugiyama, Y. Nakano and T. Suga, Univ. of Tokyo (Japan)

PS-15-3
Optical Characterization of GaInP p-i-n Solar Cells
Y.G. Li¹, D.Y. Lin¹, T.S. Ko¹, J.S. Wu¹, C.H. Wu², Y.L. Tsa², M.C. Kao³ and H.Z. Chen³, ¹National Changhua Univ. of Edu., ²Inst. of Nuclear Energy Res. and ³Hsiuping Univ. Sci. and Tech. (Taiwan)

PS-15-4
Effects of Copper Concentration on the Characteristics of Cu₂ZnSnS₄ Thin Films Prepared by Rapid Thermal Annealing
B.T. Jheng¹ and P.T. Liu², ¹National Tsing Hua Univ. and ²NCTU (Taiwan)

PS-15-5
Ultra-low Reflective Micro-structures Fabricated by One-step Advanced Silicon Etching on Silicon Surface
L. Zhang, D.Q. Zhao, J. He, X. Huang, F. Yang and D.C. Zhang, Peking Univ. (China)

PS-15-6
Investigation of chemical-bonding state and fixed charge state of Sr₂SiO₄ film on Si(100) substrate
S. Taniwaki¹, Y. Hotta^{1,3}, H. Yoshida^{1,3}, K. Arafune^{1,3}, A. Ogura^{2,3} and S. Satoh^{1,3}, ¹Univ. of Hyogo, ²Meiji Univ. and ³JST-CREST (Japan)

PS-15-7
Withdrawn

PS-15-8
Enhanced Conversion Efficiency of Hybrid Solar Cells by using Alloyed Silicon-Tin Nanocrystals via Quantum Confinement Effect
M. Lozac'h¹, V. Svrcek¹, D. Mariotti² and K. Matsukuba¹, ¹AIST and ²Univ. of Ulster (Japan)

PS-15-9 (Late News)
Effect of Inter-dot Spacing on Radiative Lifetime in InAs/GaAsSb Type II Quantum Dot Superlattices
H. Yoshikawa, T. Kotani, Y. Kuzumoto, M. Izumi and Y. Tomomura, SHARP Corp. (Japan)

Thursday, September 11

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
<p>A-6: Non Volatile Memory and Logic I (9:30-11:00) Chairs: S. Mitani (NIMS) T. Nagahama (Hokkaido Univ.)</p>	<p>B-6: Optical Interconnection I (9:30-10:45) Chairs: H. Ishii (Toyohashi Univ. of Tech.) F. Boeuf (STMICROELECTRONICS)</p>	<p>C-6: Growth and Process of Oxides (9:30-10:45) Chairs: T. Nagata (NIMS) T. Kawae (Kanazawa Univ.)</p>	<p>D-6: Bio Molecular Analysis (9:30-10:30) Chairs: M. Sasaki (Toyota Tech. Inst.) S. Machida (Hitachi)</p>		<p>F-6: Thermal Oxidation and MOS Interface (10:00-10:50) Chairs: M. Kato (Nagoya Inst. of Tech.) H. Nohira (Tokyo City Univ.)</p>	<p>G-6: Compound Semiconductor Photovoltaics (9:30-10:30) Chairs: T. Okamoto (Kisarazu National Collage of Tech.) M. Isomura (Tokai Univ.)</p>
<p>9:30 A-6-1 (Invited) Progress of STT-MRAM Technology and its application to low-power memory systems <i>A key Technology and Prospect of Normally-off memory systems</i> H. Yoda¹, N. Shimomura², J. Ito³, S. Fujita² and K. Ando³, ¹Center For Semiconductor Research & Development, Toshiba Corp., ²Corporate R&D Center, Toshiba Corp. and ³AIST (Japan)</p>	<p>9:30 B-6-1 (Invited) Luxtera's Silicon Photonics Platform for Transceiver Manufacturing M.P. Mack, A. Ayazi, Y. Chi, A. Dahl, P. De Dobbelaere, S. Denton, S. Gloeckner, K.Y. Hon, S. Hovey, Y. Liang, G. Masini, A. Mekis, M. Peterson, T. Pinguet, S. Sahni, J. Schramm, M. Sharp, C. Sohn, K. Stechschulte, P. Sun, G. Vastola, L. Verslegers and R. Zhou, Luxtera, Inc. (USA)</p>	<p>9:30 C-6-1 (Invited) Epitaxial Growth, Doping, and Electron Transport of the Semiconducting Oxides In₂O₃, Ga₂O₃, and SnO₂ O. Bierwagen^{1,2}, M.E. White², M.-Y. Tsai², J.S. Speck², T. Nagata³, N. Preissler¹ and P. Vogl¹, ¹Paul-Drude-Inst., ²Univ. of California Santa Barbara and ³NIMS (Germany)</p>	<p>9:30 D-6-1 DNA Single Base Polymerization Detection Using CMOS FET-Based Redox Potential Sensor Array H. Ishihara, K. Niitsu and K. Nakazato, Univ. of Nagoya (Japan)</p>		<p>10:00 F-6-1 Depth Profile of Thermally Grown SiO₂ Film Density R. Hasunuma, M. Hayashi and K. Yamabe, Univ. of Tsukuba (Japan)</p>	<p>9:30 G-6-1 (Invited) Cu₂ZnSnS₄ Solar Cells Fabricated by an Electrochemical Technique S. Ikeda, F. Jiang, W. Septina, T. Harada and M. Matsumura, Osaka Univ. (Japan)</p>
<p>10:00 A-6-2 Perpendicular Magnetic Tunnel Junctions with L10-MnGa/FeCo Bilayer Electrodes with Tunable Interfacial Exchange Coupling Q.L. Ma, S. Mizukami, X.M. Zhang, Y. Ando and T. Miyazaki, Tohoku Univ. (Japan)</p>	<p>10:00 B-6-2 MOS Capacitor Type Si Optical Modulator Integrated with Ge Photodetector and its High Speed Operation with CMOS Driver J. Fujikata¹, S. Takahashi¹, M. Takahashi², M. Noguchi¹, H. Noguchi³, T. Horikawa⁴, T. Nakamura¹ and Y. Arakawa⁴, ¹PETRA, ²AIST, ³NEC Corp. and ⁴Univ. of Tokyo (Japan)</p>	<p>10:00 C-6-2 A New Classification of Nano-Scale Crystallinity of In-Ga-Zn-Oxide Films Y. Nonaka, Y. Yamada, M. Oota, N. Ishihara, Y. Kurosawa, S. Nishino and S. Yamazaki, Semiconductor Energy Lab. Co., Ltd. (Japan)</p>	<p>9:45 D-6-2 DNA Biosensing using Ga₂O₃ Based Metal/Oxide Diode T. Rahman¹, T. Masui² and T. Ichiki¹, ¹Univ. of Tokyo and ²Koha Co., Ltd (Japan)</p>		<p>10:20 F-6-2 Reduction of Defect State Density at SiO₂/SiC Interface Formed by the Thermal Oxidation Accompanied with Direct CO Generation R. Kikuchi¹, Y. Fujino¹ and K. Kita^{1,2}, ¹Univ. of Tokyo and ²JST-PRESTO (Japan)</p>	<p>10:00 G-6-2 Properties of deep-level defect in Cu(In, Ga)Se₂ thin films X.B. Hu¹, T. Sakurai¹, A. Yamada², S. Ishizuka², S. Niki² and K. Akimoto¹, ¹Univ. of Tsukuba and ²AIST (Japan)</p>
<p>10:20 A-6-3 Properties of Perpendicular-Anisotropy Magnetic Tunnel Junctions Fabricated over The Cu Via S. Miura¹, H. Honjo¹, K. Kinoshita¹, K. Tokutome¹, H. Koike², S. Ikeda², T. Endoh² and H. Ohno², ¹NEC Corp. and ²Tohoku Univ. (Japan)</p>	<p>10:15 B-6-3 A Method Enables Height-Control of Bonding Chip for Edge-Emitting Laser Stacking M. Aoyagi, T.T. Bui, L. Ma, T. Amano, K. Kikuchi and M. Mori, AIST (Japan)</p>	<p>10:15 C-6-3 Rapid Thermal Oxidation of Zinc Nitride Film C.W. Lin, Y.P. Song and S.C. Chang, Tatung Univ. (Taiwan)</p>	<p>10:00 D-6-3 Single-Molecule Tunnel-Current based Detection Toward Amino-Acid Identification T. Ohshiro, M. Tsutsui, K. Yokota, T. Kawai and M. Taniguchi, Osaka Univ. (Japan)</p>		<p>10:35 F-6-3 Estimation of Real SiC-MOS Characteristics by Using Novel High-Speed Pulse IV N. Tega, D. Hisamoto, H. Yoshimoto, A. Shima and Y. Shimamoto, Hitachi, Ltd. (Japan)</p>	<p>10:15 G-6-3 Fabrication of Polycrystalline CdTe Thin-Film Solar Cells using Carbon Electrodes with Carbon Nanotubes T. Okamoto¹, R. Hayashi¹, Y. Ogawa¹, A. Hosono¹ and M. Doi², ¹Kisarazu Natl. Coll. Tech. and ²JFE Eng. Corp. (Japan)</p>
<p>10:40 A-6-4 Study about the Process Damage Mechanism of the Patterned Interface Perpendicular Magnetic Tunnel Junctions (MTJs) by Hydrogen Ion Treatments J.H. Jeong^{1,3} and T. Endoh^{1,2}, ¹Tohoku Univ., ²Center for Innovative Integrated Electronic Systems (CIES) and ³SAMSUNG Electronics Co., Ltd. (Japan)</p>	<p>10:30 B-6-4 Monolithically Integrated Quantum Dot Electro-Optic Modulator with Semiconductor Optical Amplifier for Short-Reach Optical Communications N. Yamamoto, K. Akahane, T. Umezawa and T. Kawanishi, NICT (Japan)</p>	<p>10:30 C-6-4 Epitaxial Growth of ZnO Film on Patterned n-GaN Layer by Hydrothermal Method R.M. Ko¹, Y.C. Huang², T.H. Yu², S.M. Su², Y.R. Lin³ and S.J. Wang², ¹Adv. Optoelectronic Tech. Center, National Cheng Kung Univ., ²Inst. of Microelectronics, National Cheng Kung Univ. and ³Ming Chi Univ. of Tech. (Taiwan)</p>	<p>10:15 D-6-4 Nanoporous Organosilicates Thin Films for Selective Enrichment of Metabolites C. Yeromonahos, A. Mombrun, C. Leclech, A. Bouamrani and V. Jousseau, CEA - LETI Grenoble (France)</p>			

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
<p>H-6: Quantum Transport (1) (9:30-10:45) Chairs: T. Tanamoto (Toshiba) T. Machida (Univ. of Tokyo)</p>	<p>J-6: Ge & SiGe CMOS (9:30-10:40) Chairs: N. Sugii (LEAP) F.-L. Yang (Academia Sinica)</p>	<p>K-6: OLED (9:30-10:45) Chairs: H. Okada (Univ. of Toyama) H. Murata (JAIST)</p>	<p>M-6: MEMS and Energy Harvestors (9:30-10:50) Chairs: H. Takao (Kagawa Univ.) Y. Mita (Univ. of Tokyo)</p>		<p>P-6: Nanowire Photonics (9:30-10:45) Chairs: M. Arita (Univ. of Tokyo) N. Fukata (NIMS)</p>
<p>9:30 H-6-1 (Invited) Angular momentum conversion from single photons to single electron spins in a lateral double quantum dot A. Oiwa^{1,2}, T. Fujita², K. Morimoto², H. Kiyama^{1,2}, G. Allison^{2,3}, M. Larsson², A. Ludwig⁴, A.D. Wieck⁴ and S. Tarucha^{2,3}, ¹Osaka Univ., ²Univ. of Tokyo, ³RIKEN and ⁴Ruhr-Universität Bochum (Japan)</p>	<p>9:30 J-6-1 (Invited) Drive Current Performance of Inversion Mode Ge CMOS Transistors X. Gong and Y.-C. Yeo, National Univ. of Singapore (Singapore)</p>	<p>9:30 K-6-1 (Invited) Recent Progress in Polymer Light Emitting Materials T. Yamada, Y. Tsubata, K. Ohuchi, D. Fukushima and N. Akino, Sumitomo Chemical Co., Ltd. (Japan)</p>	<p>9:30 M-6-1 A Sub-1G Tri-axis MEMS Capacitive Sensor for Integrated CMOS-MEMS Accelerometers D. Yamane¹, T. Konishi², T. Matsushima², H. Toshiyoshi³, K. Masu⁴ and K. Machida^{1,2}, ¹Tokyo Tech, ²NTT Advanced Tech. Corp. and ³Univ. of Tokyo (Japan)</p>		<p>9:30 P-6-1 (Invited) Advanced Emission Properties and Lasing from (In,Ga)As Nanowires B. Mayer¹, J. Treu¹, S. Morkötter¹, D. Rudolph¹, G. Abstreiter^{1,2}, J.J. Finley¹ and G. Koblmüller¹, ¹WSI and ²Technical Univ. Munich (Germany)</p>
<p>10:00 H-6-2 Towards Cavity QED with InSb spin qubits R.S. Deacon¹, Y. Yamazaki¹, T. Fuse¹, G. Allison¹, A. Oiwa², M.T. Deng³, H.Q. Xu^{3,4}, S. Tarucha⁵ and K. Ishibashi¹, ¹RIKEN, ²Osaka Univ., ³Lund Univ., ⁴Peking Univ. and ⁵Univ. of Tokyo (Japan)</p>	<p>10:00 J-6-2 Strained Si_{1-x}Ge_x on Strained-Si-on-Insulator (sSOI) pMOSFETs for Low-Power sSOI Based CMOS K. Ikeda, Y. Moriyama, T. Irisawa, M. Ono, Y. Kamimuta, M. Oda, T. Miyaki, E. Kurosawa and T. Tezuka, AIST (Japan)</p>	<p>10:00 K-6-2 Measurement of Thermal Carrier de-Trapping in Double-Layer Organic Light-Emitting Diodes by Electric-Field-Induced Optical Second-Harmonic Generation D. Taguchi, T. Manaka and M. Iwamoto, Tokyo Tech (Japan)</p>	<p>9:50: M-6-2 Withdrawn</p>		<p>10:00 P-6-2 Lasing Oscillation in Multi-stacked InGaAs/GaAs Quantum Dots with a Single GaAs Nanowire Cavity J. Tatebayashi¹, S. Kako¹, J.F. Ho², S. Iwamoto^{1,2} and Y. Arakawa^{1,2}, ¹NanoQUINE, Univ. of Tokyo and ²IIS, Univ. of Tokyo (Japan)</p>
<p>10:15 H-6-3 Signature of Superconducting Density of States in Luminescence Spectra of InAs Quantum Dots S. S. Mou¹, H. Irie², K. Akahane³, H. Kurosawa¹, H. Nakajima¹, H. Kumano¹, M. Sasaki³ and I. Suemune¹, ¹Hokkaido Univ., ²NTT Basic Res. Labs. and ³Nat. Inst. of Info. Comm. Tech. (Japan)</p>	<p>10:20 J-6-3 Study of Si- and SiGe-on-Insulator Ω-Gate Nanowire PMOS FETs by Low-frequency Noise Measurements M. Koyama^{1,2}, M. Cassé¹, S. Barraud¹, P. Nguyen^{1,3}, G. Ghibaudo¹, H. Iwai² and G. Reimbold¹, ¹CEA-LETI, ²Tokyo Tech, ³SOITEC and ⁴IMEP-LAHC (France)</p>	<p>10:15 K-6-3 Application of Silver Nanowire for Transparent Electrode of OLED Device A. Tadamasu, T. Matsui and A. Tsujimoto, Panasonic Corp. (Japan)</p>	<p>10:10 M-6-3 An RF Energy Harvesting Power Management Circuit with Timing Detection A. Shirane, H. Ito, N. Ishihara and K. Masu, Tokyo Tech (Japan)</p>		<p>10:15 P-6-3 Room-temperature Electroluminescence of Radial p-i-n InP Nanowires with InAsP Quantum Wells in the 1.5-μm Wavelength Region K. Kawaguchi^{1,2}, H. Sudo¹, M. Matsuda¹ and Y. Arakawa^{2,3}, ¹Fujitsu Labs., ²INQIE, Univ. of Tokyo and ³IIS, Univ. of Tokyo (Japan)</p>
<p>10:30 H-6-4 (Late News) Electrically Driven Dynamic Nuclear Spin Polarization in Single Quantum Dot M. Kawamura, D. Gottwald, K. Ono and K. Kono, RIKEN (Japan)</p>		<p>10:30 K-6-4 Improved Light-Emitting Properties of Bilayer Polymer Light-Emitting Transistors with Phosphorescent Dye Doped in Fluorene-Type Polymers H. Kajii, H. Tanaka, I. Ikezoe, M. Hara, T. Ohtomo and Y. Ohmori, Osaka Univ. (Japan)</p>	<p>10:30 M-6-4 Improvement of Power Conversion Efficiency in Photovoltaic-Assisted UHF Rectifiers by Adopting Non-Silicide PV Cells K. Kotani and T. Bando, Tohoku Univ. (Japan)</p>		<p>10:30 P-6-4 Strain Characterization of InAs Segment in Au-free InP/InAs Heterostructure Nanowires by Micro-Raman Measurement G. Zhang¹, K. Suzuki², S. Nakagawa³, K. Tateno¹, T. Sogawa¹ and H. Gotoh¹, ¹Basic Res. Labs., NTT Corp., ²Tokyo Denki Univ. and ³Toyoashi Univ. of Tech. (Japan)</p>

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
<p>A-7: Non Volatile Memory and Logic II (11:15-12:15) Chairs: Y. Saito (Toshiba) K. Takeuchi (Chuo Univ.)</p>	<p>B-7: Optical Interconnection II (11:15-12:15) Chairs: Y. Ishikawa (Univ. of Tokyo) S. Itabashi (NTT-AT)</p>	<p>C-7: Properties of Oxides (11:15-12:15) Chairs: T. Kawae (Kanazawa Univ.) T. Nagata (NIMS)</p>	<p>D-7: Microdevices for Biomedical Applications (11:15-12:30) Chairs: J. Ohta (Nara Inst. of Sci. & Tech.) C. -S. Lai (Chang Gung Univ.)</p>	<p>E-7: Oxide Devices (11:15-12:30) Chairs: N. Hara (Fujitsu Labs.) E. Y. Chang (NCTU)</p>	<p>F-7: Ge Channel Devices (11:15-12:35) Chairs: T. Aoyama (Toshiba) H. Morioka (Fujitsu Semicon.)</p>	<p>G-7: New Concepts (11:15-12:30) Chairs: Y. Kurokawa (Tokyo Tech) N. Kojima (Toyota Tech. Inst.)</p>
<p>11:15 A-7-1 A Power-gated 32bit MPU with a Power Controller Circuit Activated by Deep-sleep-mode Instruction Achieving Ultra-low Power Operation H. Koike¹, T. Ohsawa¹, S. Miura¹, H. Honjo¹, K. Kinoshita², S. Ikeda¹, T. Hanyu¹, H. Ohno¹ and T. Endoh¹, ¹Tohoku Univ. and ²NEC Corp. (Japan)</p>	<p>11:15 B-7-1 (Invited) High-density Silicon Optical Interposer for Inter-chip Interconnect T. Nakamura¹, Y. Urino¹ and Y. Arakawa², ¹PETRA and ²Univ. of Tokyo (Japan)</p>	<p>11:15 C-7-1 High Proton Conductivity in Highly Defected Perovskite-Type Oxide Thin Films Y. Zenitani, T. Nishihara, T. Asano, H. Adachi, A. Itou, H. Takeuchi, S. Badar and E. Fujii, Panasonic Corp. (Japan)</p>	<p>11:15 D-7-1 An Implantable Subminiature PWM Image Sensor Based on Body Channel Communication H. Hayami, K. Sasagawa, H. Takehara, T. Noda, T. Tokuda and J. Ohta, Nara Inst. of Sci. and Tech. (Japan)</p>	<p>11:15 E-7-1 High-speed and Low-leakage Characteristics of 60-nm C-axis Aligned Crystalline Oxide Semiconductor FET with GHz-ordered Cutoff Frequency Y. Yakubo¹, S. Nagatsuka¹, S. Matsuda¹, S. Hondo¹, Y. Hata¹, Y. Okazaki¹, Y. Yamamoto¹, M. Nagai¹, S. Sasagawa¹, T. Atsumi¹, M. Sakakura¹, T. Nakura¹, Y. Yamamoto¹ and S. Yamazaki¹, ¹Semiconductor Energy Lab. Corp., Ltd. and ²Univ. of Tokyo (Japan)</p>	<p>11:15 F-7-1 Fermi-level Unpinning at Sn/Ge Interfaces; First-principles Calculation K. Kobinata and T. Nakayama, Chiba Univ. (Japan)</p>	<p>11:15 G-7-1 Photoelectrochemical CO₂ conversion system with 3C-SiC photo-anode and Pt counter electrode J.T. Song, T. Iwasaki and M. Hatano, Tokyo Tech (Japan)</p>
<p>11:35 A-7-2 Nonvolatile FPGA Using 2T-1MTJ-Cell-Based Multi-Context Array for Power and Area Efficient Dynamically Reconfigurable Logic D. Suzuki and T. Hanyu, Tohoku Univ. (Japan)</p>	<p>11:45 B-7-2 Process Control for Silicon Photonics using 300mm SOI Wafers F. Boeuf¹, S. Cremer¹, N. Vulliet¹, B. Orlando¹, F. Leverd¹, D. Ristoiti¹, C. Baudot¹, S. Joblot¹, D. Pelissier-Tanon¹, S. Jan¹, H. Petiton¹, A. Mekis², T. Pinguer² and L. Verslegers², ¹STMicroelectronics and ²Luxtera (France)</p>	<p>11:30 C-7-2 BaTiO₃ Based Relaxor Ferroelectric Epitaxial Thin-films for High-temperature Operational Capacitors S. Kumaragurubaran¹, T. Nagata¹, K. Takahashi², S.G. Ri², Y. Tsunekawa², S. Suzuki² and T. Chikyow¹, ¹NIMS and ²COMET Inc. (Japan)</p>	<p>11:30 D-7-2 Lower Invasive in vivo Brain Insertion of the Si Neural Probe with Triangular Shank and Sharpened Tip T. Harashima¹, T. Tani², H. Kinō², N. Katayama² and T. Tanaka^{1,2}, ¹Dept. of Bioengineering and Robotics, Tohoku Univ., ²Dept. of Biomedical Engineering, Tohoku Univ. and ³Dept. of Applied Information Sciences, Tohoku Univ. (Japan)</p>	<p>11:30 E-7-2 A Novel Method for Fabrication of Sub-100nm IGZO TFTs B.S. Shie¹, H.C. Lin^{1,2} and T.Y. Huang¹, ¹NCTU and ²National Nano Device Labs. (Taiwan)</p>	<p>11:35 F-7-2 Impact of YScO₃ on Ge Gate Stack in Terms of EOT Reduction as Well as Interface C. Lu^{1,2}, C.H. Lee^{1,2}, T. Nishimura^{1,2}, K. Nagashio^{1,2} and A. Toriumi^{1,2}, ¹Univ. of Tokyo and ²JST-CREST (Japan)</p>	<p>11:30 G-7-2 Improvement in Solar Cell Efficiency via Addition of Luminescent Down-shifting Phosphors as Spectral Converters W.Y. Lin¹, H.V. Han¹, T.L. Shen¹, Y.L. Tsai¹, C.C. Lin², H.C. Kuo¹ and P.C. Yu¹, ¹Department of Photonics and Institute of Electro-Optical Engineering, NCTU and ²Institute of Photonic System, NCTU (Taiwan)</p>
<p>11:55 A-7-3 CAAC-OS-based Nonvolatile Programmable Analog Device: Voltage Controlled Oscillator Realizing Instant Frequency Switching Y. Okamoto¹, T. Nakagawa¹, T. Aoki¹, M. Kozuma¹, Y. Kurokawa¹, T. Ikeda¹, N. Yamade¹, Y. Okazaki¹, H. Miya¹, M. Fujita² and S. Yamazaki¹, ¹Semiconductor Energy Laboratory Co., Ltd. and ²VLSI Design and Education Center, Univ. of Tokyo (Japan)</p>	<p>12:00 B-7-3 Distribution of Refractive Indices of Si-Wire Waveguides Fabricated on a 300 nm SOI Wafer Using ArF Immersion Lithography M. Soma¹, Y. Tanushi¹, T. Kita¹, M. Toyama^{1,2}, M. Seki², N. Yokoyama², M. Ohtsuka² and H. Yamada¹, ¹Tohoku Univ. and ²AIST (Japan)</p>	<p>11:45 C-7-3 Luminescence Properties of Pr-doped La-GPS Grown by the Floating Zone Method R. Murakami¹, S. Kurosawa^{1,2}, T. Shishido^{1,2}, A. Suzuki¹, Y. Shoji^{1,4}, Y. Ohashi¹, J. Pejchal^{2,3}, K. Kamada^{2,4}, Y. Yokota² and A. Yoshikawa^{1,2,4}, ¹IMR, Tohoku Univ., ²NICHE, Tohoku Univ., ³Inst. of Phys. AS CR and ⁴C&A Corp. (Japan)</p>	<p>11:45 D-7-3 A Multi-Modal Implantable CMOS Imaging Device with Two-Color Light Source for Intrinsic Signal Detection in a Brain M. Haruta, Y. Sunaga, T. Yamaguchi, H. Takehara, T. Noda, K. Sasagawa, T. Tokuda and J. Ohta, Nara Inst. of Sci. and Tech. (Japan)</p>	<p>11:45 E-7-3 All Solution Processed High Performance In-Ga-Zn-O Thin Film Transistor Fabricated at Low Temperature using Microwave irradiation K.W. Jo and W.J. Cho, Kwangwoon Univ., Department of Electronic Materials Engineering (Korea)</p>	<p>11:55 F-7-3 Origin of Self-limiting Oxidation of Ge in High-Pressure O₂ at Low Temperature C.H. Lee^{1,2}, T. Nishimura^{1,2}, K. Nagashio^{1,2} and A. Toriumi^{1,2}, ¹Univ. of Tokyo and ²JST-CREST (Japan)</p>	<p>11:45 G-7-3 Photovoltaic effect in organically surface-modified nanocrystalline porous silicon layers R. Mentek¹, B. Gelloz², D. Hippo¹ and N. Koshida¹, ¹Tokyo Univ. of Agr. & Tech. and ²Nagoya Univ. (Japan)</p>
		<p>12:00 C-7-4 (Late News) Intraocular Pressure Monitoring Using Moiré Patterns Generated from a Contact Lens P.C. Lin, C.S. Ho, L.A. Wang, L.J. Wang and J.Y. Yen, National Taiwan Univ. (Taiwan)</p>	<p>12:00 D-7-4 Intraocular Pressure Monitoring Using Moiré Patterns Generated from a Contact Lens P.C. Lin, C.S. Ho, L.A. Wang, L.J. Wang and J.Y. Yen, National Taiwan Univ. (Taiwan)</p>	<p>12:00 E-7-4 Fabrication of IGZO Thin-Film Transistors with Film Profile Engineering R.J. Lyu¹, H.C. Lin^{1,2} and T.Y. Huang¹, ¹NCTU and ²National Nano Device Labs. (Taiwan)</p>	<p>12:15 F-7-4 Very Low EOT in Ge MOS Devices with High Oxidation State Interfacial Layer C.H. Lin, K.S. Chang-Liao, C.C. Li, L.J. Liu and T.M. Lee, National Tsing Hua Univ. (Taiwan)</p>	<p>12:00 G-7-4 Fabrication And Optical Characterization Of α-Germanium Nano Disk Structure Using Bio-Template And Neutral Beam Etching for Solar Cell Application M.T. Chentfi^{1,2}, T. Fujii^{1,3}, T. Okada¹, T. Isoda¹, K. Itoh^{2,4}, H. Endo³, Y. Hoshi⁵, N. Usami⁶ and S. Samukawa^{1,2,6}, ¹Inst. of Fluid Sci., Tohoku Univ., ²CREST Japan Sci. and Tech. Agency, ³Honda R&D Co., Ltd., ⁴Keio Univ., ⁵Nagoya Univ. and ⁶WPI-Advanced Inst. for Materials Res., Tohoku Univ. (Japan)</p>
			<p>12:15 D-7-5 Improvement of dynamic range on filter-less fluorescence sensor with body biasing technique Y. Moriwaki¹, K. Takahashi¹, I. Akita¹, M. Ishida^{1,2} and K. Sawada^{1,2}, ¹Toyohashi Univ. of Tech. and ²Electronics-Inspired Interdisciplinary Res. Inst. (Japan)</p>	<p>12:15 E-7-5 Impact of Oriented Crystalline InGaZnO Semiconductor on Electrical Properties of Thin Film Transistor S.S. Yen¹, H.H. Hsu¹, P. Chiou¹, C.H. Cheng², C.Y. Chang³, Y.C. Lai³, C.P. Chang³, H.H. Lu³, C.S. Chuang² and Y.H. Lin², ¹NCTU, ²National Taiwan Normal Univ. and ³AU Optronics Corp. (Taiwan)</p>	<p>12:15 G-7-5 Built-in Low Pressure Drop Liquid Cooling with Internal Graphene Fins on PV/T and CPV modules: Parametric Analysis and Experimental Study P. Jarumongkonsak and Y.Y. Yan, Univ. of Nottingham (UK)</p>	

Thursday, September 11

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
<p>H-7: Quantum Transport (2) (11:15-12:15) Chairs: T. Ota (NTT) T. Nakaoka (Sophia Univ.)</p>	<p>J-7: Noise (11:15-12:15) Chairs: Y. Fukuzaki (SONY) M. Masahara (AIST)</p>	<p>K-7: Characterization (11:15-12:30) Chairs: M. Kitamura (Kobe Univ.) H. Kajii (Osaka Univ.)</p>			<p>P-7: Nanocarbon Based FETs & ICs (11:15-12:15) Chairs: Y. Ohno (Nagoya Univ.) K. Maehashi (Osaka Univ.)</p>
<p>11:15 H-7-1 Thermal-Noise Suppression in Nanometer-Scale Si Field-Effect Transistors by Feedback Control with Single-Electron Resolution K. Chida, K. Nishiguchi, G. Yamahata and A. Fujiwara, NTT BRL (Japan)</p>	<p>11:15 J-7-1 Ultra Low-Frequency Noise in Vertical MOSFETs Having Tunable Threshold Voltage Fabricated with 60 nm CMOS Technology on 300 mm Wafer Process T. Imamoto^{1,2} and T. Endoh^{1,2,3}, ¹Graduate School of Engineering, Tohoku Univ., ²ACCEL, JST and ³Center for Innovative Integrated Electronic Systems, Tohoku Univ. (Japan)</p>	<p>11:15 K-7-1 (Invited) Exciplex Forming Co-Hosts as a Platform for OLEDs with Ultimate Efficiency J.-J. Kim, Seoul National Univ. (Korea)</p>			<p>11:15 P-7-1 (Invited) Carbon Nanotube FETs for Robust Digital Logic Systems M. Shulaker, G. Hills, H. Wei, H.-Y. Chen, H.-S.P. Wong and S. Mitra, Stanford Univ. (USA)</p>
<p>11:30 H-7-2 Charge Manipulations in Si-Based Quantum Dot Qubit Devices with Single Electron Transistors: Theory and Experiment A. Andreev¹, T. Ferrus¹, S. Das¹, T.Y. Yang¹, T. Koderá², S. Ihara², K. Horibe², S. Oda² and D. Williams¹, ¹Hitachi Cambridge Lab. and ²Tokyo Tech (UK)</p>	<p>11:35 J-7-2 Comprehensive Studies on the Accuracy of Traps Characterization by Using Advanced Random Telegraph Noise Simulator Y. Higashi, K. Matsuzawa and T. Ishihara, Toshiba Corp. (Japan)</p>	<p>11:45 K-7-2 Evaluation of Layer-by-layer Thin Film of PDADMAC:Alcian Blue and PSS Using Surface Plasmon Resonance and Optical Waveguide Spectroscopies M. Ishigooka, T. Ito, K. Shinbo, Y. Ohdaira, A. Baba, K. Kato and F. Kaneko, Niigata Univ. (Japan)</p>			<p>11:45 P-7-2 Sub-10 μm Top-Gate Carbon Nanotube Thin-Film Transistors Fabricated by Flexographic Printing Process M. Maeda¹, K. Higuchi¹, S. Kishimoto¹, T. Tomura², M. Takesue², K. Hata² and Y. Ohno¹, ¹Nagoya Univ. and ²Bando Chemical Indus. Ltd. (Japan)</p>
<p>11:45 H-7-3 Effect of Phase Inversion on Quantum Transport in Group IV Two-Dimensional U-shape Device M. Sadi, G. Gupta and G. Liang, NUS (Singapore)</p>	<p>11:55 J-7-3 Experiment Study on Random Telegraph Signal Noise in (110) pMOSFETS with 1 nm EOT J. Chen and Y. Mitani, Toshiba Corp. (Japan)</p>	<p>12:00 K-7-3 Establishing pn Junction of Doped Organic Semiconductors by Wet Process K. Fujita, N. Mizutani and T. Hayashida, Kyushu Univ. (Japan)</p>			<p>12:00 P-7-3 Wafer Scale Fabrication of Transistors using CVD-Grown Graphene and its Application to Inverter Circuit S. Nakaharai^{1,2}, T. Iijima², S. Ogawa², K. Yagi², N. Harada², K. Hayashi², D. Kondo², M. Takahashi², S.L. Li¹, K. Tsukagoshi¹, S. Sato² and N. Yokoyama², ¹NIMS and ²AIST (Japan)</p>
<p>12:00 H-7-4 (Late News) Gate-Controlled Semimetal-Topological Insulator Transition in an InAs/GaSb Heterostructure K. Suzuki, Y. Harada, K. Onomitsu and K. Muraki, NTT Basic Research Labs., NTT Corp. (Japan)</p>		<p>12:15 K-7-4 Hybridization of HOMO and Next HOMO in Organic Semiconductor Crystals Revealed by Band Calculations H. Matsui¹, T. Okamoto^{1,2}, C. Mitsui¹, M. Yamagishi^{1,3}, H. Sato⁴, A. Yamano⁴ and J. Takeya¹, ¹Univ. of Tokyo, ²PRESTO, JST, ³Toyama National College of Technology and ⁴Rigaku Corp. (Japan)</p>			

Thursday, September 11

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
<p>A-8: MTJ/MRAM (14:00-15:10) Chairs: T. Endoh (Tohoku Univ.) S. Shuto (Toshiba)</p>		<p>C-8: Growth of Germanium Based Semiconductors (14:00-15:15) Chairs: N. Fujimura (Osaka Pref. Univ.) Y. Hotta (Univ. of Hyogo)</p>		<p>E-8: III-V MOS Technologies (14:00-15:15) Chairs: M. Kuzuhara (Univ. of Fukui) N. Hara (Fujitsu Labs.)</p>		<p>G-8: Silicon Photovoltaics (14:00-15:15) Chairs: K. Ohdaira (JAIST) S. Yata (Panasonic)</p>
<p>14:00 A-8-1 (Invited) Switching current and thermal stability of perpendicular magnetic tunnel junction with MgO/CoFeB/Ta/CoFeB/MgO recording structure scaling down to 1X nm H. Sato^{1,2}, T. Yamamoto^{1,3}, E.C.I. Enobio^{1,4}, M. Yamanouchi^{1,4}, S. Ikeda^{1,2,4}, S. Fukami^{1,2}, K. Kinoshita¹, F. Matsukura^{3,1,4}, N. Kasai¹ and H. Ohno^{1,2,4,5}, ¹CSIS, Tohoku Univ., ²CHES, Tohoku Univ., ³ULVAC, Inc., ⁴Lab. for Nanoelectronics and Spintronics, RIEC, Tohoku Univ. and ⁵WPI-AIMR, Tohoku Univ. (Japan)</p> <p>14:30 A-8-2 Impact of Sub-Volume Excitation for Improving Overdrive Delay Product in Sub-40nm p-MTJ and Its Beyond S. Ohuchida¹, K. Ito² and T. Endoh^{1,2}, ¹Graduate School of Engineering, Tohoku Univ. and ²Center for Innovative Integrated Electronic Systems, Tohoku Univ. (Japan)</p> <p>14:50 A-8-3 A 500ps/8.5ns Array Read/Write Latency 1Mb Twin 1T1MTJ STT-MRAM designed in 90nm CMOS/40nm MTJ Process with Novel Positive Feedback S/A Circuit T. Ohsawa¹, S. Miura², H. Honjo³, S. Ikeda¹, T. Hanyu¹, H. Ohno¹ and T. Endoh¹, ¹Tohoku Univ. and ²NEC Corp. (Japan)</p>		<p>14:00 C-8-1 Growth of Two Inch Si_{0.5}Ge_{0.5} Bulk Single Crystals K. Kinoshita¹, Y. Arai¹, O. Nakatsuka¹, K. Taguchi³, H. Tomioka³, R. Tanaka² and S. Yoda¹, ¹Japan Aerospace Exploration Agency, ²Nagoya Univ. and ³Advanced Engineering Services Co. Ltd. (Japan)</p> <p>14:15 C-8-2 Formation and Energy Band Engineering of Ternary Alloy Ge_{1-x-y}Sn_xC_y Layers T. Yamaha¹, H. Oda¹, M. Kurosawa^{1,2}, W. Takeuchi¹, N. Taoka¹, O. Nakatsuka¹ and S. Zaima¹, ¹Nagoya Univ. and ²JSPS Research Fellow (Japan)</p> <p>14:30 C-8-3 Impact of Hydrogen Surfutant Epitaxy and Annealing on Crystallinity of Epitaxial Ge_{1-x}Sn_x Layers T. Asano^{1,2}, N. Taoka³, K. Hozaki¹, W. Takeuchi¹, M. Sakashita¹, O. Nakatsuka¹ and S. Zaima¹, ¹Nagoya Univ., ²JSPS Research Fellow and ³IHP (Japan)</p> <p>14:45 C-8-4 Melting-Sn Induced Seeding-Processing for Low-Temperature Lateral-Crystallization of a-GeSn on Insulating Substrate H. Chikita¹, R. Matsumura^{1,2}, Y. Kai¹, T. Sadoh¹ and M. Miyao¹, ¹Kyushu Univ. and ²JSPS Research Fellow (Japan)</p> <p>15:00 C-8-5 Formation of Large-Grain Ge-Based Group-IV Crystals on Insulator by Seedless Rapid-Melting Growth in Solid-Liquid-Coexisting Temperature Region R. Matsumura^{1,2}, Y. Kai¹, H. Chikita¹, Y. Sadoh¹ and M. Miyao¹, ¹Kyushu Univ. and ²JSPS Research Fellow (Japan)</p>		<p>14:00 E-8-1 (Invited) High Performance III-V MOS Technologies M.J.W. Rodwell¹, S. Lee¹, C.-Y. Huang¹, D. Elias¹, V. Chobpattana², B.J. Thibeault¹, W. Mitchell¹, S. Stemmer² and A.C. Gossard², ¹ECE Dept. Univ. of California, Santa Barbara and ²Materials Dept. Univ. of California, Santa Barbara (USA)</p> <p>14:30 E-8-2 Hole Mobility Enhancements in Strained In_xGa_{1-x}Sb Heterostructure PMOSFET P.Y. Chang¹, X.Y. Liu², L. Zeng² and G. Du², ¹School of Electronic and Computer Eng., Peking Univ. and ²Inst. of Microelectronics, Peking Univ. (China)</p> <p>14:45 E-8-3 Body Width Dependence of Subthreshold Slope and On-Current in GaAsSb/InGaAs Double-Gate Vertical Tunnel FETs K. Ohashi, M. Fujimatsu and Y. Miyamoto, Tokyo Tech (Japan)</p> <p>15:00 E-8-4 RF Modeling of III-V FINFETs E. Lind, C.B. Zota and L.E. Wernersson, Lund Univ. (Sweden)</p>	<p>14:00 G-8-1 (Invited) Development of Heterojunction Back Contact Si Solar Cells J. Nakamura, Sharp Corp. (Japan)</p> <p>14:30 G-8-2 Surface Passivation of c-Si by Nanoengineered AlOx toward Low-Cost, High-Efficiency c-Si Solar Cells H. Lee^{1,4}, N. Sawamoto¹, K. Ueda², Y. Enomoto², K. Arafune^{3,4}, H. Yoshida^{2,4}, S. Satoh^{2,4}, T. Nagata³, T. Chikyow³ and A. Ogura^{1,4}, ¹Meiji Univ., ²Univ. of Hyogo, ³NIMS and ⁴CREST, JST (Japan)</p> <p>14:45 G-8-3 Epitaxial Growth of Germanium Thin Films on Crystal Silicon Substrates by Solid Phase Crystallization M. Kanai and M. Isomura, Tokai Univ. (Japan)</p> <p>15:00 G-8-4 Degradation by Acetic Acid for Crystalline Si Photovoltaic Modules N. Uchiyama and A. Masuda, AIST (Japan)</p>	

Thursday, September 11

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
		<p>K-8: OTFT (14:00-15:00) Chairs: J. Takeya (Univ. of Tokyo) H. Endoh (NEC)</p>	<p>M-8: Wireless Circuits (14:00-15:10) Chairs: K. Okada (Tokyo Tech) T. Minotani (NTT TELECON)</p>	<p>N-8: Device Modeling and Characterization (14:00-15:15) Chairs: C.-F. Huang (National Tsing Hua Univ.) H. Umezawa (AIST)</p>	<p>P-8: Nanocarbon Growth & Applications (14:00-15:00) Chairs: K. Nagashio (Univ. of Tokyo) S. Nakaharai (NIMS)</p>
		<p>14:00 K-8-1 Pentacene Thin-Film Transistors with Controlled Threshold Voltages and Their Application to Pseudo CMOS Inverters <i>Y. Kimura¹, M. Kitamura^{1,2} and Y. Arakawa², ¹Kobe Univ. and ²Univ. of Tokyo (Japan)</i></p>	<p>14:00 M-8-1 (Invited) Ultra-Wideband Technology for Short-Range Communications <i>W. Rhee, X. Chen, D. Liu, F. Chen and Z. Wang, Tsinghua Univ. (China)</i></p>	<p>14:00 N-8-1 (Invited) Accurate physical compact models of high-voltage/ power semiconductor devices for efficient design of performance-optimized circuits and systems <i>H.J. Mattausch, T. Umeda, H. Kikuchihara and M. Miura-Mattausch, Hiroshima Univ. (Japan)</i></p>	<p>14:00 P-8-1 Development of Two-dimensional Tactile Sensor Using Carbon Nanotubes <i>M. Ohnishi, M. Yang, T. Nozaki, K. Suzuki and H. Miura, Tohoku Univ. (Japan)</i></p>
		<p>14:15 K-8-2 Single-Crystal Structure and Transport Analyses of Rubrene under High Pressure <i>J. Tsurumi¹, K. Sakai¹, H. Matsui¹, Y. Okada¹, T. Okamoto¹, H. Sato², A. Yamano², K. Sugimoto³, A. Fujiwara³ and J. Takeya¹, ¹Univ. of Tokyo, ²Rigaku Corp. and ³JASRI (Japan)</i></p>	<p>14:30 M-8-2 A 0.5-V 5.8-GHz Highly Linear VCO with Back-Gate Tuning Technique <i>S. Ikeda, S. Lee, H. Ito, N. Ishihara and K. Masu, Tokyo Tech (Japan)</i></p>	<p>14:30 N-8-2 Two-component model for threshold voltage shifts of SiC MOSFETs under negative bias stress <i>M. Matsumura, K. Kobayashi, Y. Mori, N. Tega, A. Shima, D. Hisamoto and Y. Shimamoto, Hitachi, Ltd., (Japan)</i></p>	<p>14:15 P-8-2 Enhancement of Carrier Injection in OLEDs Utilizing Field Concentration to Carbon Nanotubes <i>T. Yamada, S. Kishimoto and Y. Ohno, Nagoya Univ. (Japan)</i></p>
		<p>14:30 K-8-3 Estimating the Density of Trap States in the Middle of the Bandgap using Ambipolar Organic Field-Effect Transistors <i>R. Haeusermann¹, S. Chauvin¹, A. Facchetti², Z. Chen² and B. Batlogg¹, ¹ETH Zurich and ²Polyera Corp. (Switzerland)</i></p>	<p>14:50 M-8-3 A Varactor-Less and Dither-Less LC-Digitally Controlled Oscillator with 9-bit Fine Bank, 0.26 mm² Area, and 6.7 kHz Frequency Resolution <i>Z. Xu, M. Sugawara, K. Mori, M. Miyahara and A. Matsuzawa, Tokyo Tech (Japan)</i></p>	<p>14:45 N-8-3 High-temperature and High-voltage characteristics of Cu/ diamond Schottky diodes <i>K. Ueda, K. Kawamoto, S. Aichi, M. Nishiwaki and H. Asano, Nagoya Univ. (Japan)</i></p>	<p>14:30 P-8-3 Graphene Synthesis by Laser-Annealing Technique Using Co Catalyst <i>Y. Ishibashi, K. Koshida, Y. Kanai, Y. Ohno, K. Maehashi, K. Inoue and K. Matsumoto, Osaka Univ. (Japan)</i></p>
		<p>14:45 K-8-4 Effects of Deposition Pressure on the Characteristics of Organic Thin-Film Transistors Fabricated with Film Profile Engineering <i>M.H. Wu¹, H.C. Lin^{1,2} and T.Y. Huang¹, ¹NCTU and ²National Nano Device Lab. (Taiwan)</i></p>		<p>15:00 N-8-4 Microwave reflectivity from 4H-SiC in the high injection condition: Impacts of the electron-hole scattering <i>M. Kato, Y. Mori and M. Ichimura, Nagoya Inst. of Tech. (Japan)</i></p>	<p>14:45 P-8-4 (Late News) Subthreshold transport in mono- and multi-layered MoS₂ FETs <i>F. Nan, K. Nagashio and A. Toriumi, The Univ. of Tokyo (Japan)</i></p>

Thursday, September 11

2F Conv. Hall 200	2F 201A	2F 201B	2F 202A	4F 405	4F 406	4F 403
<p>A-9: Flash Memory (15:30-16:40) Chairs: S. Shuto (Toshiba) M. -H. Lee (Macronix)</p>		<p>C-9: Growth Processing of Group IV Semiconductors (15:30-16:15) Chairs: Y. Hotta (Univ. of Hyogo) N. Fujimura (Osaka Pref Univ.)</p>				
<p>15:30 A-9-1 (Invited) Trends on Advanced Semiconductor Memories <i>A. Nitayama, Tohoku Univ. (Japan)</i></p>		<p>15:30 C-9-1 Deposition of Thin Si, Ge, and SiGe Films by Ballistic Hot Electron Reduction <i>M. Yagi¹, R. Suda¹, A. Kojima¹, R. Mentek¹, N. Mori², J. Shirakashi¹ and N. Koshida¹, ¹Tokyo Univ. of Agri. & Tech. and ²Osaka Univ. (Japan)</i></p>				
<p>16:00 A-9-2 Substrate Doping Concentration Dependence on Random Telegraph Noise Spatial and Statistical Distribution in 30nm NAND Flash Memory <i>T. Tomita and K. Miyaji, Shinshu Univ. (Japan)</i></p>		<p>15:45 C-9-2 Grain Growth Control by Micro-Thermal-Plasma- Jet Irradiation to Very Narrow Amorphous Silicon Strips and Its Application to Thin Film Transistors <i>S. Yamamoto, S. Morisaki, S. Hayashi, T. Nakatani and S. Higashi, Hiroshima Univ. (Japan)</i></p>				
<p>16:20 A-9-3 Comparative Study of Floating Gate Type 3D Fin-Channel Flash Memories with Different Channel Shapes and Interpoly Dielectric Layers <i>Y.X. Liu¹, T. Nabatame², N. Nguyen², T. Matsukawa¹, K. Endo¹, S. O'uchi¹, J. Tsukada¹, H. Yamauchi¹, Y. Ishikawa¹, W. Mizubayashi¹, Y. Morita¹, S. Migita¹, H. Ota¹, T. Chikyow² and M. Masahara¹, ¹AIST and ²NIMS (Japan)</i></p>		<p>16:00 C-9-3 Versatile Doping Technique for Diamond by Solid Dopant Immersion During Microwave Plasma CVD <i>T. Tamura¹, T. Yanase¹, T. Nagahama¹, S. Sato² and T. Shimada¹, ¹Hokkaido Univ. and ²Arios Inc. (Japan)</i></p>				

Thursday, September 11

4F 404	1F 101	2F 202B	3F 304	4F 401	4F 402
			<p>M-9: Image Sensors (15:30-16:45) Chairs: K. Kagawa (Shizuoka Univ.) K. Takeuchi (Chuo Univ.)</p>		<p>P-9: 2D Materials & Devices (15:30-16:30) Chairs: H. Miyazaki (Toshiba) T. Kawai (NEC)</p>
			<p>15:30 M-9-1 300 μs Short Interval Continuous Capturing Image Sensor with C-axis Aligned Crystalline Oxide Semiconductor FET/ p-channel Silicon FET Stacked CMOS Structure S. Yoneda, Y. Okamoto, T. Nakagawa, S. Maeda, T. Aoki, M. Kozuma, T. Ohmaru, H. Inoue, S. Nagatsuka, Y. Kurokawa, T. Ikeda, Y. Suzuki, N. Yamada, H. Miyairi and S. Yamazaki, Semiconductor Energy Lab. Corp., Ltd. (Japan)</p> <p>15:50 M-9-2 A Platform for Backside Illuminated CMOS Image Sensors for UV and Visible Applications B. Vereecke, C. Cavaco, K. De Mynck, L. Haspelslagh, K. Minoglou, D. Sabuncuoglu, K. Tack and H. Osman, imec (Belgium)</p> <p>16:10 M-9-3 A Micro-Machined IR Thermal Detector Using Torsional Oscillation: Improvement of Resonator Profile for High Sensitivity J.H. Jeong¹, S. Kumagai^{1,2,3}, I. Yamashita^{2,3}, Y. Uraoka^{2,3} and M. Sasaki^{1,3}, ¹Toyota Tech. Inst., ²NAIST and ³CREST-JST (Japan)</p> <p>16:30 M-9-4 (Late News) Leakage-Delay Analysis of Monolithic 3D Logic Circuits using Ultra-Thin-Body InGaAs/Ge MOSFETs considering Interlayer Electrical Coupling K.-C. Yu, M.-L. Fan, P. Su and C.-T. Chuang, National Chiao Tung Univ. (Taiwan)</p>		<p>15:30 P-9-1 Multi-Layered MoS₂ Thin Film Formed by High-Temperature Sputtering for Enhancement-Mode nMOSFETs T. Ohashi¹, K. Suda², S. Ishihara², N. Sawamoto², S. Yamaguchi¹, K. Matsuura¹, K. Kakushima¹, N. Sugii¹, A. Nishiyama¹, Y. Kataoka¹, K. Natori¹, K. Tsutsui¹, H. Iwai¹, A. Ogura² and H. Wakabayashi¹, ¹Tokyo Tech and ²Meiji Univ. (Japan)</p> <p>15:45 P-9-2 Direct Deposition of High-k Y₂O₃ on h-BN by Atomic Layer Deposition N. Takahashi¹, K. Watanabe², T. Taniguchi² and K. Nagashio¹, ¹Univ. of Tokyo and ²NIMS (Japan)</p> <p>16:00 P-9-3 Epitaxial Graphene Devices for Scanning Probe Measurements A. Iagallo¹, S. Tanabe², S. Roddaro¹, M. Takamura², Y. Sekine², H. Hibino², V. Miseikis³, C. Coletti², V. Piazza², F. Beltram¹ and S. Heun¹, ¹NEST, Istituto Nanoscienze-CNR and Scuola Normale Superiore, ²NTT Basic Res. Lab., ³NTT Corp. and ³Center for Nanotechnology Innovation @ NEST, Istituto Italiano di Tecnologia (Italy)</p> <p>16:15 P-9-4 Low Pull-in Voltage Graphene Contact Switch Fabricated without Acid-Etching J. Sun¹, W.Z. Wang¹, M. Muruganathan¹ and H. Mizuta^{1,2}, ¹AIST and ²Univ. of Southampton (Japan)</p>

RUMP SESSION A (Room 201A+B):**“Beyond wearable electronics”**

The communication tools that can be worn like clothes are called wearable devices (“wearables”), and they are eyed by the global researchers as detonators that lead ICT in the next generation. Recently, global companies introduce wearable computers which resemble standard eyeglasses or watches one after another. The market eye them for their potentials to sweep over smart phones or tablet PCs. New services of wearable are actively brought up or brain stormed in the world as well. For example, wearable devices are not just downsized communication tools, but, additional unique features of wearables, such as health-monitoring, are being combined. The strength of wearables that they do not impair the movement of the user allows new service concepts to arise; the new services are body condition monitoring during exercises or technical instructional supports during maintenances.

Though, various neo-wearables are introduced and gain global attentions, their goals or directions are somewhat not clear. Furthermore, just reducing electricity consumption and downsizing, such trends in conventional information communication terminals, are not enough for this new apparatuses. Some specific requirements imposed for the wearables are their softness and designs, nonetheless, what is expected of the devices and their materials remain less well-defined.

In this Rump session, we name the new wearables “Beyond wearable electronics” as they exceed the present eyeglass-types or watch-types. Our main focus is to determine the direction of electronic materials and devices, especially on the possibilities of flexible devices and stretchable materials, since this discussion is inevitable for realizing “Beyond wearable electronics”.

Organizer: Akira Fujiwara (NTT Basic Res. Labs.)
Moderator: Takao Someya (The University of Tokyo)
Panelists: Magnus Berggren (Linköping University), Motoki Nakano (Activelink Co., Ltd)
Hiroshi Onodera (The University of Tokyo), Koji Sumitomo (NTT Basic Res. Labs.)
Tsutomu Terada (Kobe University)

RUMP SESSION B (Room 202A+B):**“Change the future through the strong collaborations among our society”**

An information communication technology (ICT), based on a solid state device and materials, has been rapidly and globally changing the society. To accelerate the innovations more, the collaborations among industry and academia are strongly expected. In this rump session, we invited the excellent panelists, who have managed the one of the COI program to change the future society.

(COI: Center-of-Innovation program led by MEXT and JST of Japan)

Organizer / Moderator: Hitoshi Wakabayashi (Tokyo Institute of Technology)
Panelists: Yoshinobu Baba (Nagoya University), Tetsuo Endoh (Tohoku University)
Chris Van Hoof (imec), Shoji Kawahito (Shizuoka University)
Kazuhiko Matsumoto (Osaka University), Shunri Oda (Tokyo Institute of Technology)

Short Course A (Convention Hall 300):**“Trends for Future Power Devices”****Organizer: Shizuo Fujita (Kyoto University)**

Evolution of power devices is undoubtedly inevitable for supporting future sustainable society, but we have not clearly drawn a roadmap which devices (materials and structures) should take which application fields; this may be due to the continuing competition between Si-based and wide band gap semiconductor-based devices both in their performance and cost. In this course we intend the participants to learn the issues on which especially the wide band gap semiconductors are, or might be facing for their future wide applications, based on their most up-to-date achievements and science lying, so that they can imagine their own roadmap for the future of power devices.

13:00-14:20 “Basic Requirements and Physics of Power Devices”

Prof. Jun Suda (Kyoto University)

Break (10 min.)

14:30-15:30 “Trends in the Development of SiC Power Devices by Manufactures”

Prof. Hidekazu Yamamoto (Chiba Institute of Technology)

Break (10 min.)

15:40-16:40 “High-speed switching operation of wide band-gap semiconductor and its circuit application”

Prof. Nobuo Satoh (Chiba Institute of Technology)

16:40-17:20 “Gallium oxide-based electronics: Present status and future prospects”

Dr. Masataka Higashiwaki (NICT)

Short Course B (Convention Hall 200):**“Functional Devices in Integrated Systems”****Organizer: Hitoshi Wakabayashi (Tokyo Institute of Technology)**

Evolution of functional device has been strongly expected to achieve in integrated systems, such as a smart phone, wearable electronics and beyond. In this short course, the SSDM has invited five excellent lecturers not only more Moore but also more than Moore areas to discuss in the same room.

13:00-13:05 Introduction on topics

13:05-13:55 “Multigate Transistors: Pushing Moore's law to the limit”

Dr. Jean-Pierre Colinge (TSMC)

13:55-14:45 “Volatile and Non-volatile Semiconductor Memories: Past, Present and Future Outlook”

Dr. Toshiharu Watanabe (Toshiba Corporation)

Break (15 min.)

15:00-15:50 “Co-designs of Devices and Circuits to improve performances of RF/Analog and High voltage I/Os in SoC/MCUs”

Dr. Yoshihiro Hayashi (Renesas Electronics Corporation)

15:50-16:40 “Recent Challenges and Solutions in Image Sensor Technology”

Dr. Hideo Nomura (Sony Corporation)

16:40-17:30 “Integrated MEMS Technology for Construction of Diverse Functional Devices”

Prof. Hidekuni Takao (Kagawa University)

INSTRUCTION FOR SPEAKERS

Oral Presentation:

Time Schedule

	Total session time	Presentation time	Discussion time
Invited	30 min.	25 min.	5 min.
Regular-1: Area1-5	20 min.	15 min.	5 min.
Regular-2: Area 6-15	15 min.	10 min.	5 min.
Late News	15 min.	10 min.	5 min.

BELL: First: Warning, Second: End of speech, Third: End of the discussion.

Audio-Visual Equipment

The following equipments are ready at each session room during SSDM2014:

- * LCD projector
- * PC (laptop computer), Windows 7 Professional, PowerPoint 2007-2013 and PDF
- * Projection laser pointer

Uploading Your Presentation

The most important action for presenting authors is to upload their presentation file to the PC in each session room, using their own USB thumb drive. The use of personal PCs is prohibited. It is the presenter's responsibility to **upload his/her presentation file as soon as possible in each session room at any break** well in advance to the session of presentation. If the session chair cannot find your presentation file at the beginning of the session, your presentation will be withdrawn. The file must be compatible with Microsoft PowerPoint or Adobe Acrobat on Microsoft Windows.

Poster Presentation:

Presenting Your Poster

Poster sessions are scheduled for Wednesday, September 10 from 14:00 to 16:00 at Multi-Purpose Hall and Conference Room 102 on the 1st floor. Poster boards will be available with identifying labels from 11:00 on September 10. Authors are requested to prepare and set-up their posters by 14:00 on September 10. After the session, authors must immediately remove their posters by 17:30 on September 10. Please note that after 17:30 all remaining posters will be destroyed. Each poster board is 1,500mm wide and 2,100mm high. Pushpins will be available. The identifying label gives only paper session number. Therefore, please display the paper title, author names and affiliations on the poster. Authors are requested to stay near by their posters during the poster session for discussions.

Short Oral Presentation for Poster Presenters

All poster presenters must give short oral presentation on September 10. The presentation time should be less than 3 minutes, including the time needed to move on to the next presenter. To ensure smooth progress of the session, while one presenter is giving his/her presentation, next presenter should wait nearby in line for their turn. Only a PC projector will be made available.

Short oral presentations will be held as follows:

Area 1(PS-1) 4F 406	Area 6(PS-6) 4F 405	Area 11(PS-11) 2F 202A
Area 2 & 13 (PS-2, PS-13) 4F 402	Area 7(PS-7) 2F 201A	Area 14(PS-14) 4F 401
Area 3(PS-3) 1F 101	Area 8(PS-8) 2F 201B	Area 15(PS-15) 4F 403
Area 4(PS-4) 2F Convention Hall 200	Area 9(PS-9) 4F 404	
Area 5 & 12 (PS-5, PS-12) 3F 304	Area 10(PS-10) 2F 202B	

Confidentiality:

We will delete all electronic files from the SSDM computers after presentations are completed. SSDM will not publish or distribute the presentation material.

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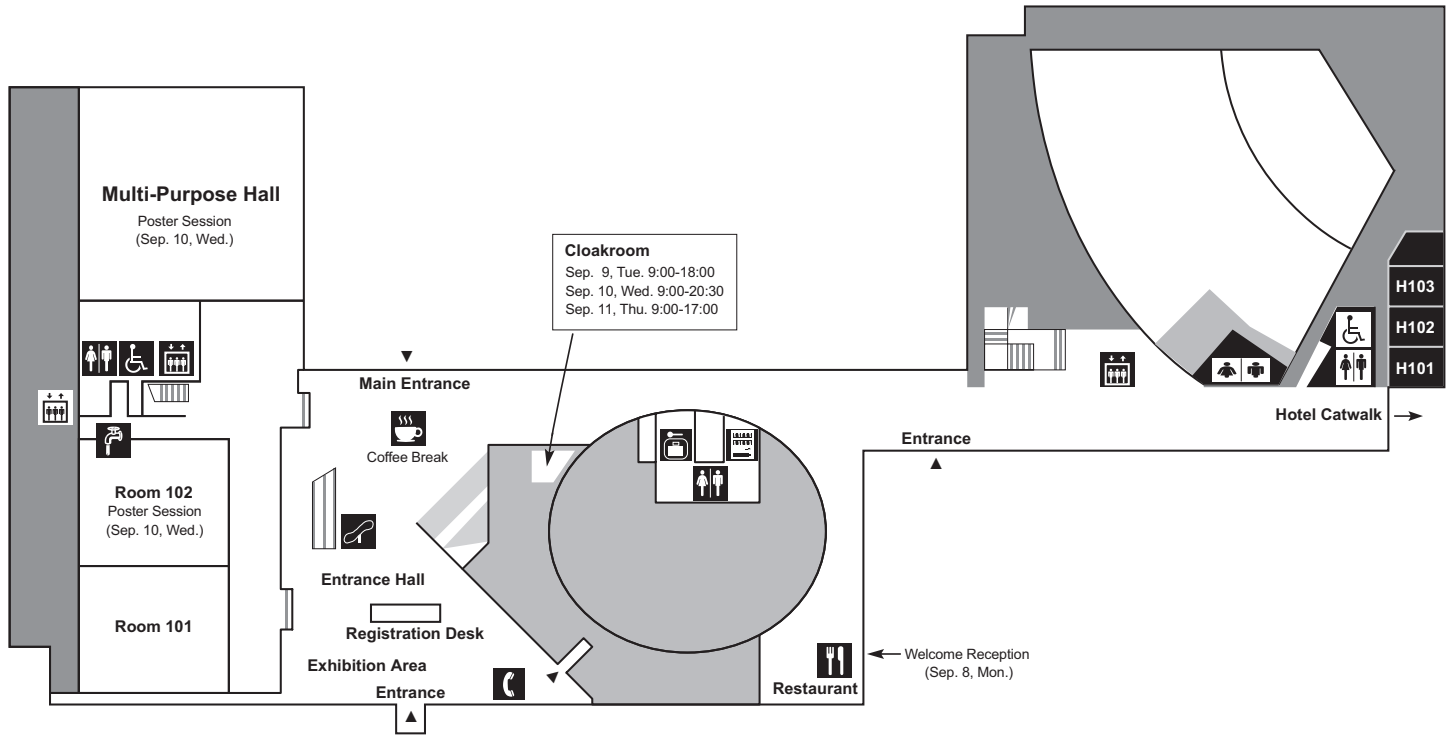
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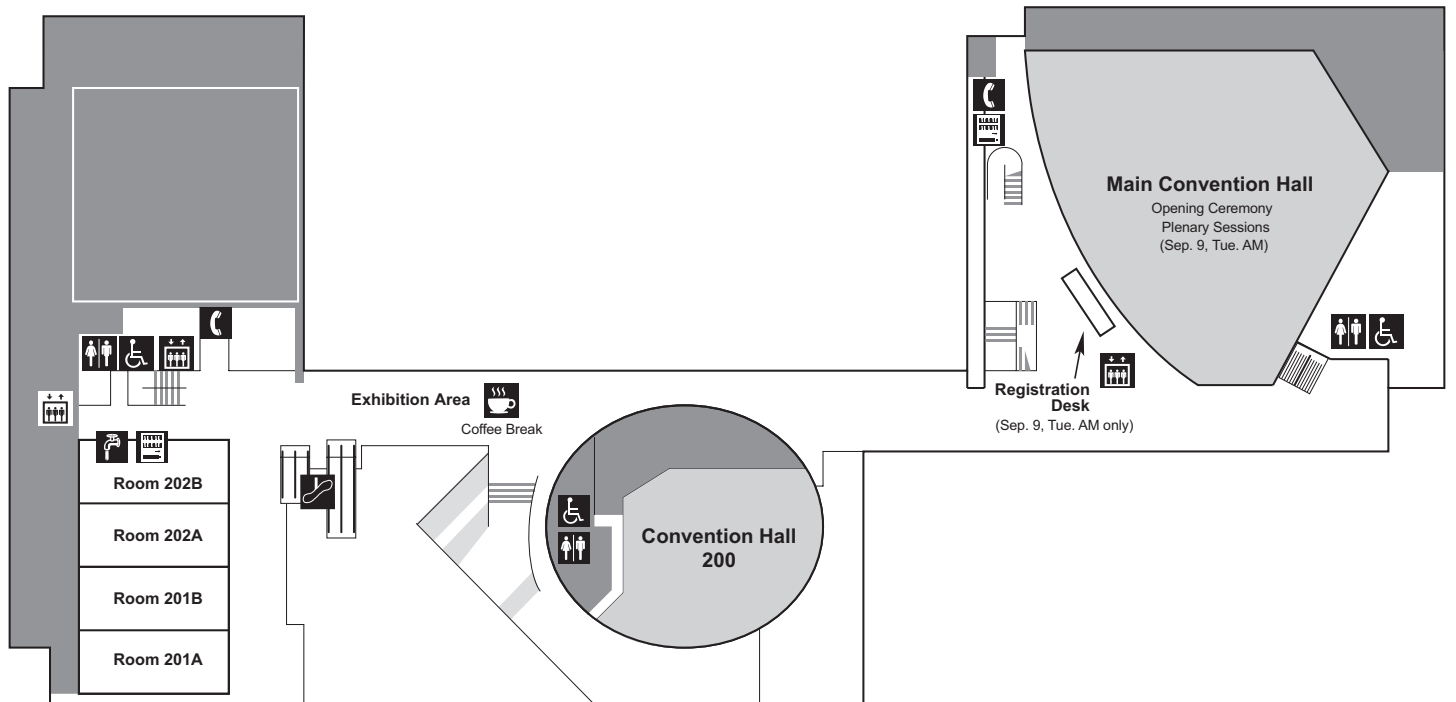
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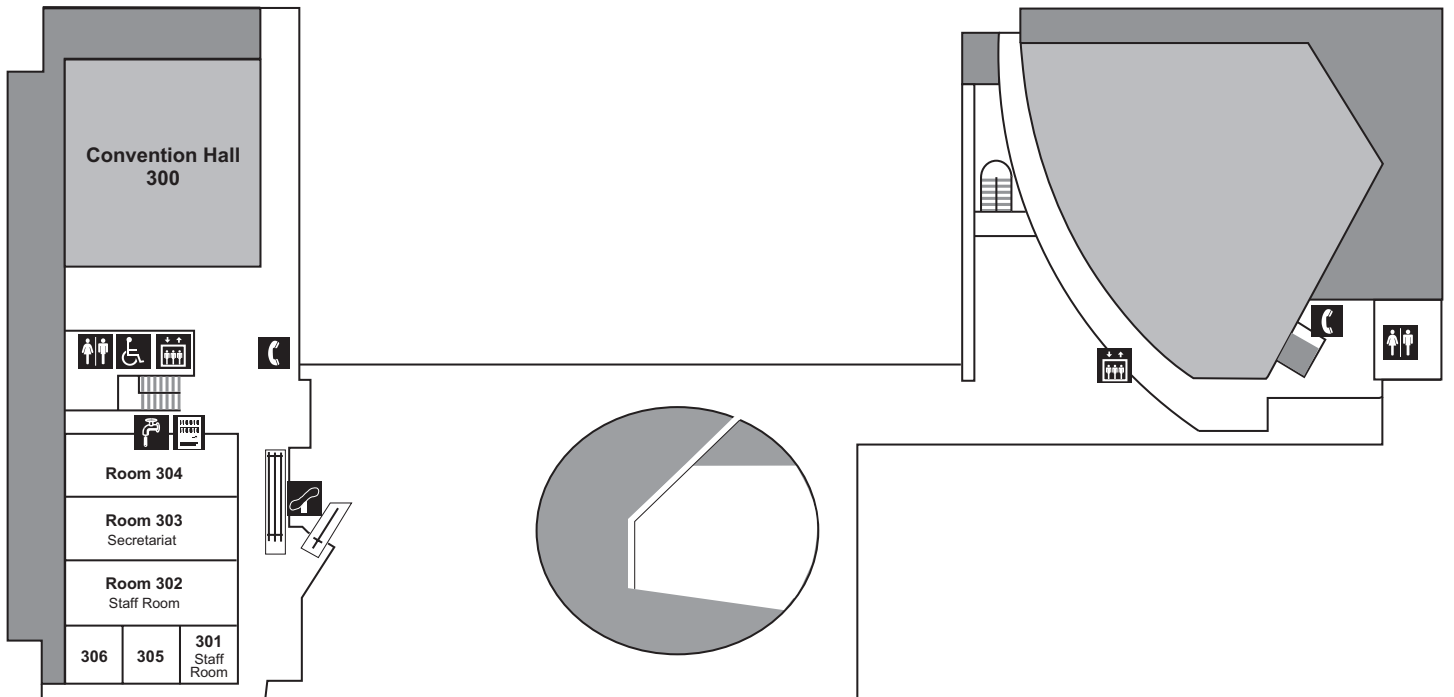
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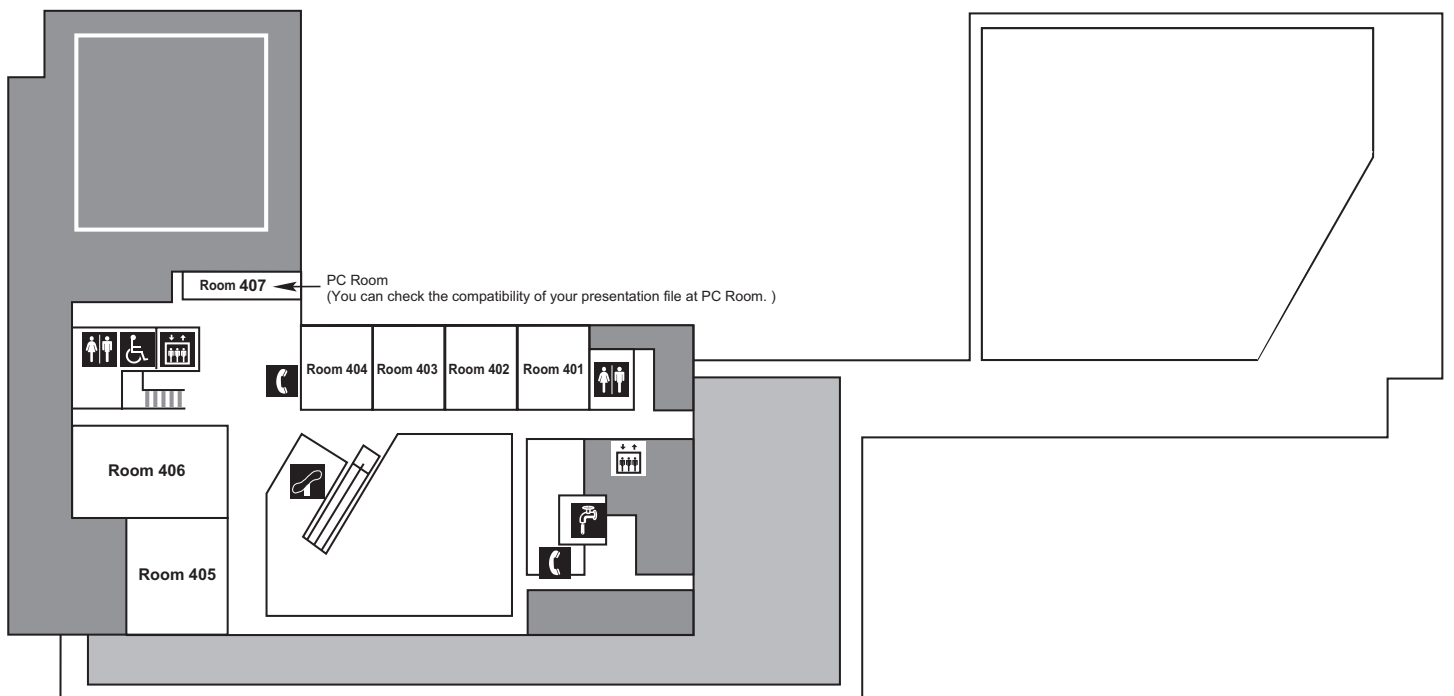
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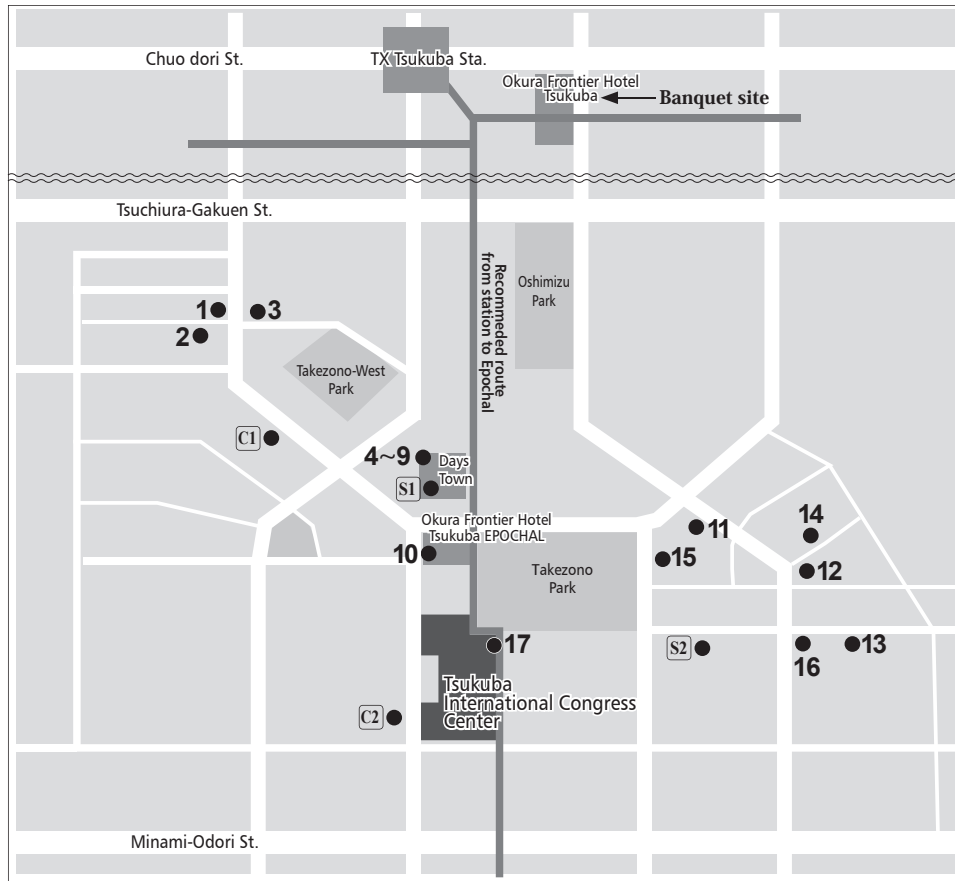


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Lunch Map

Recommended by SSDM



		OPEN		CLOSED		
1	Korean Barbecue	Takarajima 宝島	11 : 00 ~ 25 : 00			☎ 029-850-1061
2	Korean Barbecue	Shu-en 秀苑	11 : 30 ~ 14 : 00 17 : 00 ~ 23 : 00			☎ 029-861-1129
3	Sushi	YAGURA やぐら	11 : 30 ~ 14 : 00 17 : 00 ~ 22 : 30	Mon		☎ 029-852-6222
4	Ethnic food	MONSTAR 門星	11 : 30 ~ 15 : 00 17 : 30 ~ 26 : 00			☎ 029-859-5566
5	Noodle	AOBA 青葉	11 : 00 ~ 24 : 00			☎ 029-859-6090
6	Pub	KAGARI 季彩かがり	11 : 30 ~ 26 : 00			☎ 029-875-7219
7	Pub	Sennen no utage 千年の宴	11 : 00 ~ 24 : 00			☎ 029-852-7788
8	Cafe	Minna no Italian みんなのイタリアン	11 : 00 ~ 24 : 00			☎ 029-896-3131
9	Shabu shabu	Musubi むすび	11 : 30 ~ 14 : 30 18 : 00 ~ 24 : 00			☎ 029-856-0107
10	Restaurant	CASA	7 : 00 ~ 23 : 00			☎ 029-861-7626
11	Curry	Himalaya ヒマラヤ	11 : 00 ~ 15 : 00 17 : 00 ~ 22 : 00			☎ 029-856-5640
12	Noodle	MIYABI-YA 雅屋	11 : 30 ~ 14 : 30 17 : 30 ~ 21 : 00	Mon		☎ 029-869-9638
13	Pub	HANA Q 花Q	11 : 30 ~ 25 : 00			☎ 029-855-6468
14	Pub	TOYOCHO とよ長	11 : 30 ~ 23 : 00	Tue		☎ 029-855-7011
15	Noodle	AOI 蒼	11 : 00 ~ 14 : 30 17 : 30 ~ 21 : 00	Wed		☎ 029-856-5585
16	Chinese food	Kouenken 廣源軒	11 : 00 ~ 15 : 00 17 : 00 ~ 24 : 00			☎ 029-858-3040
17	Restaurant	Espoir (EPOCHAL TSUKUBA 1F)	9 : 00 ~ 17 : 00			☎ 029-850-3266

Bento Boxes are available at

S1 SEIYU (supermarket)

S2 KASUMI (supermarket)

C1 7 Eleven (convenience store)

C2 MINI STOP (convenience store)

MEMO

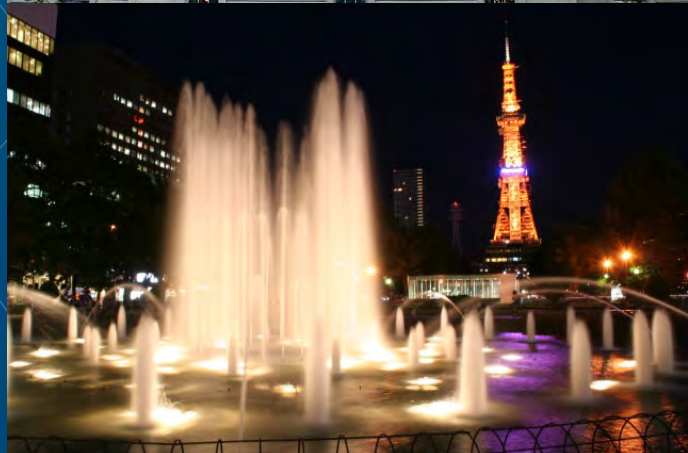


ssdm 2015

2015 International Conference on Solid State Devices and Materials

Sep. 27-30, 2015

**Sapporo Convention Center
Sapporo, Japan**



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